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Yamada et al.

(54) **CONNECTOR AND METHOD OF PRODUCING THE SAME**

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(52) **U.S. Cl.** **439/607**; 439/676; 29/876

(57) **ABSTRACT**

A receptacle includes contact modules, each of which includes contacts, one of common ends thereof being connected to contact pins of a plug when the receptacle and the plug are connected to each other, and the other of the common ends of the contacts being connected to a circuit board. Each contact module includes holding plates arranged in a direction of thickness of the each contact module. At least one conductive layer and at least one insulating portion are formed on opposed surfaces of adjacent holding plates. At least one of contacts is held between the insulating portions that are formed on the opposed surfaces of the adjacent holding plates.

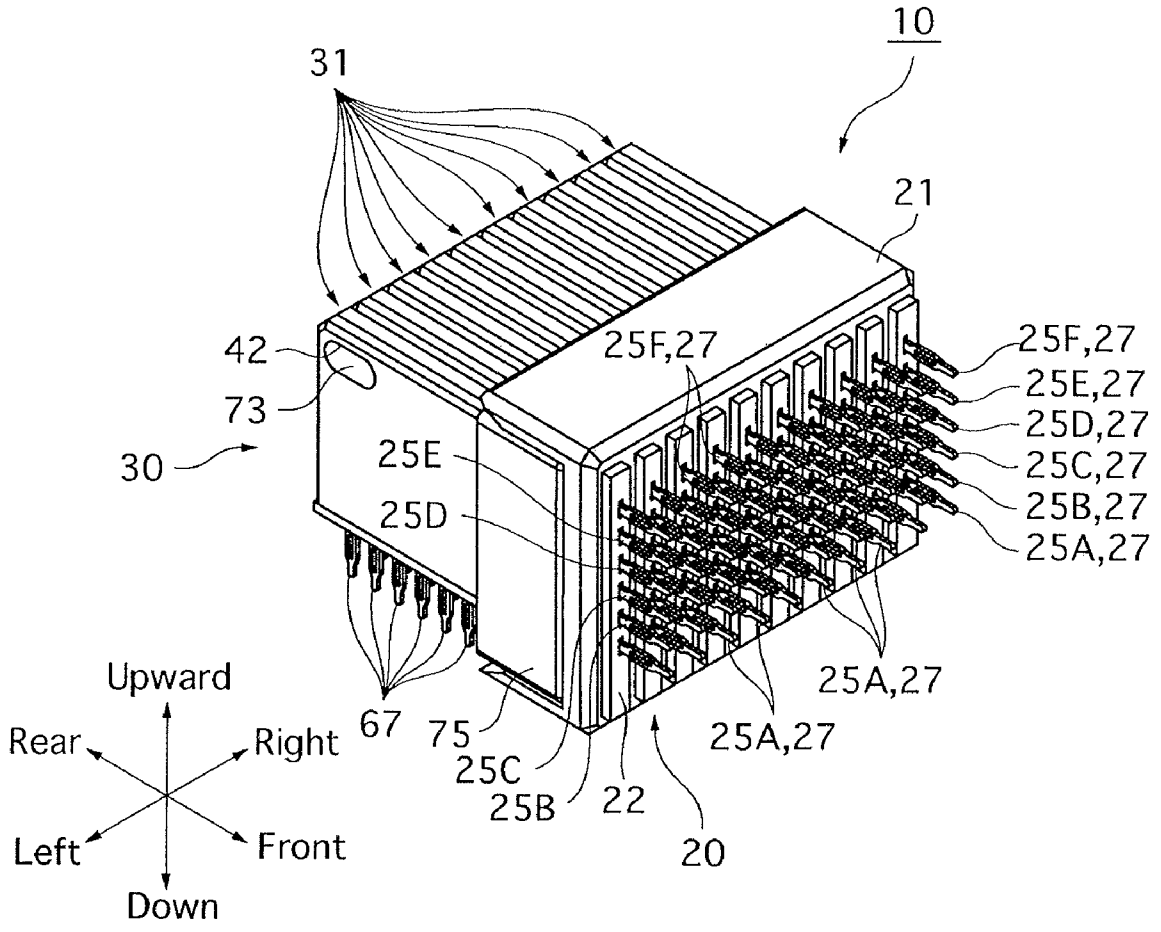


Fig. 1

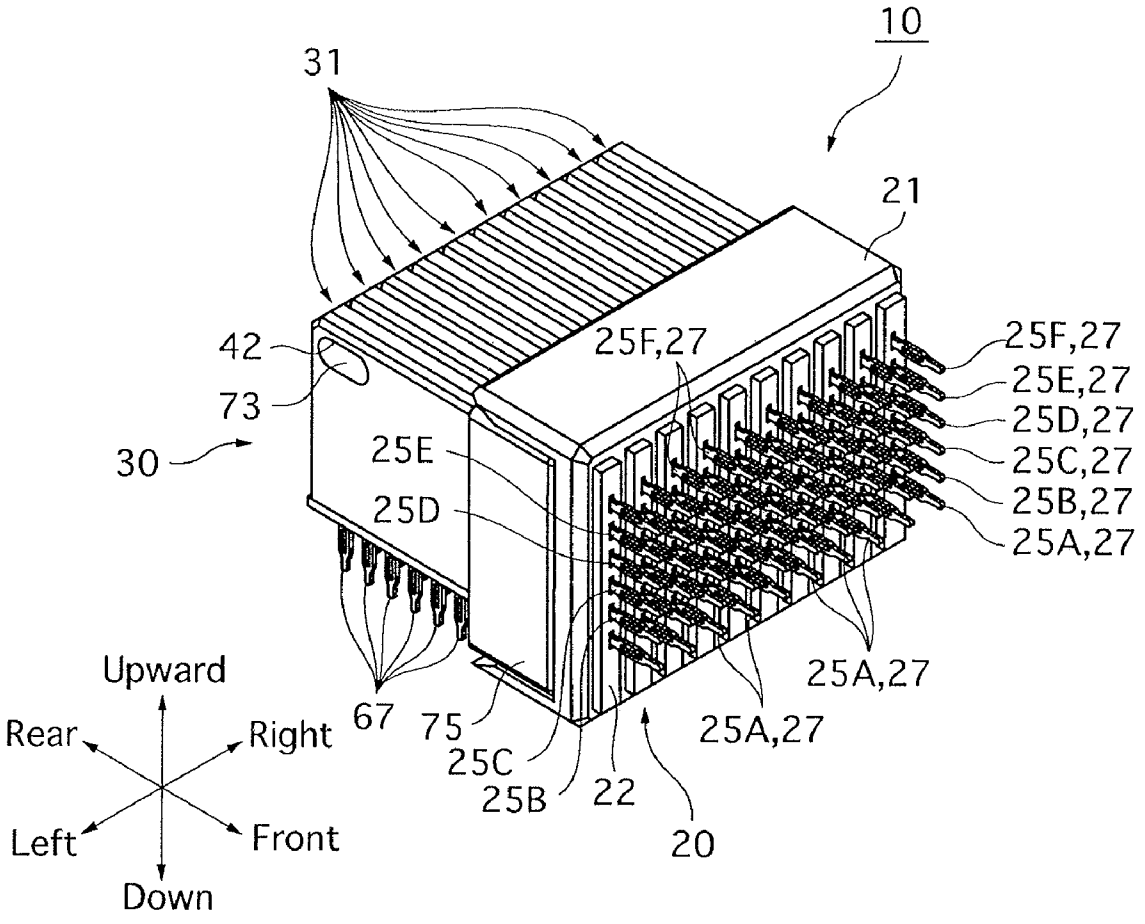

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Fig. 2

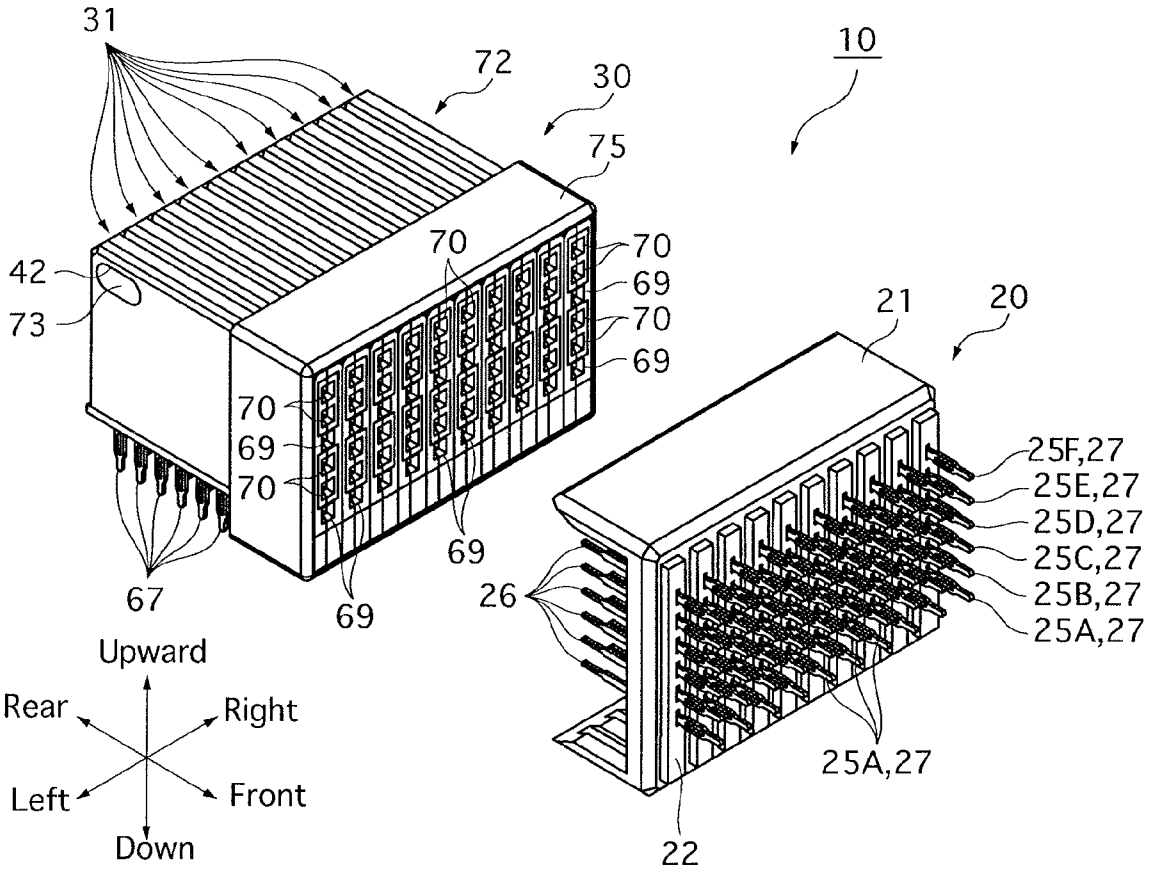

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Fig. 3

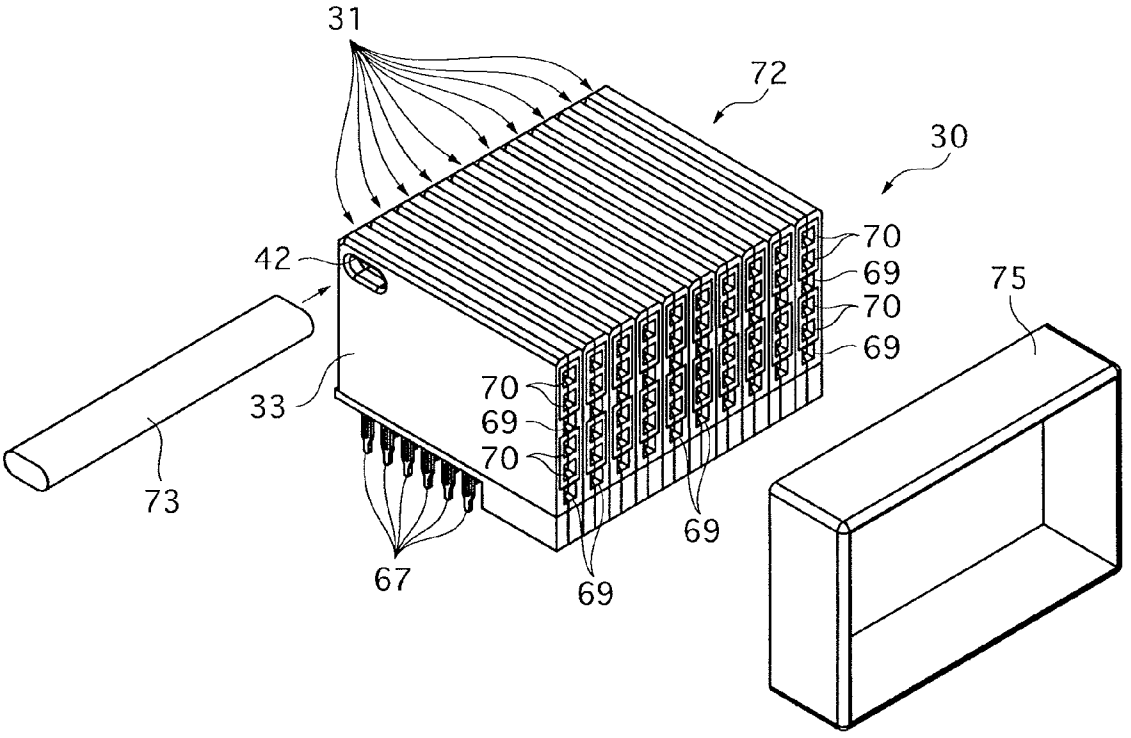

31
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Fig. 4

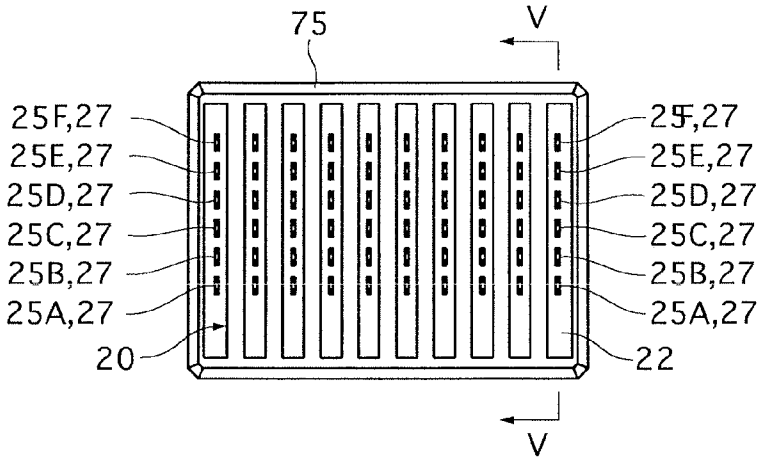

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25F,27
25E,27
25D,27
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25B,27
25A,27
20
25F,27
25E,27
25D,27
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25B,27
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Fig. 5

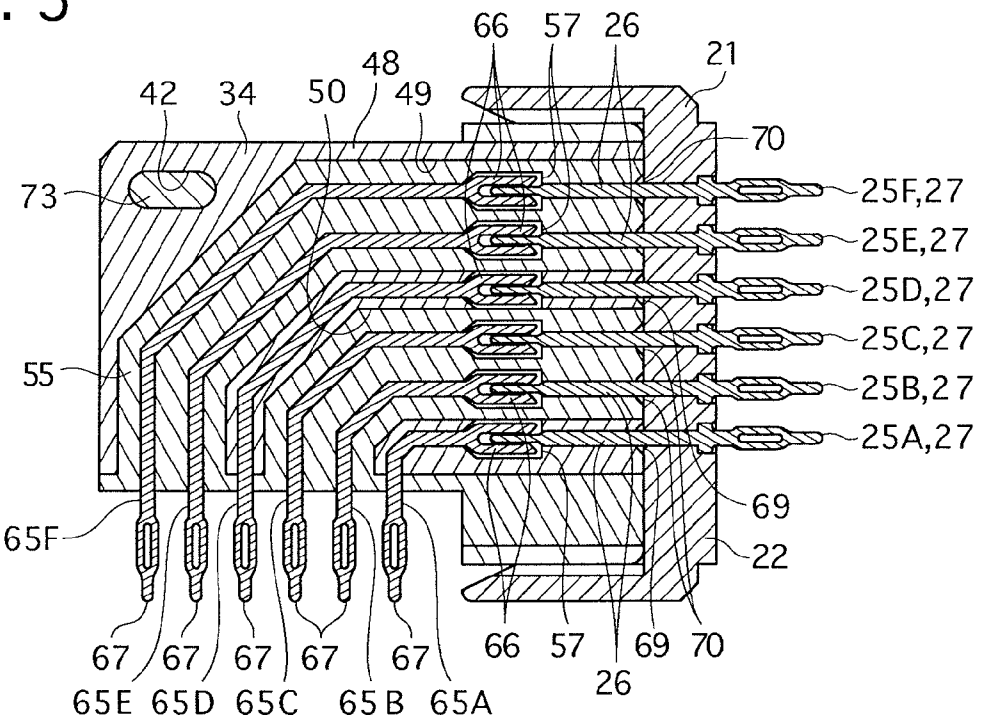
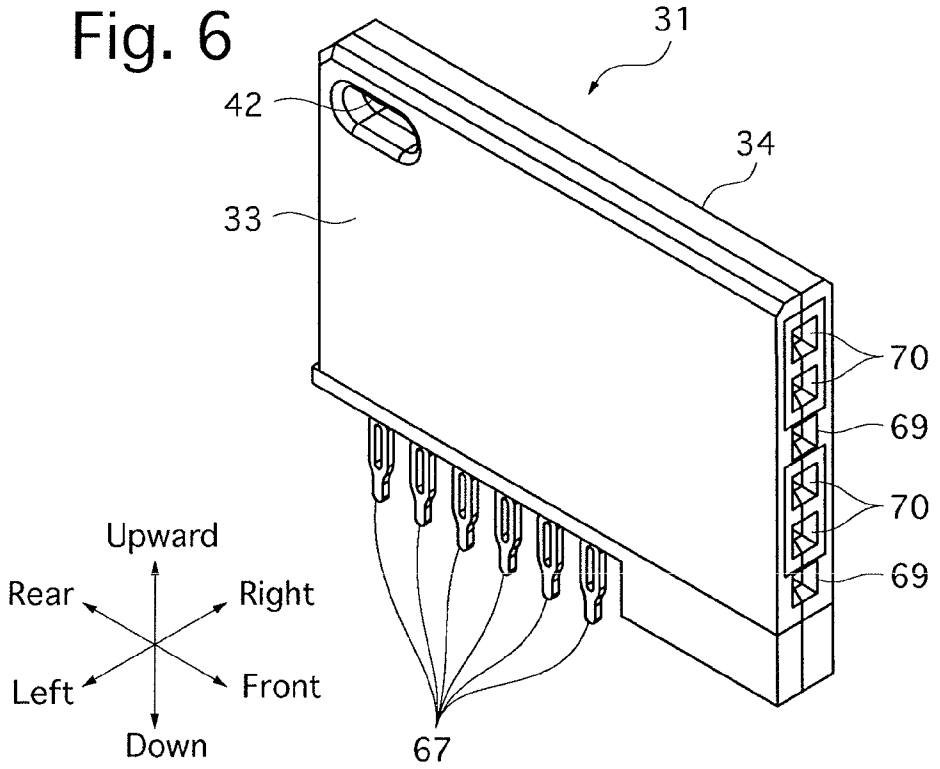

66
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Fig. 6


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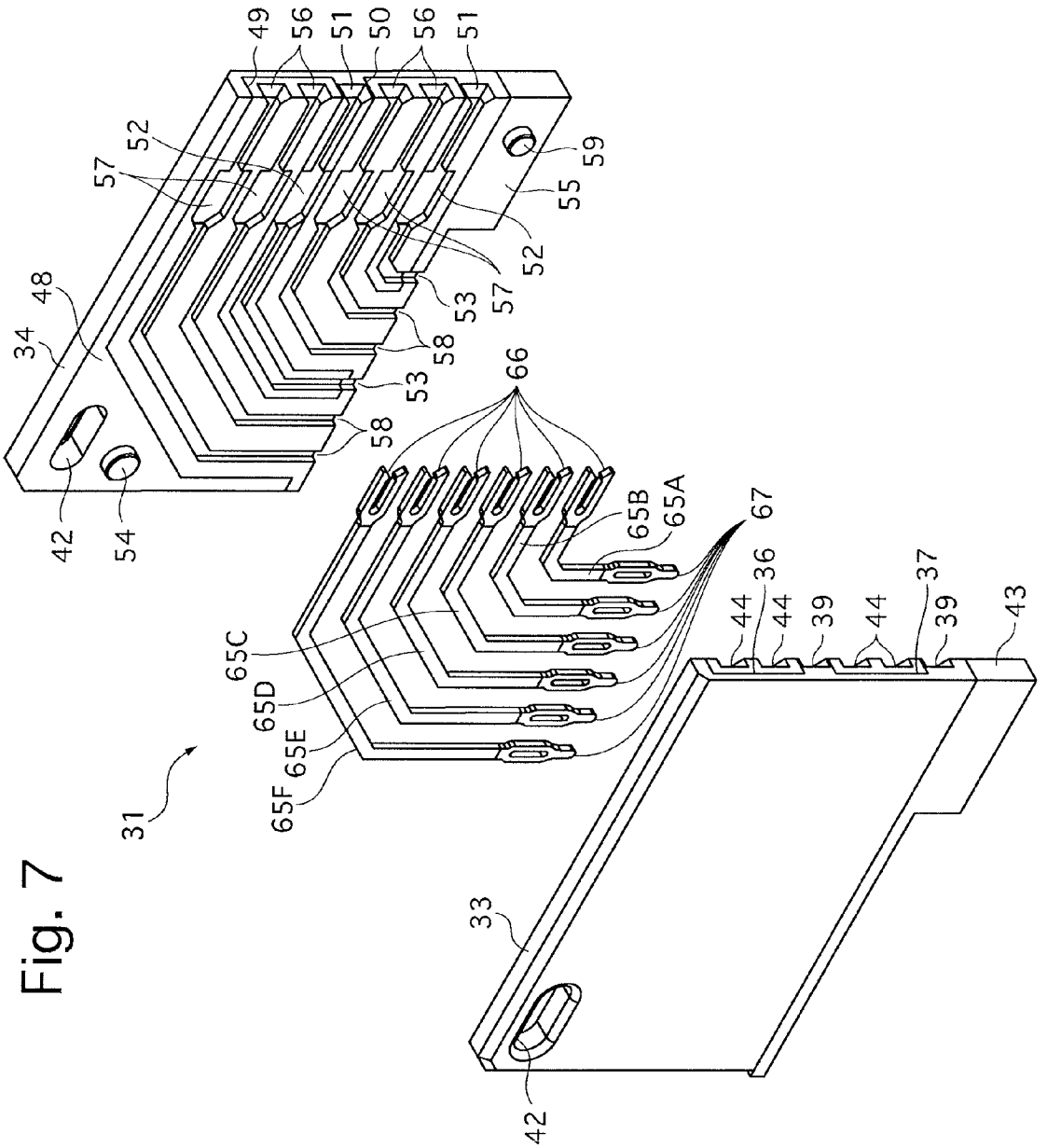

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Fig. 7

Fig. 8

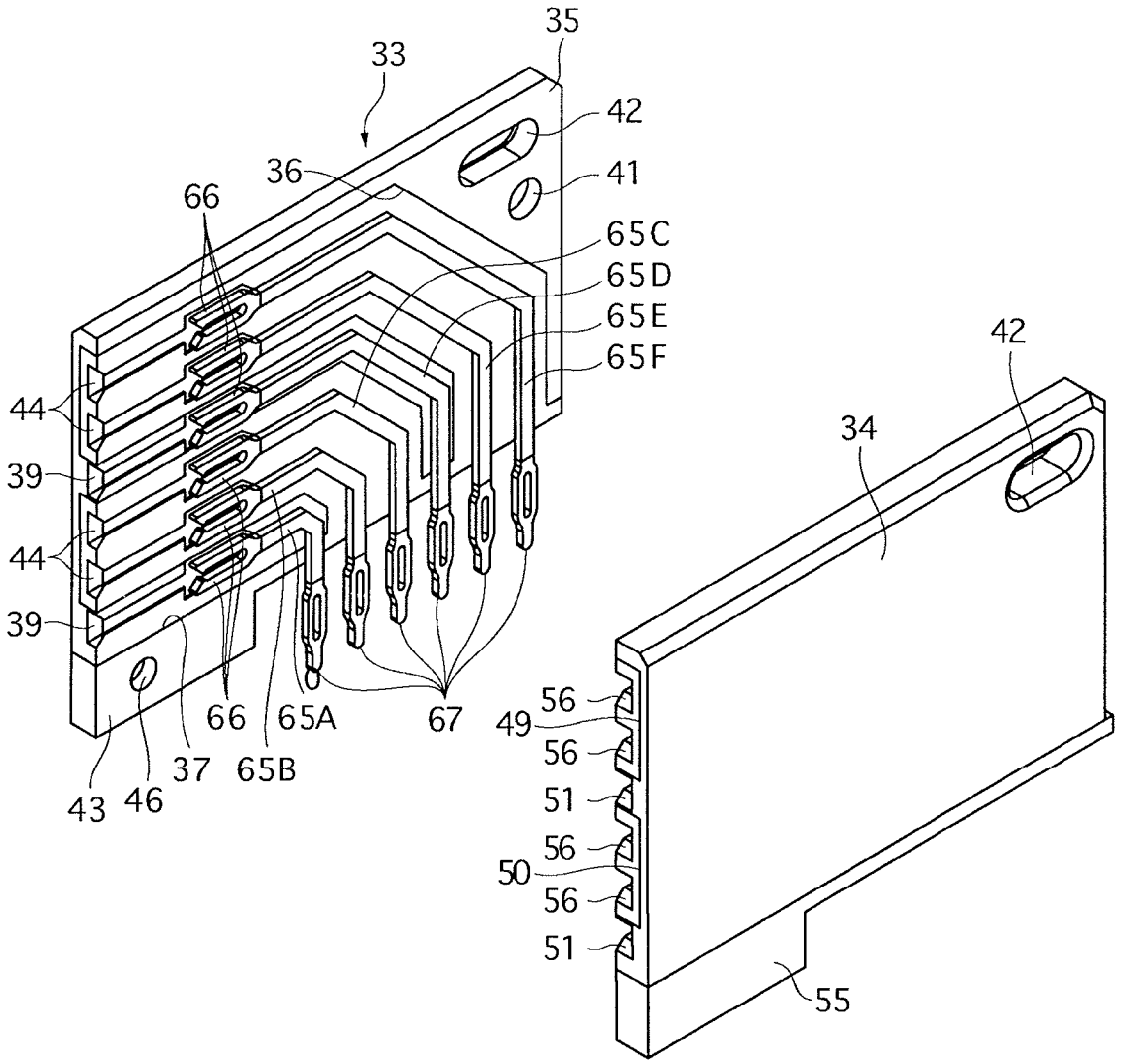

35
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Fig. 9

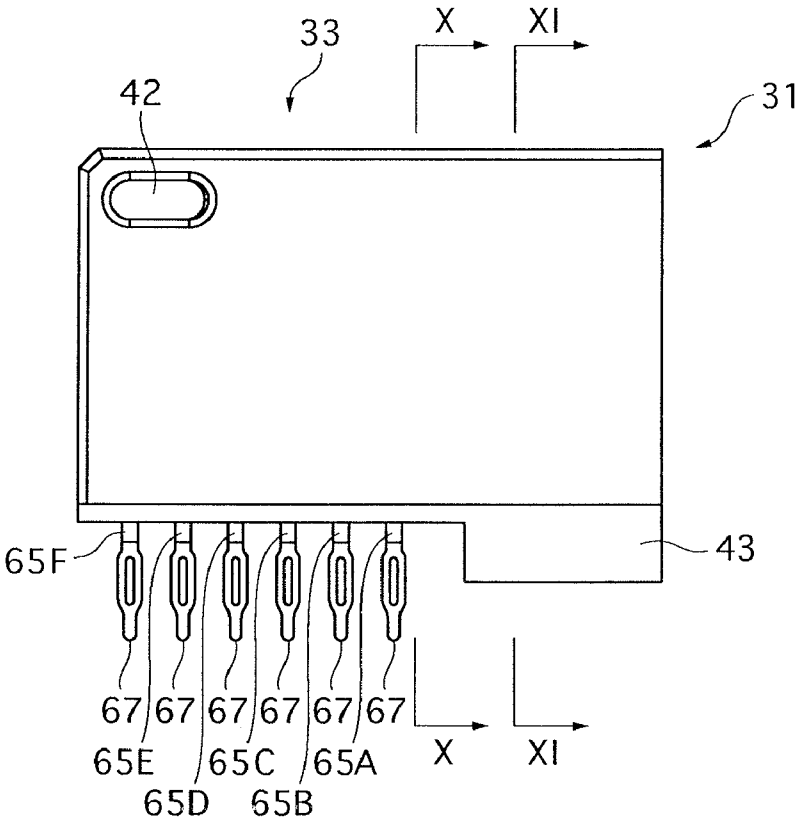

33
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Fig. 10

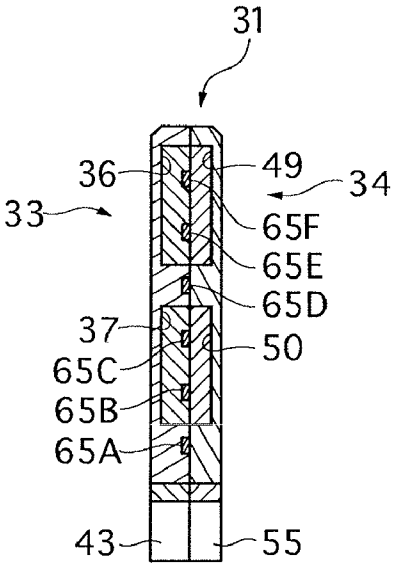

31
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Fig. 11

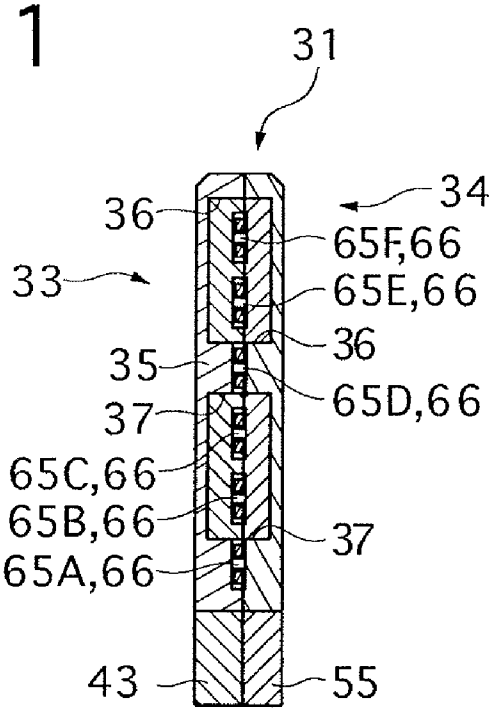

31
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65F,66
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Fig. 12

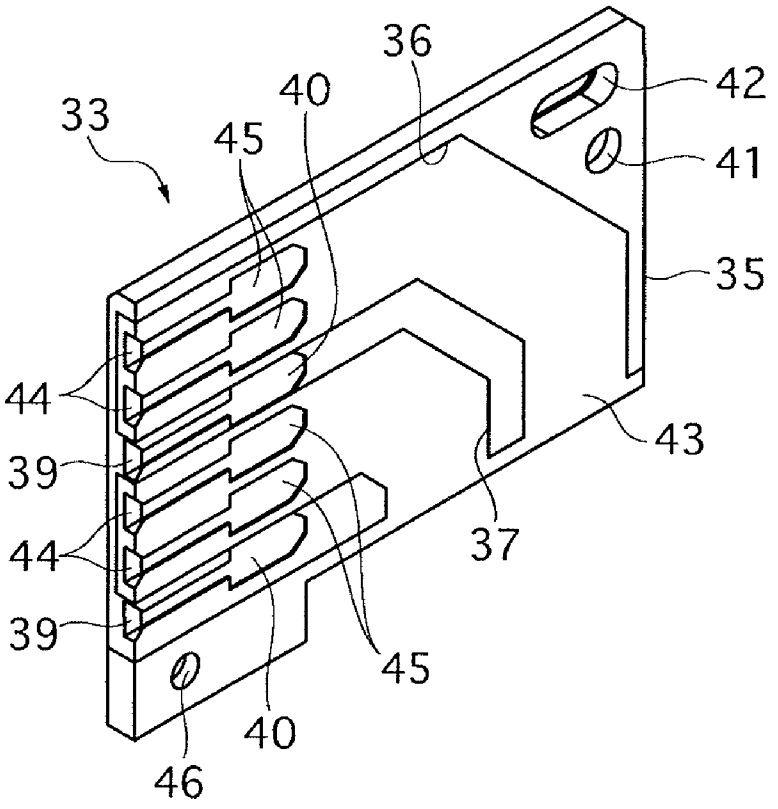

36
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Fig. 13

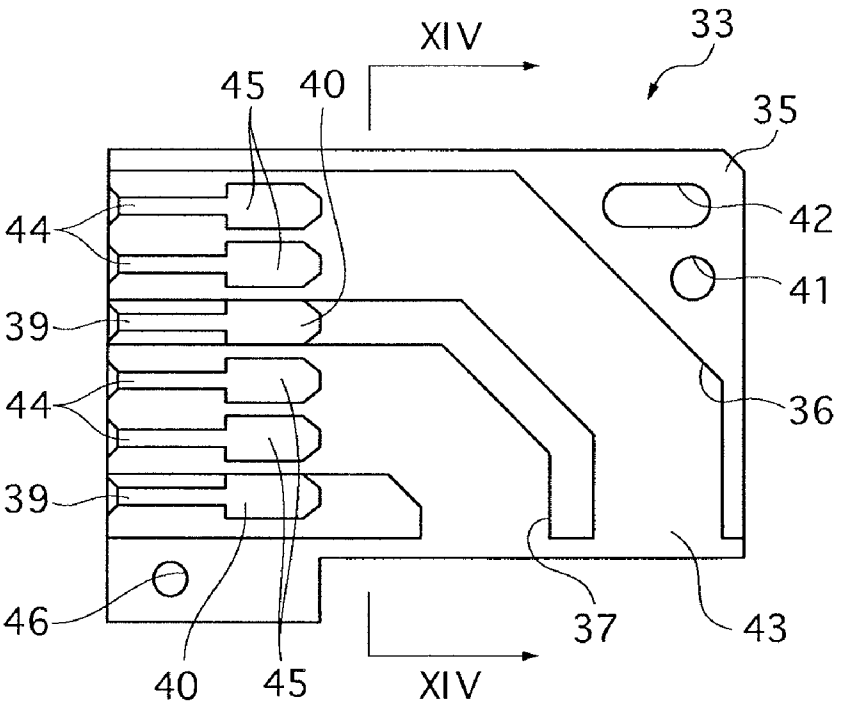

XIV
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XIV

Fig. 14

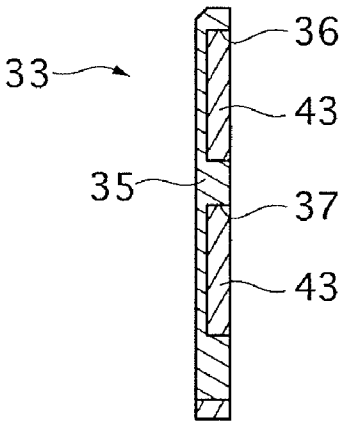

36
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Fig. 15

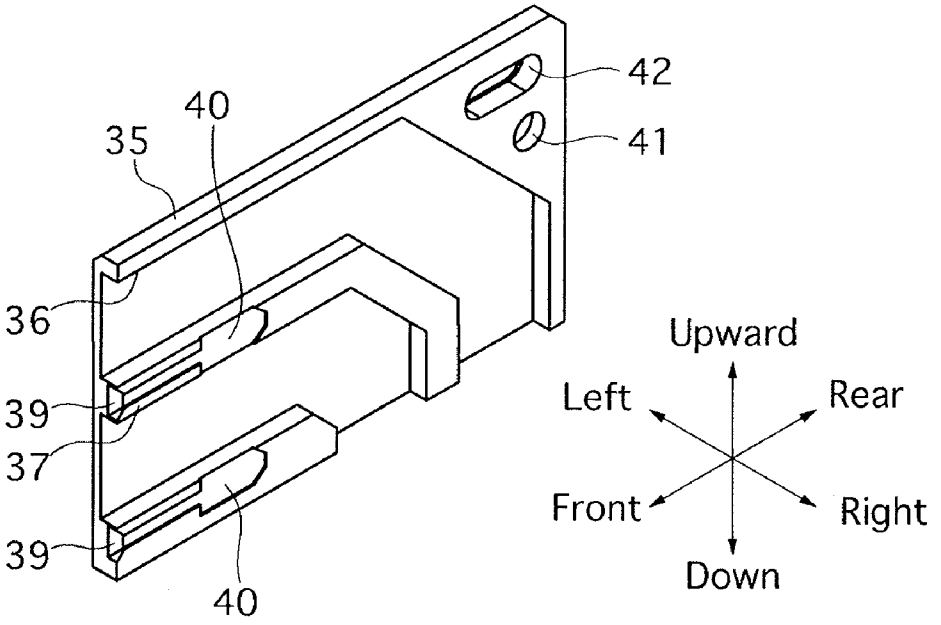

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Fig. 16

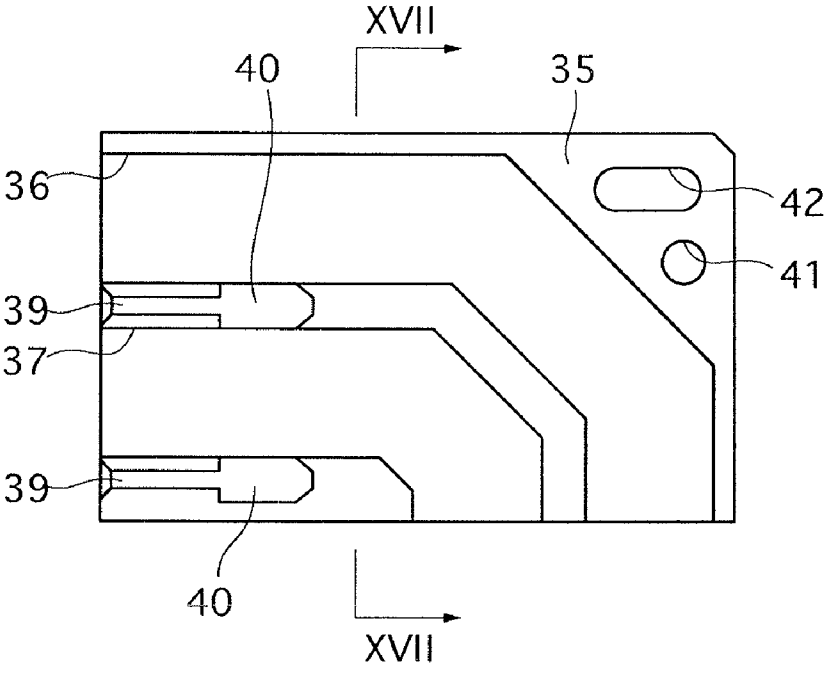

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XVII

Fig. 17

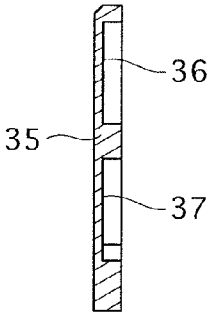


Fig. 18

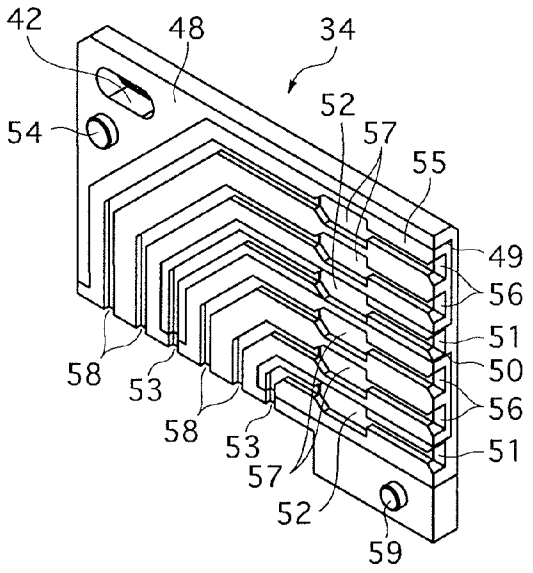


Fig. 19

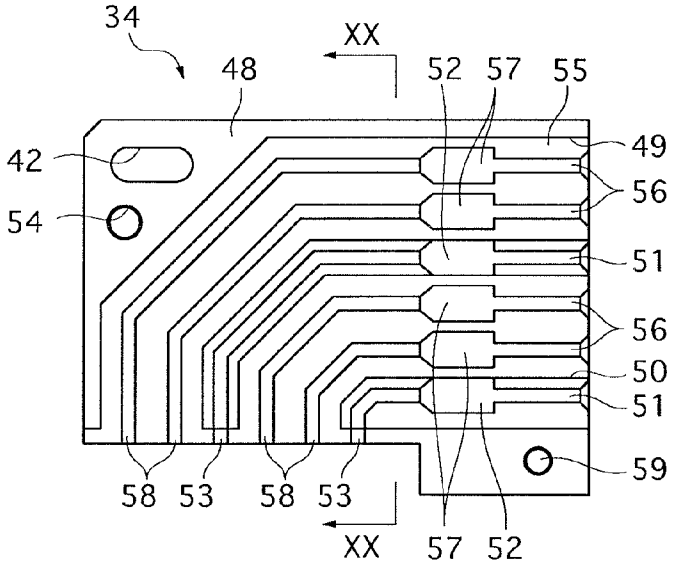


Fig. 20

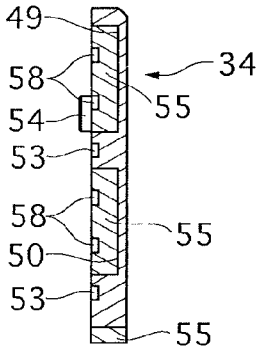


Fig. 21

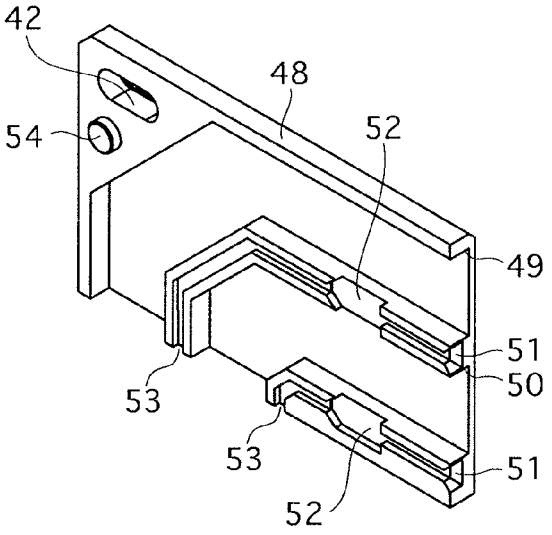


Fig. 22

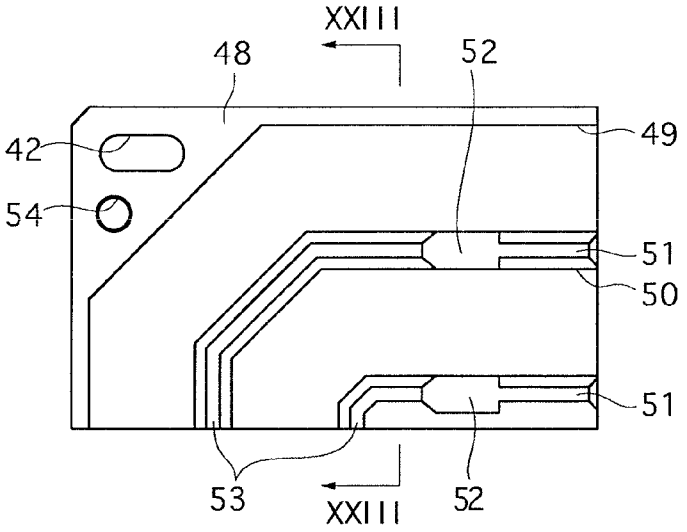


Fig. 23

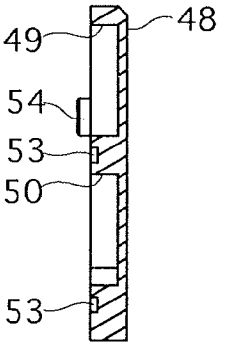


Fig. 24

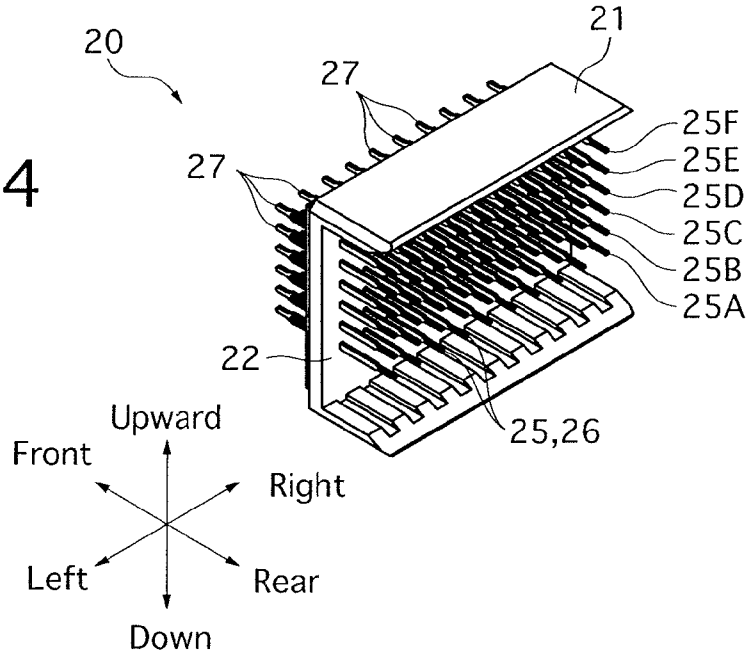


Fig. 25

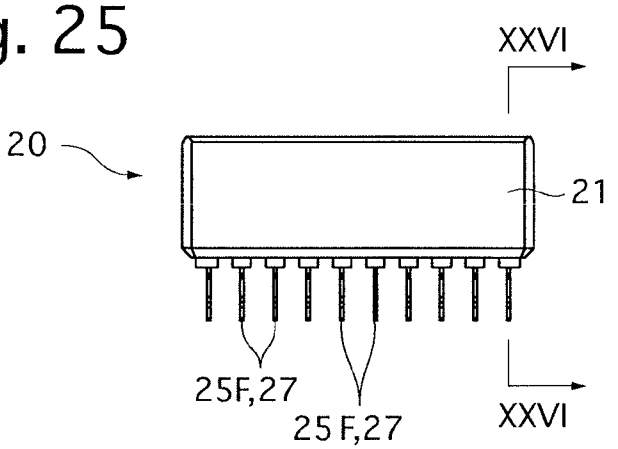


Fig. 26

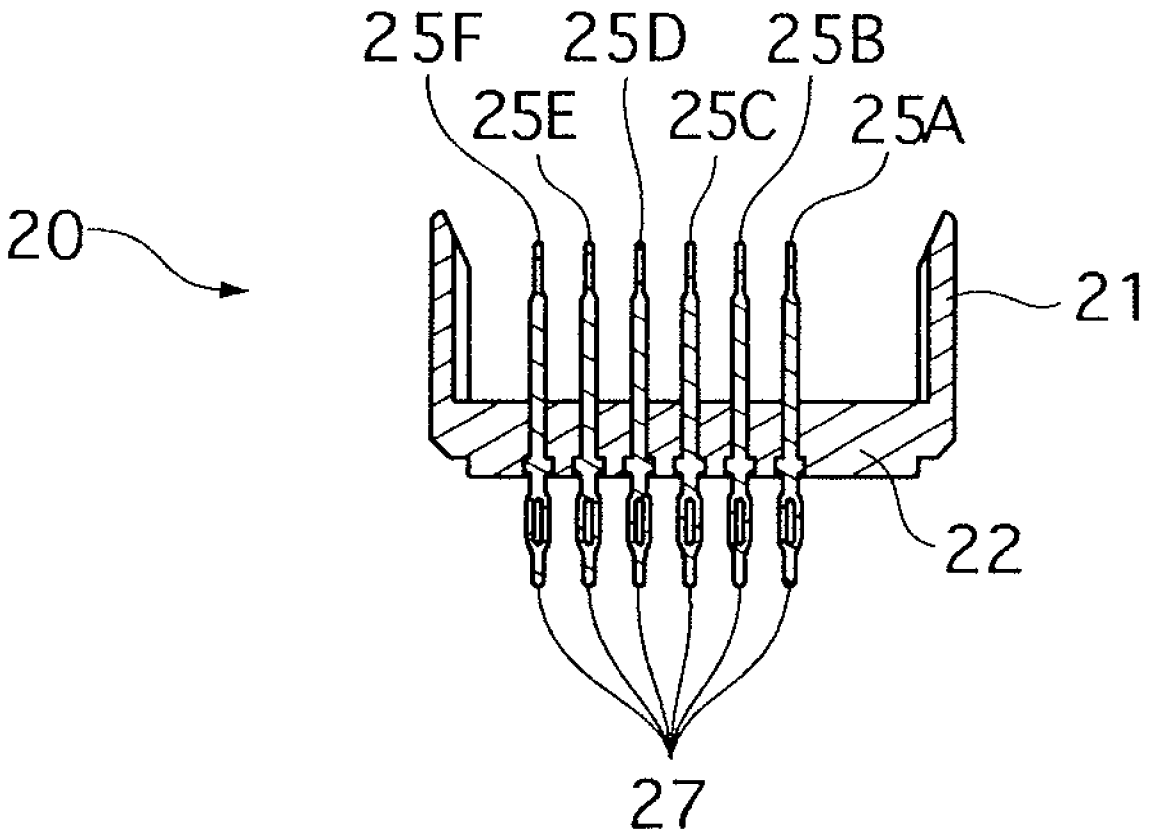


Fig. 27

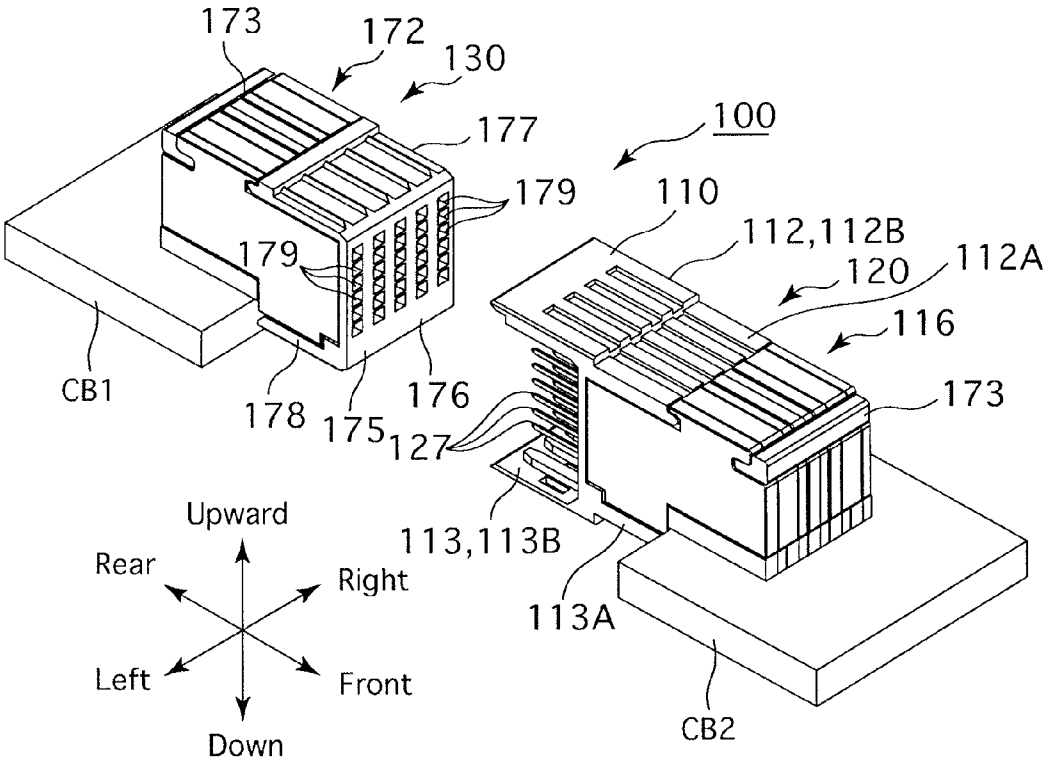

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177
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110
112,112B
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112A
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Upward
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113,113B
113A
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CB2

Fig. 28

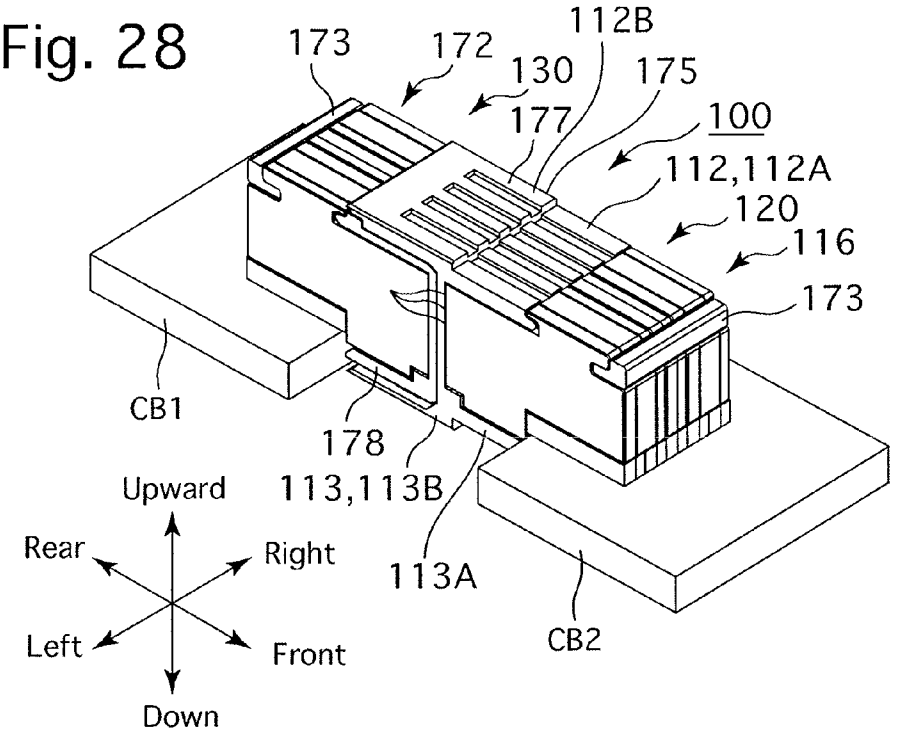

112B
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113A
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Front
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CB2

Fig. 29

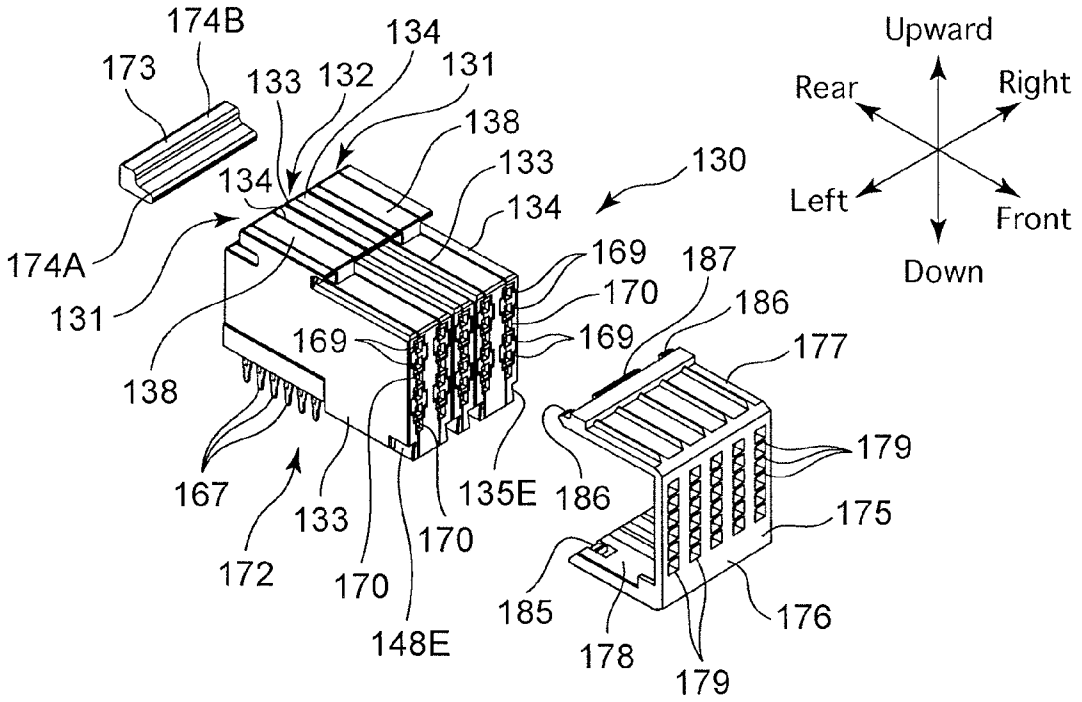

174B
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Fig. 30

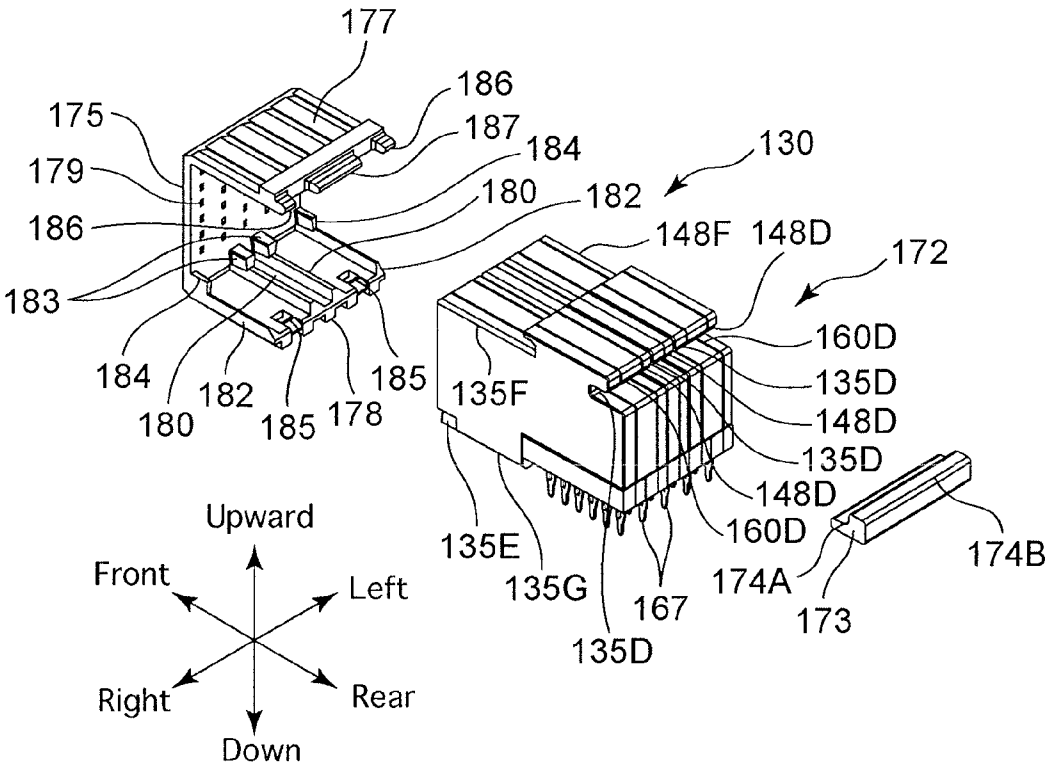

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148F
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160D
135D
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135F
148D
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Fig. 31

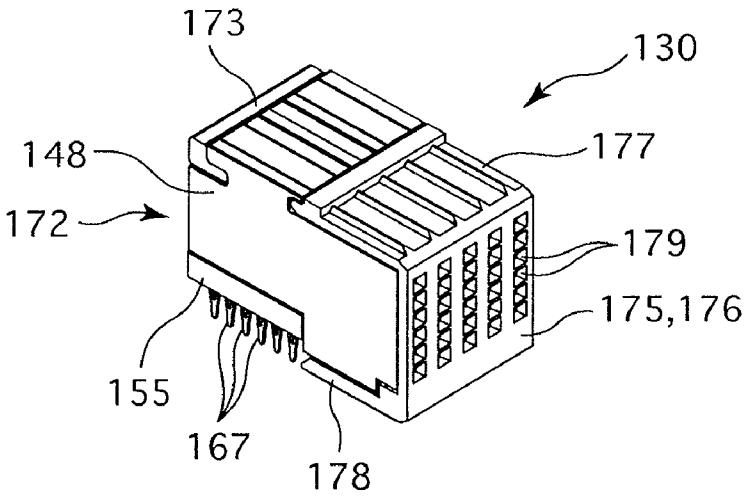

173
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148
177
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Fig. 32

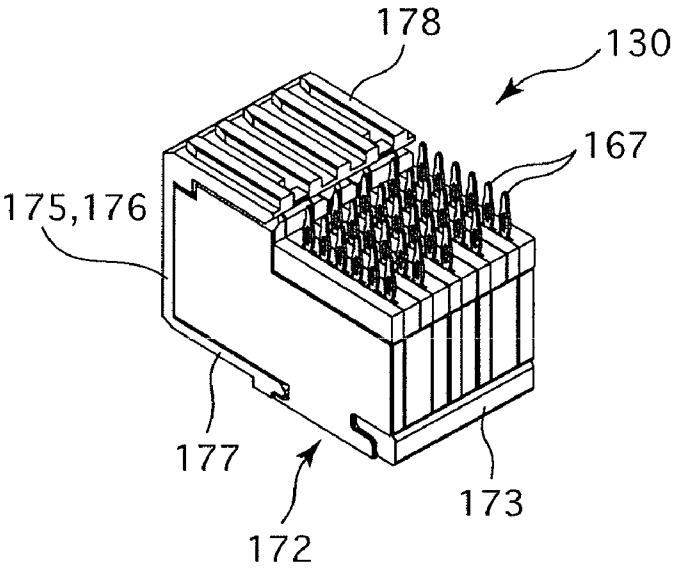

178
130
167
175,176
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Fig. 33

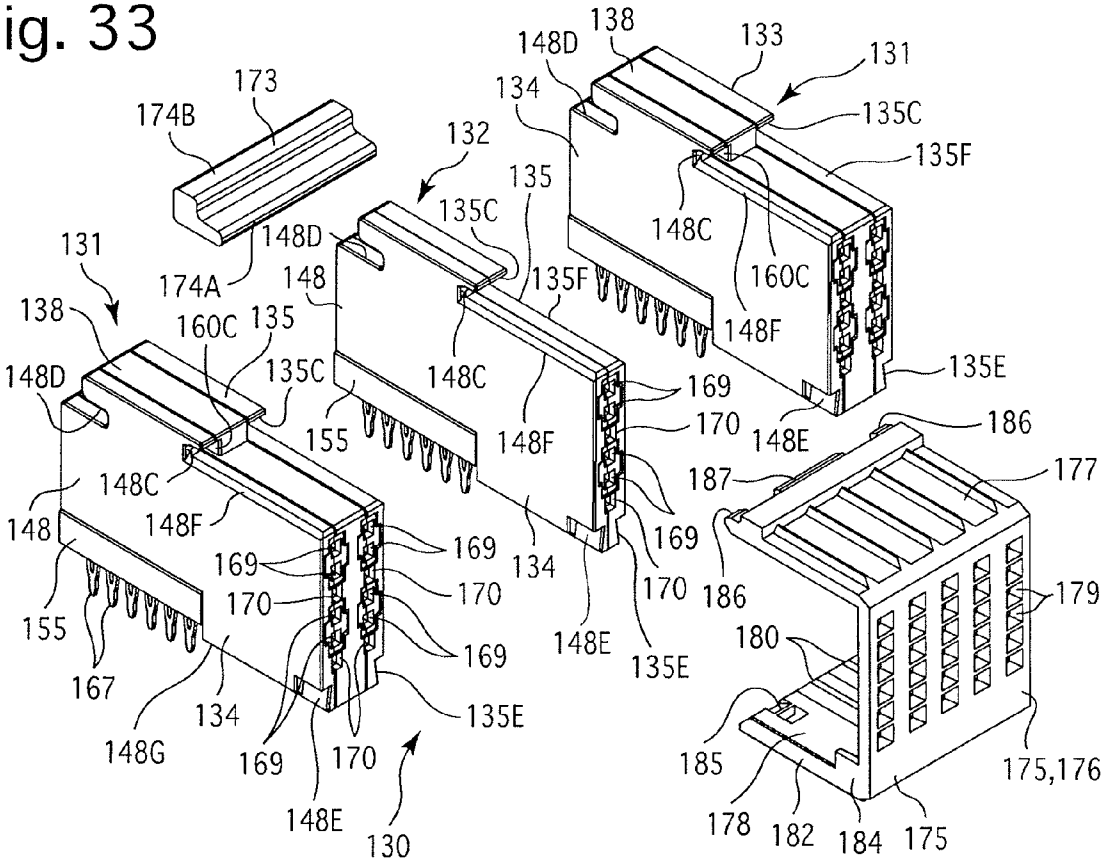
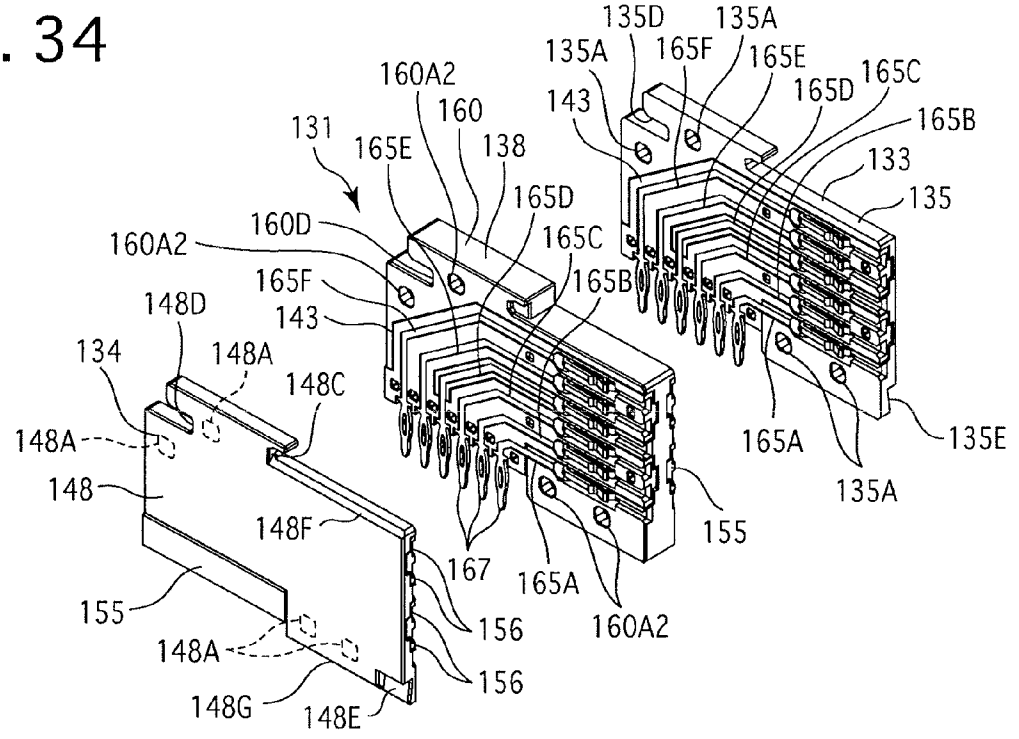

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174A
148D
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160C
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135C
148
148C
148F
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148G
169
170
148E
130
132
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135F
133
135E
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148E
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Fig. 34


135D
135A
165F
165E
165D
165C
165B
160A2
160
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143
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135
160D
165A
135E
148D
148A
148C
148
148F
155
167
156
148G
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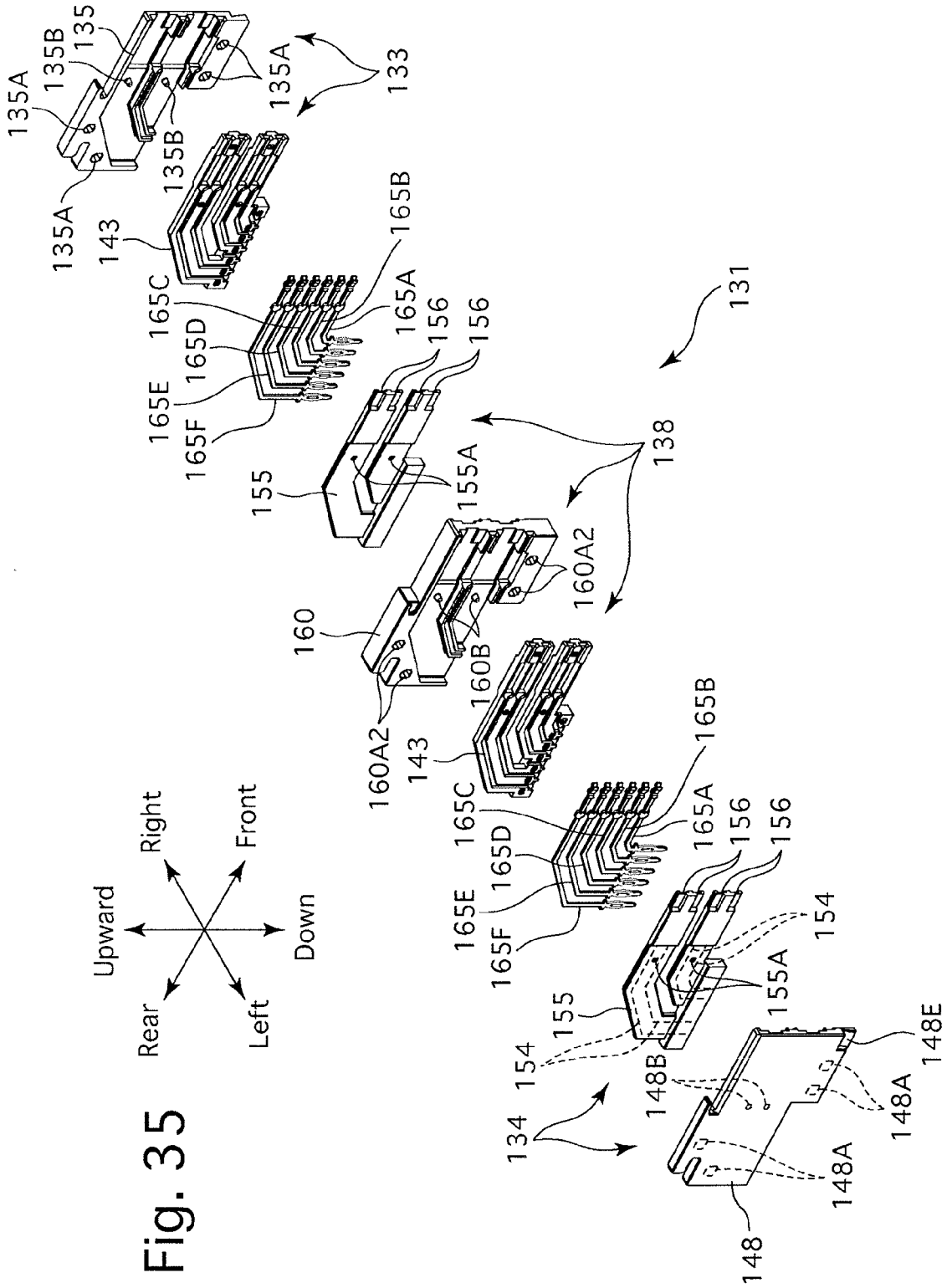

135A
135B
135
135A
135A
135B
133
143
165C
165B
165D
165A
165E
156
156
165F
155
155A
131
138
160
160A2
160B
160A2
143
165C
165B
165D
165A
165E
156
156
165F
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155A
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148B
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148A
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Fig. 35

Fig. 36

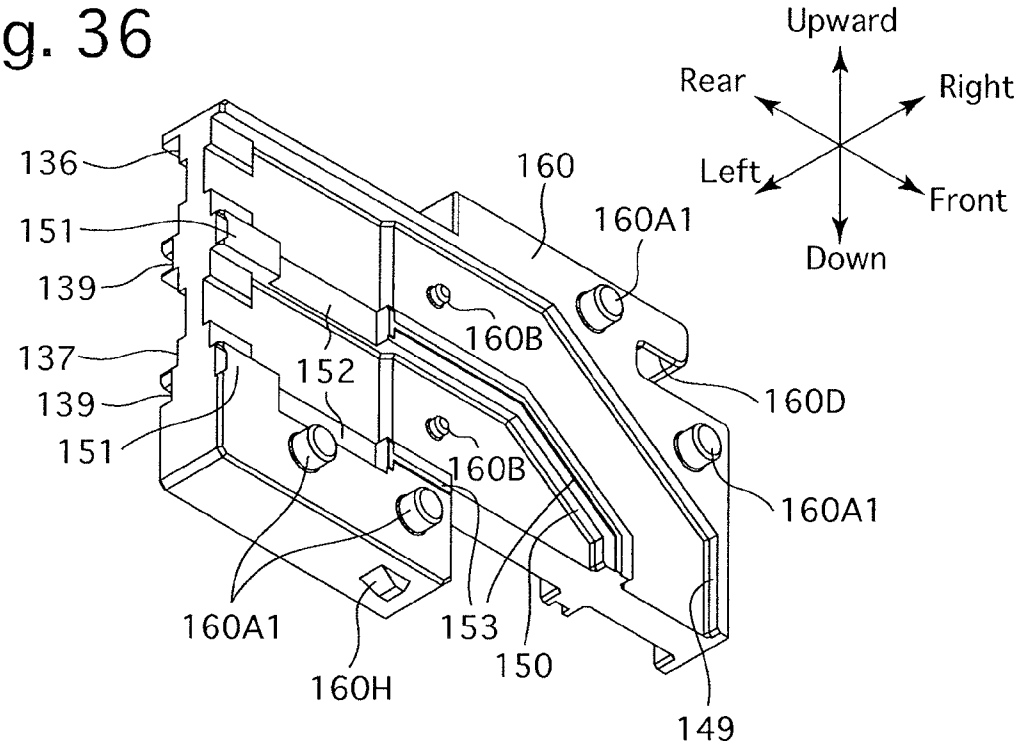

Upward
Rear
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139
137
139
151
160
160A1
160B
152
160B
160D
160A1
160A1
153
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160H
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Fig. 37

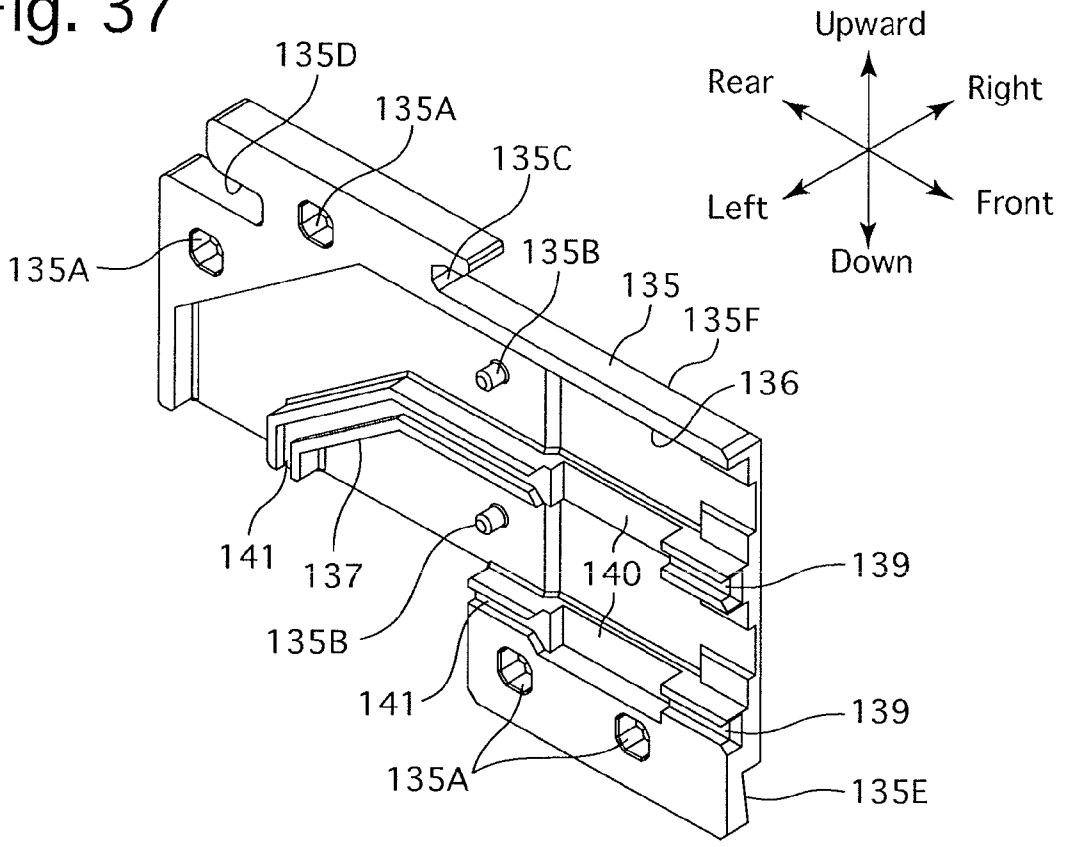

Upward
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135F
136
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135A
135E

Fig. 38

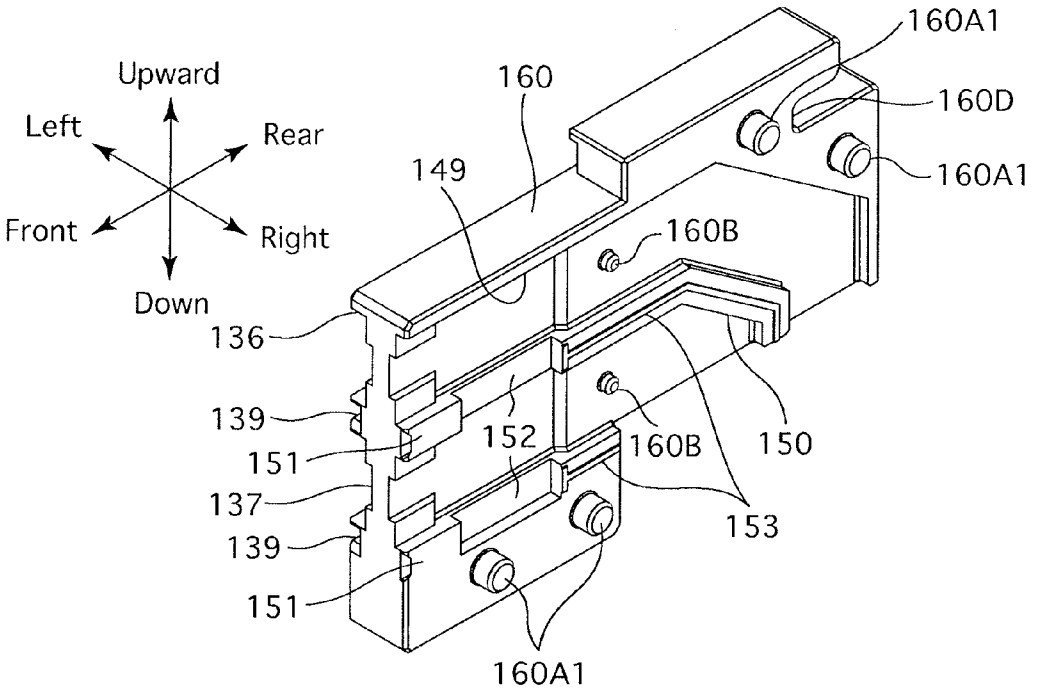

Upward
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160A1
160
160D
149
160A1
160B
136
139
152
160B
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160A1

Fig. 39

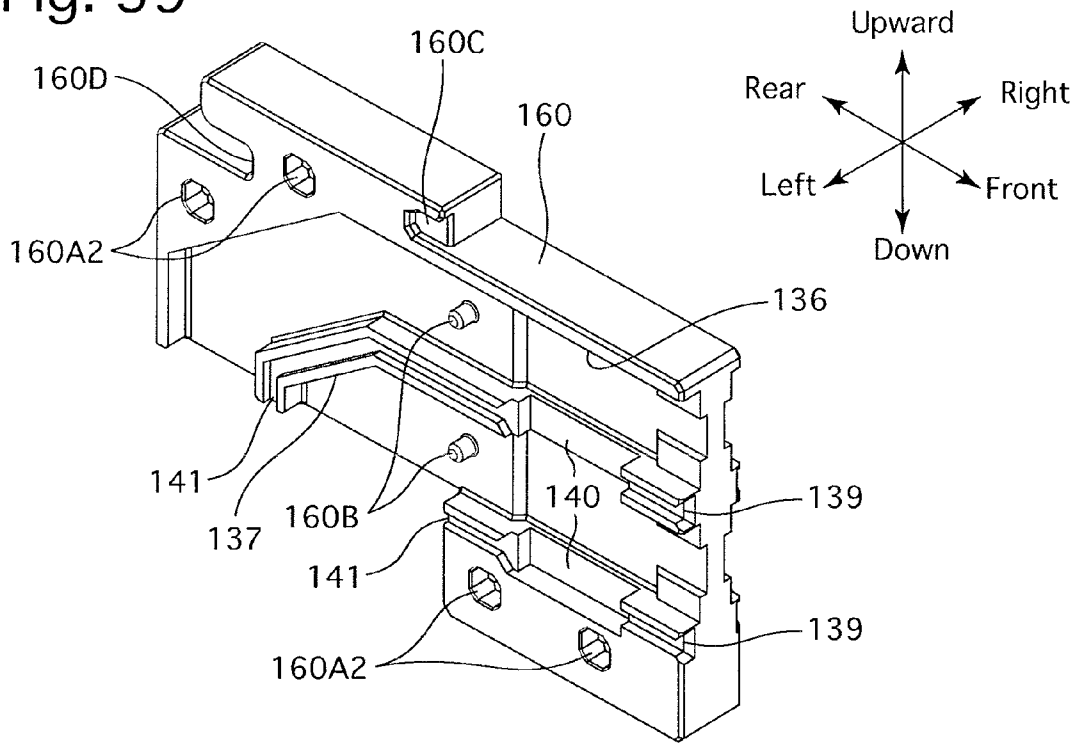

160C
160D
160
Upward
Rear
Right
Left
Front
Down
160A2
136
141
140
139
137
160B
141
139
160A2

Fig. 40

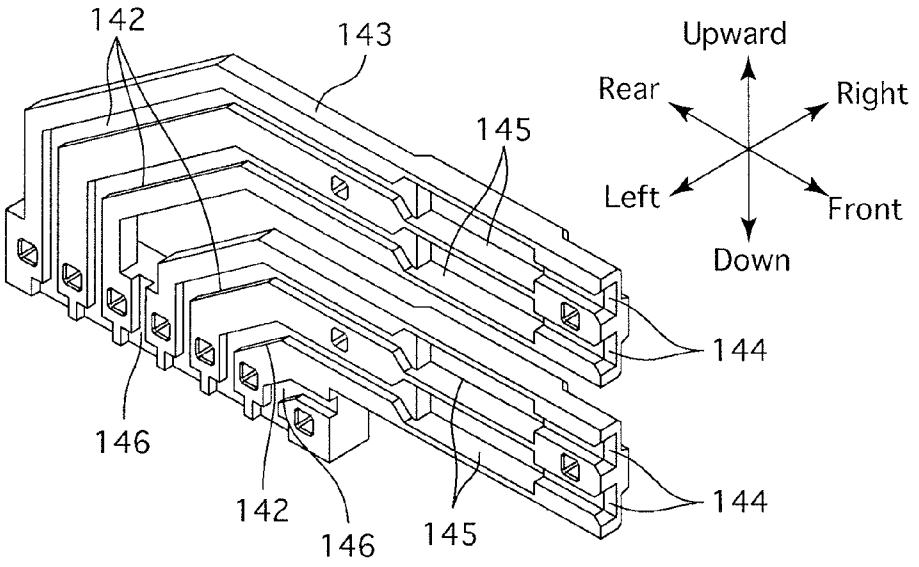


Fig. 41

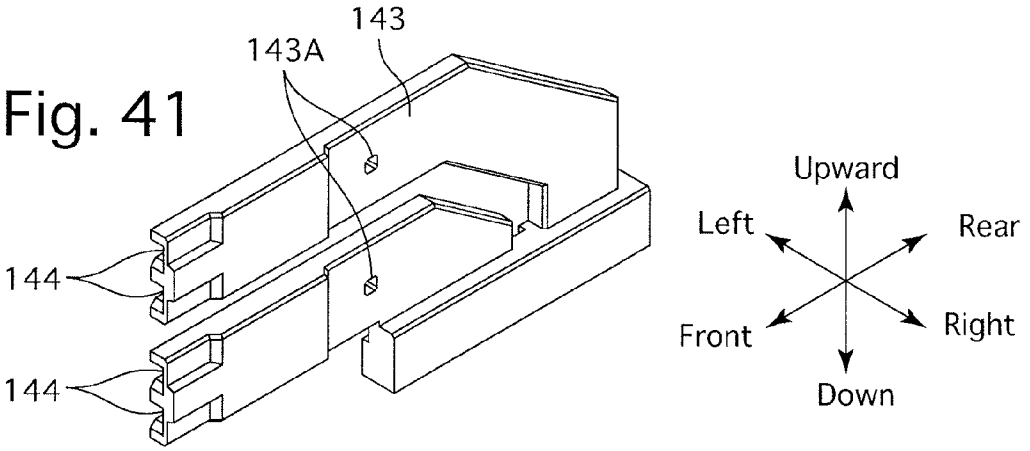


Fig. 42

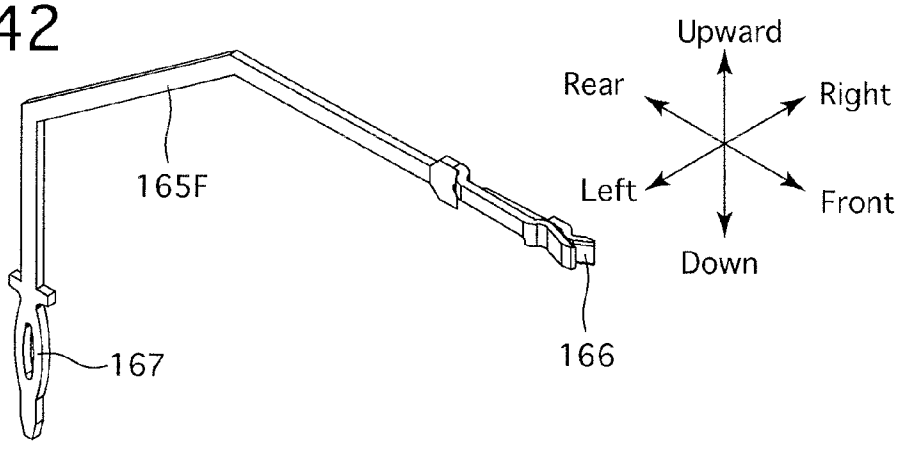


Fig. 43

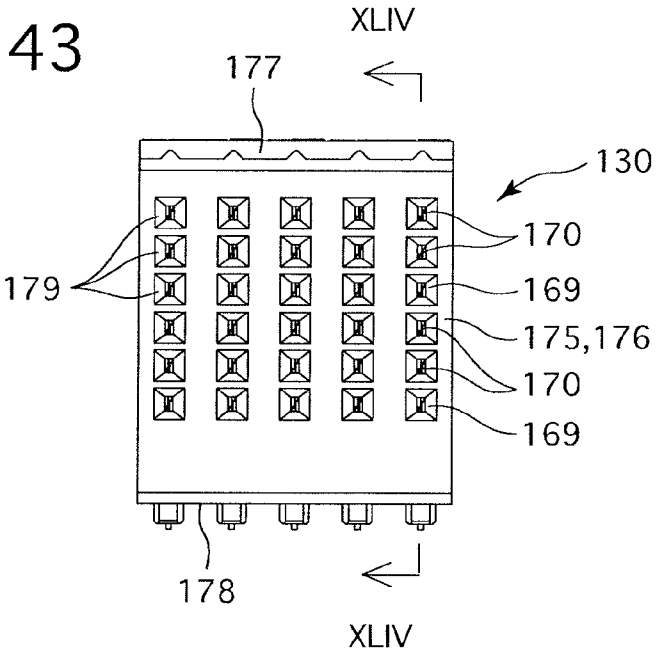

XLIV
177
130
170
179
169
175,176
170
169
178
XLIV

Fig. 44

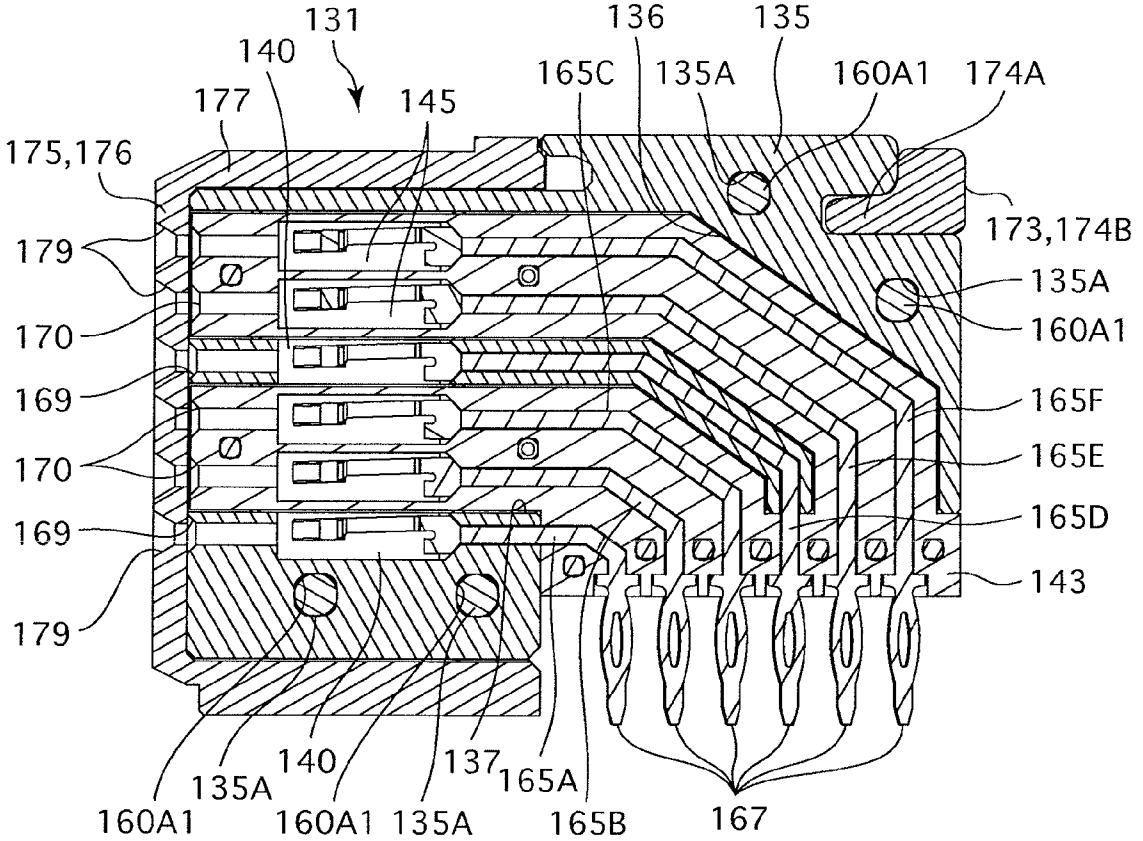

131
136
135
140
165C
135A
160A1
174A
177
145
175,176
173,174B
179
135A
170
160A1
169
165F
170
165E
169
165D
179
143
135A
140
137
165A
160A1
160A1
135A
165B
167

Fig. 45

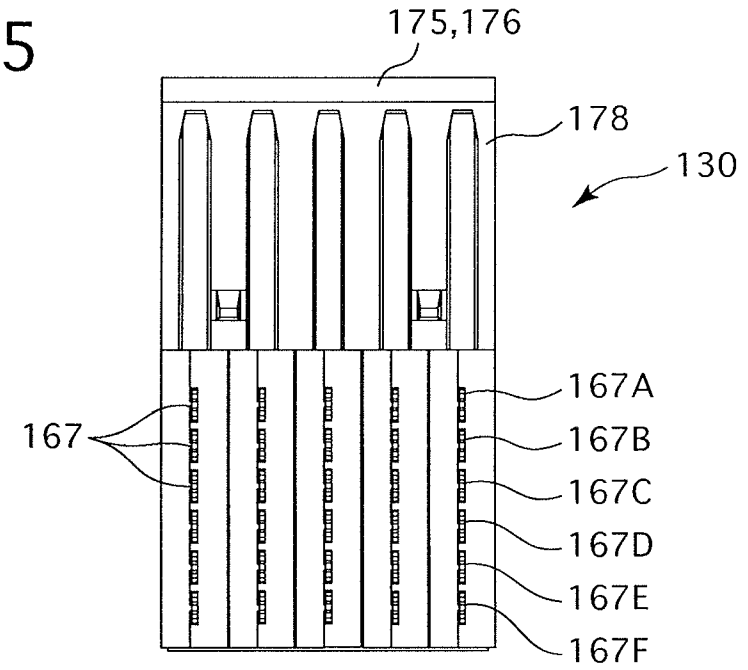

175,176
178
130
167A
167
167B
167C
167D
167E
167F

Fig. 46

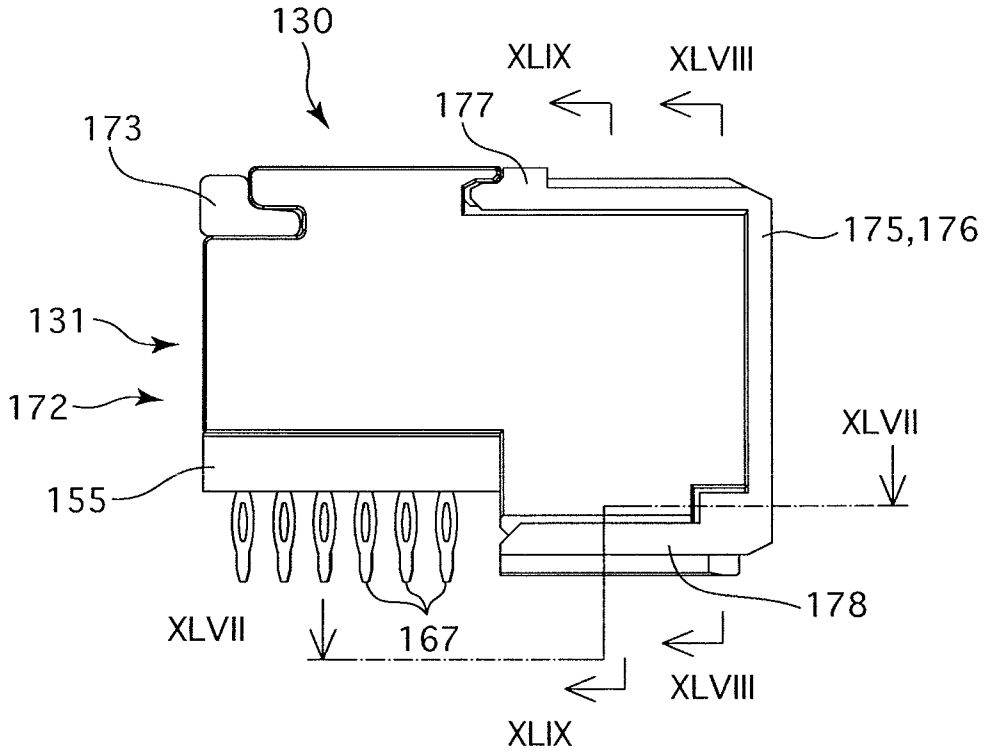

130
XLIX
XLVIII
177
173
175,176
131
172
XLVII
155
178
XLVII
167
XLVIII
XLIX

Fig. 47

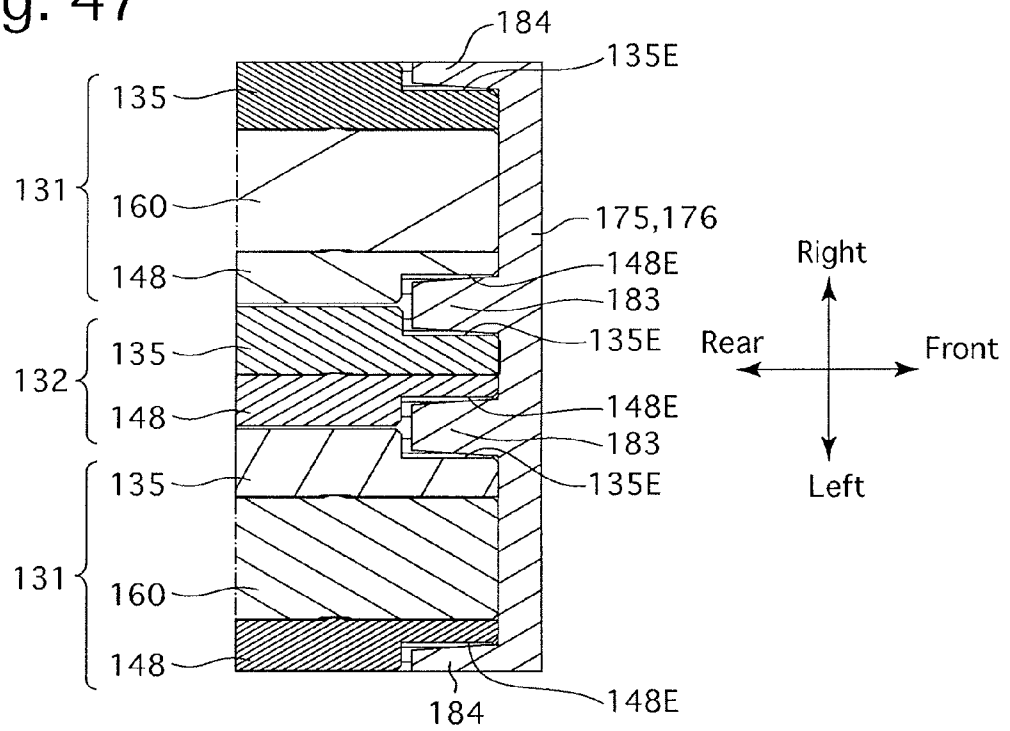

184
135E
135
131
160
175,176
148
148E
183
135E
135
132
148
148E
183
135E
135
131
160
148
148E
184
Right
Rear
Front
Left

Fig. 48

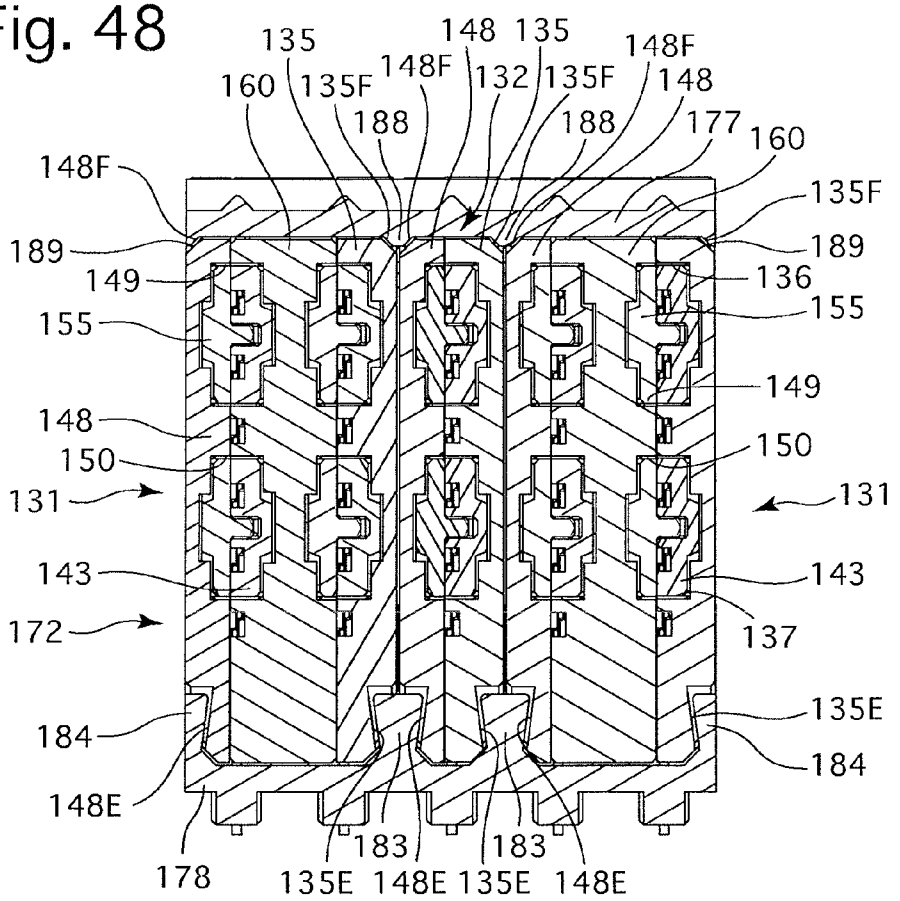

135
148
135
148F
160
135F
148F
132
135F
148
188
188
177
160
148F
135F
189
189
149
136
155
155
149
148
150
150
131
131
143
143
172
137
135E
184
184
148E
178
183
183
135E
148E
135E
148E

Fig. 49

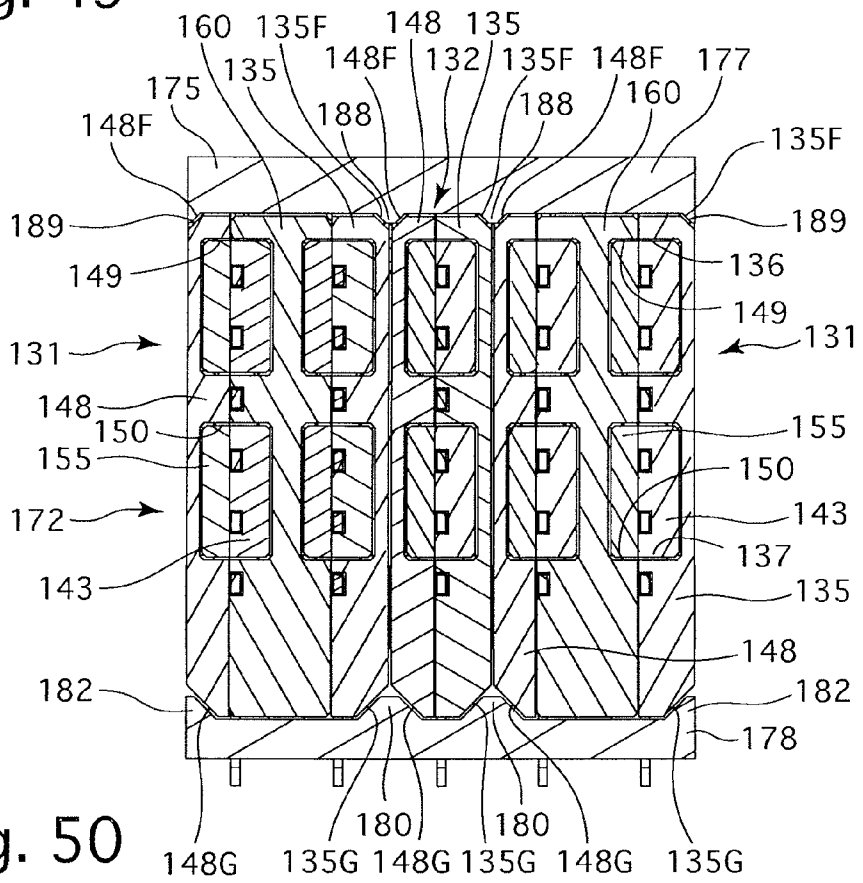

160
135F
148
135
148F
132
135F
148F
177
135
175
188
188
160
148F
135F
189
189
149
136
149
131
131
148
150
155
155
150
172
143
143
137
135
148
182
182
178
148G
135G
180
148G
180
135G
148G
135G

Fig. 50

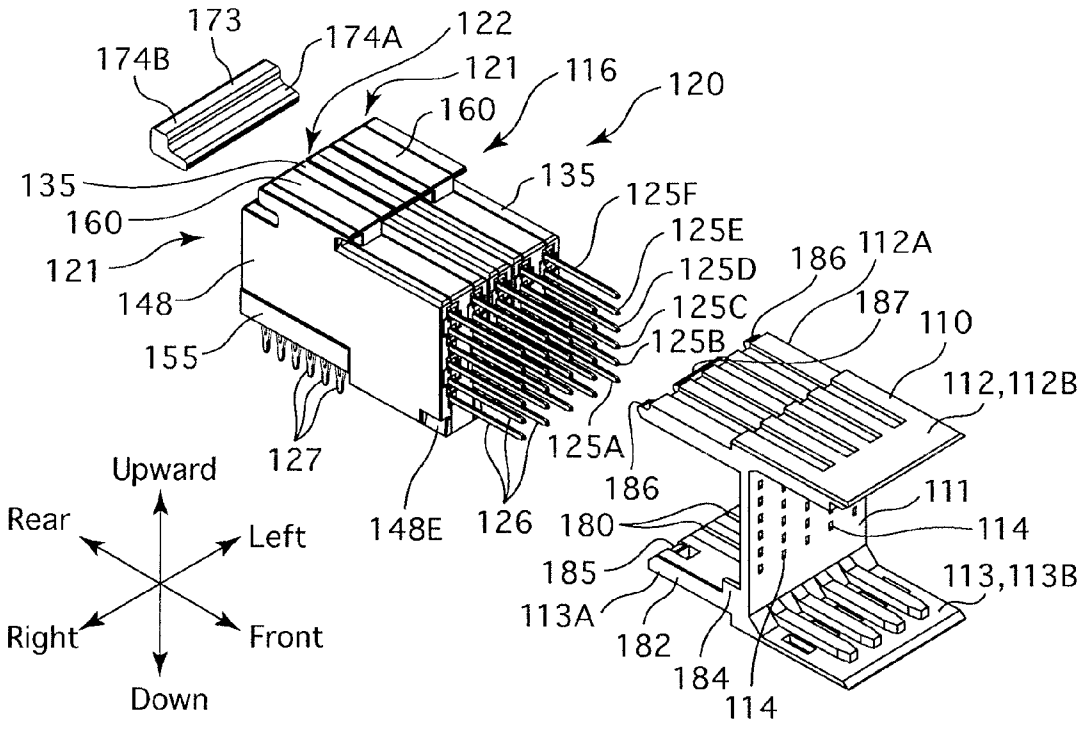

173
174A
122
174B
121
116
120
160
135
135
160
125F
125E
121
125D
186
112A
148
125C
187
155
125B
110
112,112B
127
125A
186
148E
126
180
111
114
185
113,113B
113A
182
184
114
Upward
Rear
Left
Right
Front
Down

Fig. 51

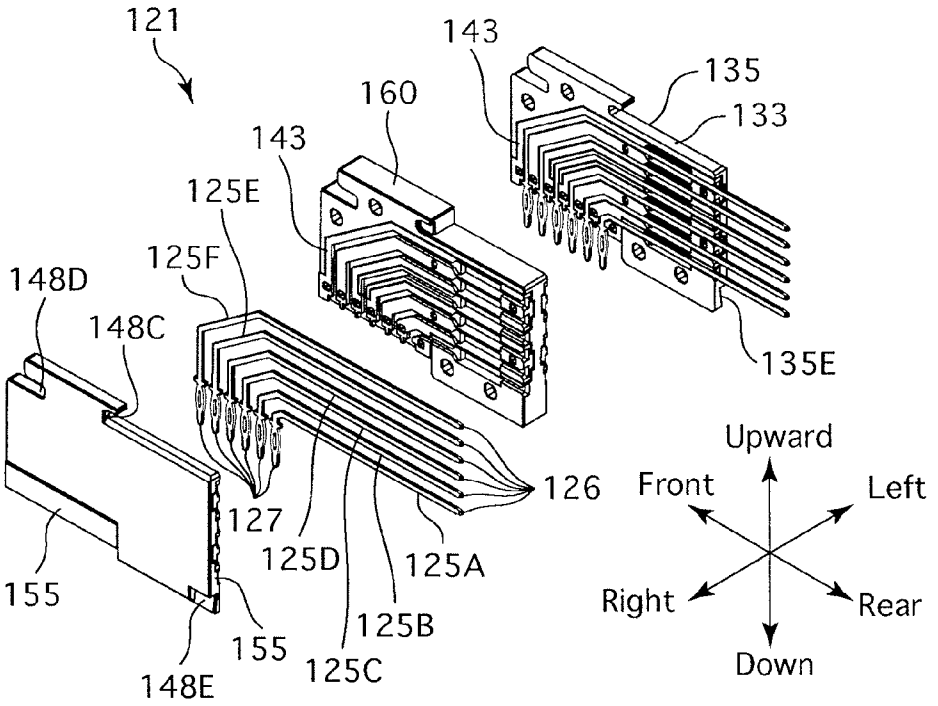

121
143
135
133
160
143
125E
125F
148D
148C
135E
126
127
125D
125A
155
155
125B
125C
148E
Upward
Front
Left
Right
Rear
Down

Fig. 52

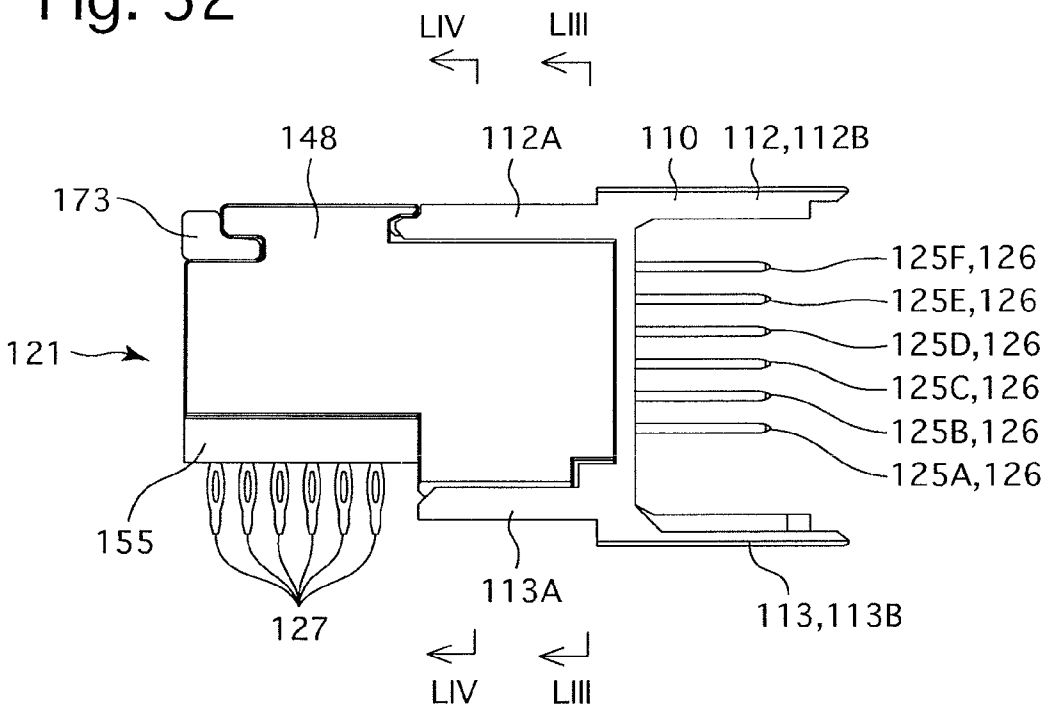

LIV
LIII
148
112A
110
112,112B
173
125F,126
125E,126
125D,126
125C,126
125B,126
125A,126
121
155
113A
113,113B
127
LIV
LIII

Fig. 53

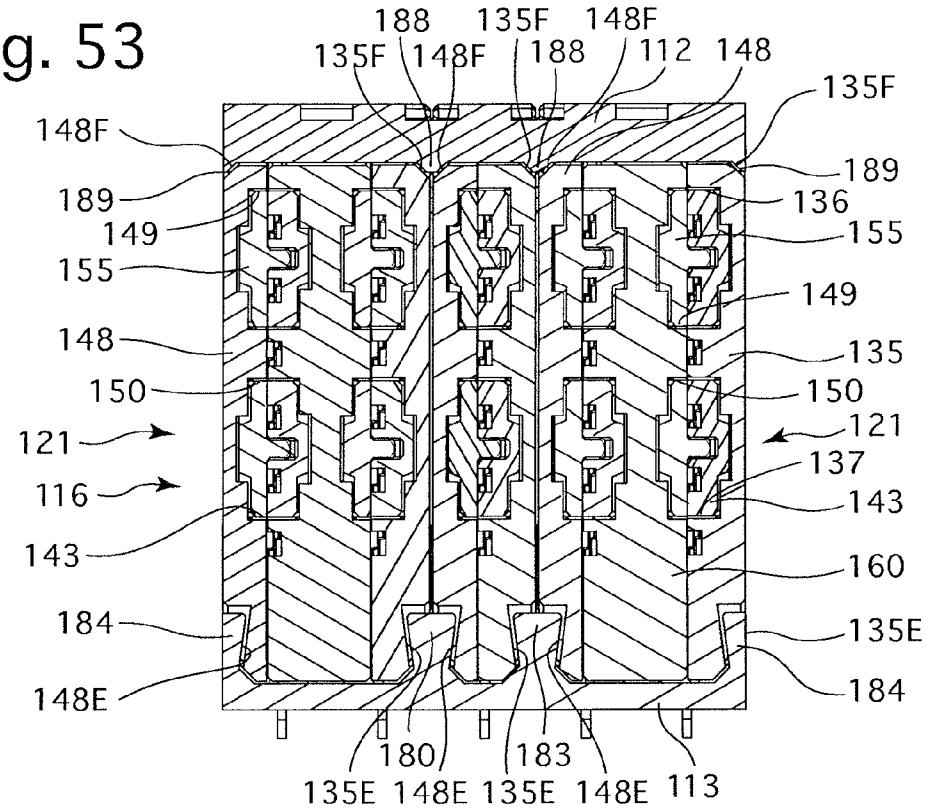

188
135F
148F
135F
148F
188
112
148
135F
148F
189
189
136
149
155
155
149
148
135
150
150
121
121
137
116
143
143
160
184
135E
148E
184
180
183
135E
148E
135E
148E
113

Fig. 54

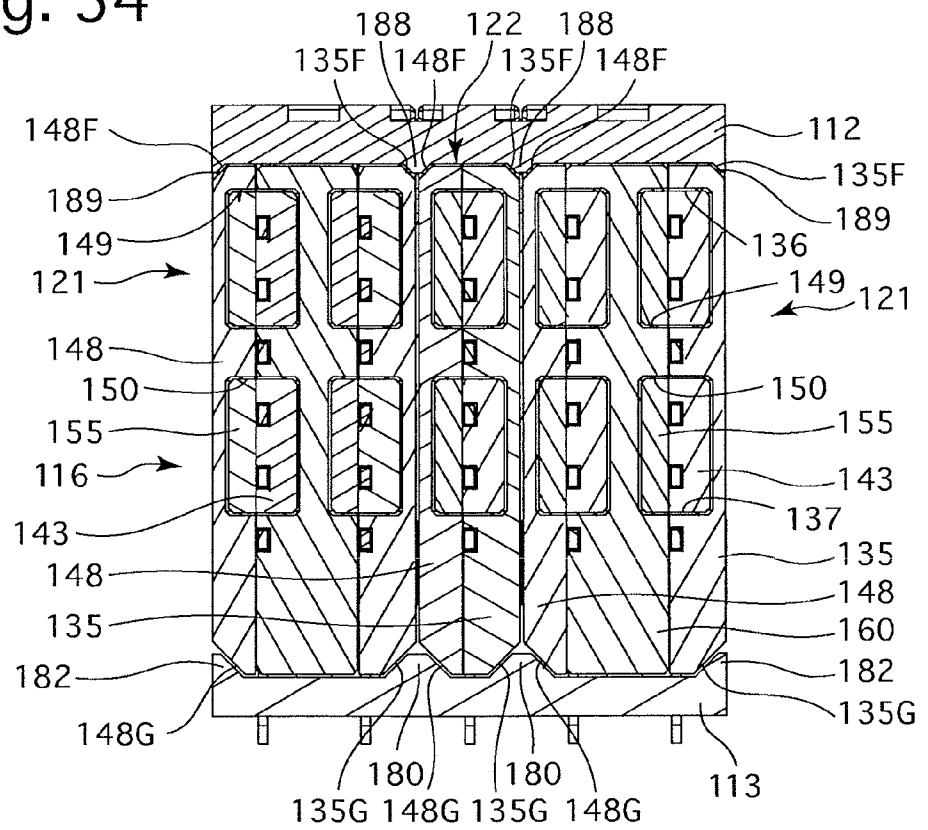

188
122
188
135F
148F
135F
148F
148F
112
135F
189
189
136
149
121
121
149
148
150
150
155
155
116
143
137
143
135
148
148
135
160
182
182
135G
148G
180
180
113
135G
148G
135G
148G

Fig. 55

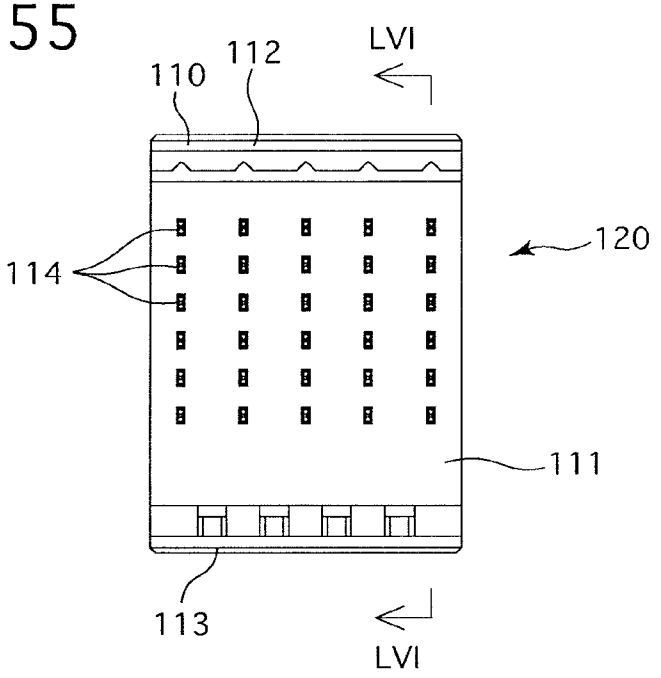

LVI
110
112
120
114
111
113
LVI

Fig. 56

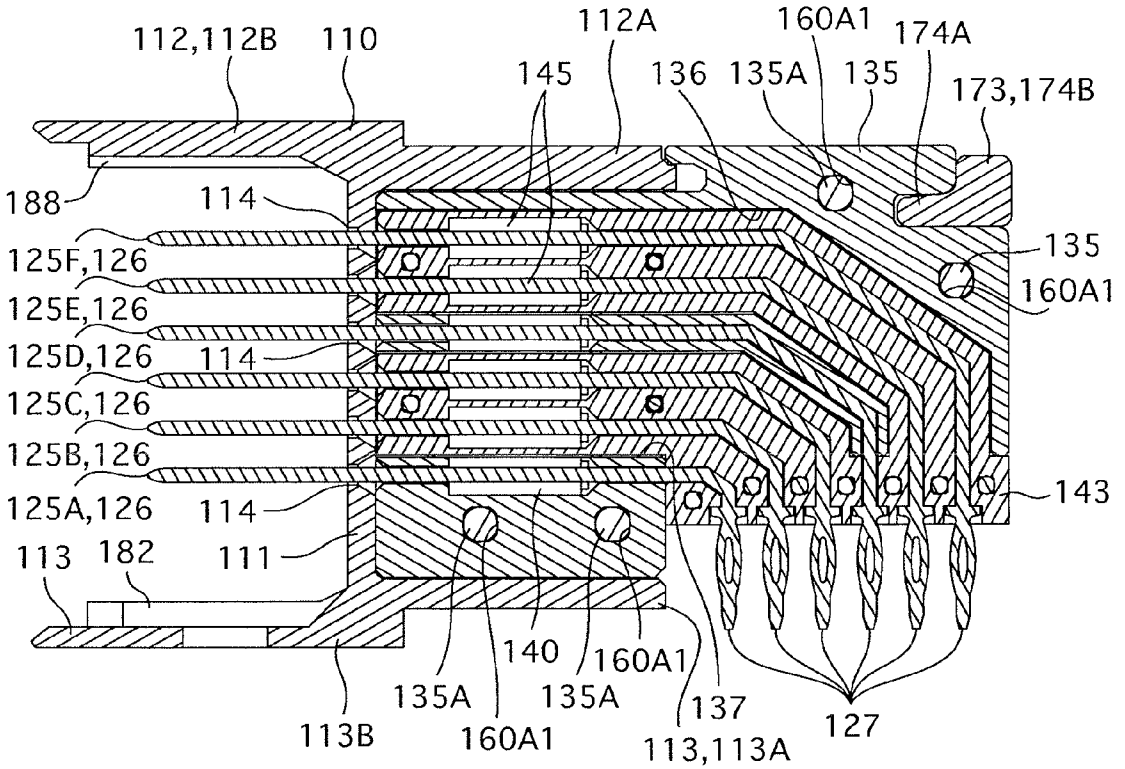

112,112B
110
112A
160A1
174A
145
136
135A
135
173,174B
188
114
125F,126
125E,126
125D,126
125C,126
125B,126
125A,126
113
182
111
135
160A1
143
140
160A1
135A
135A
137
127
113B
160A1
113,113A

Fig. 57

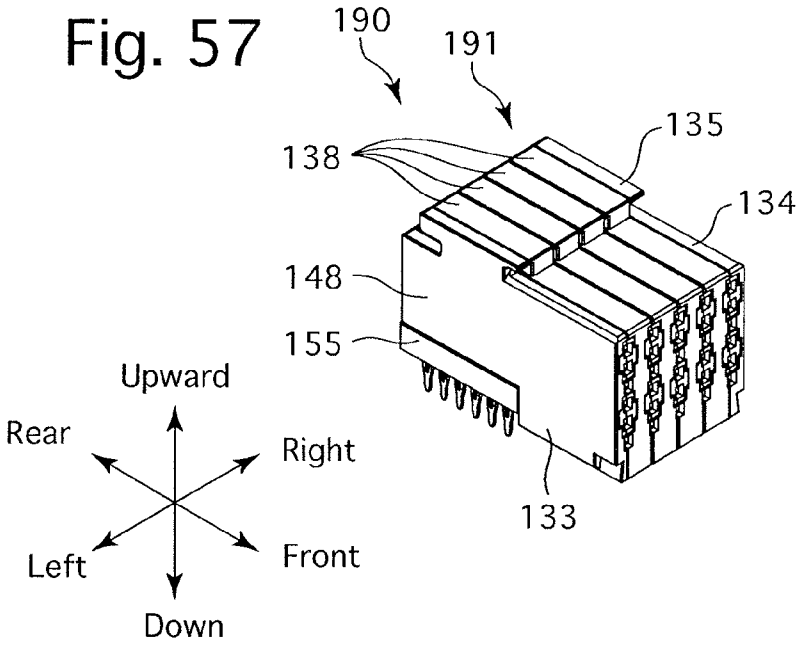

190
191
135
138
134
148
155
133
Upward
Rear
Right
Left
Front
Down

Fig. 58

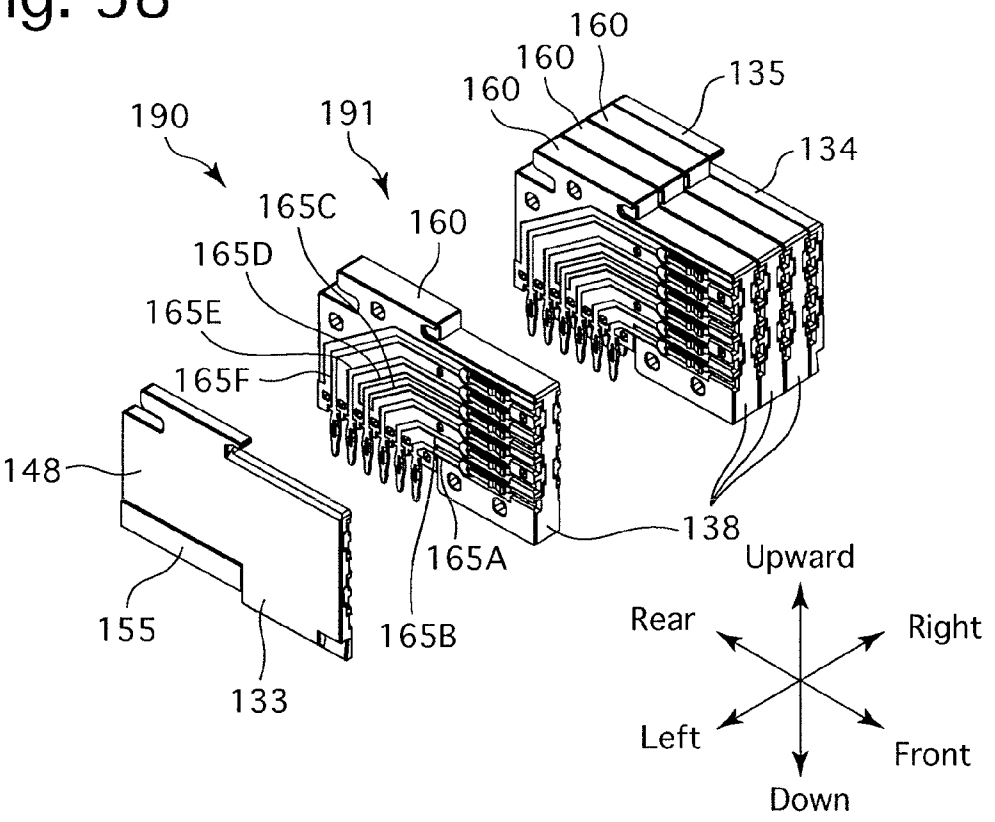

160
160
160
135
134
190
191
165C
160
165D
165E
165F
148
138
165A
155
165B
133
Upward
Rear
Right
Left
Front
Down

Fig. 59

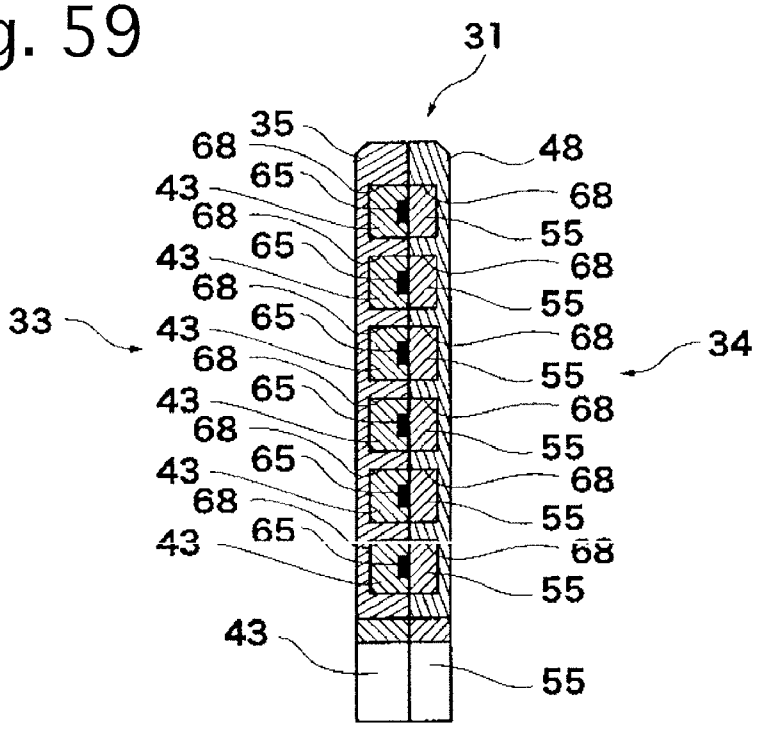

31
35
68
65
43
68
65
43
68
65
33
43
68
65
43
68
65
43
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65
43
48
68
55
68
55
68
55
34
68
55
68
55
68
55
43
55

Fig. 60

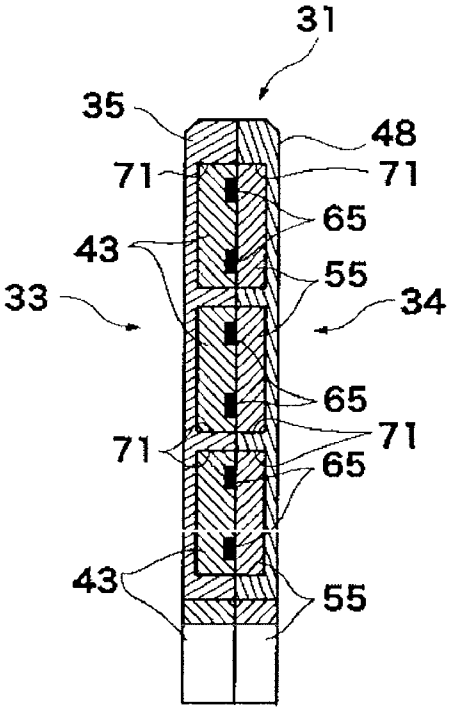
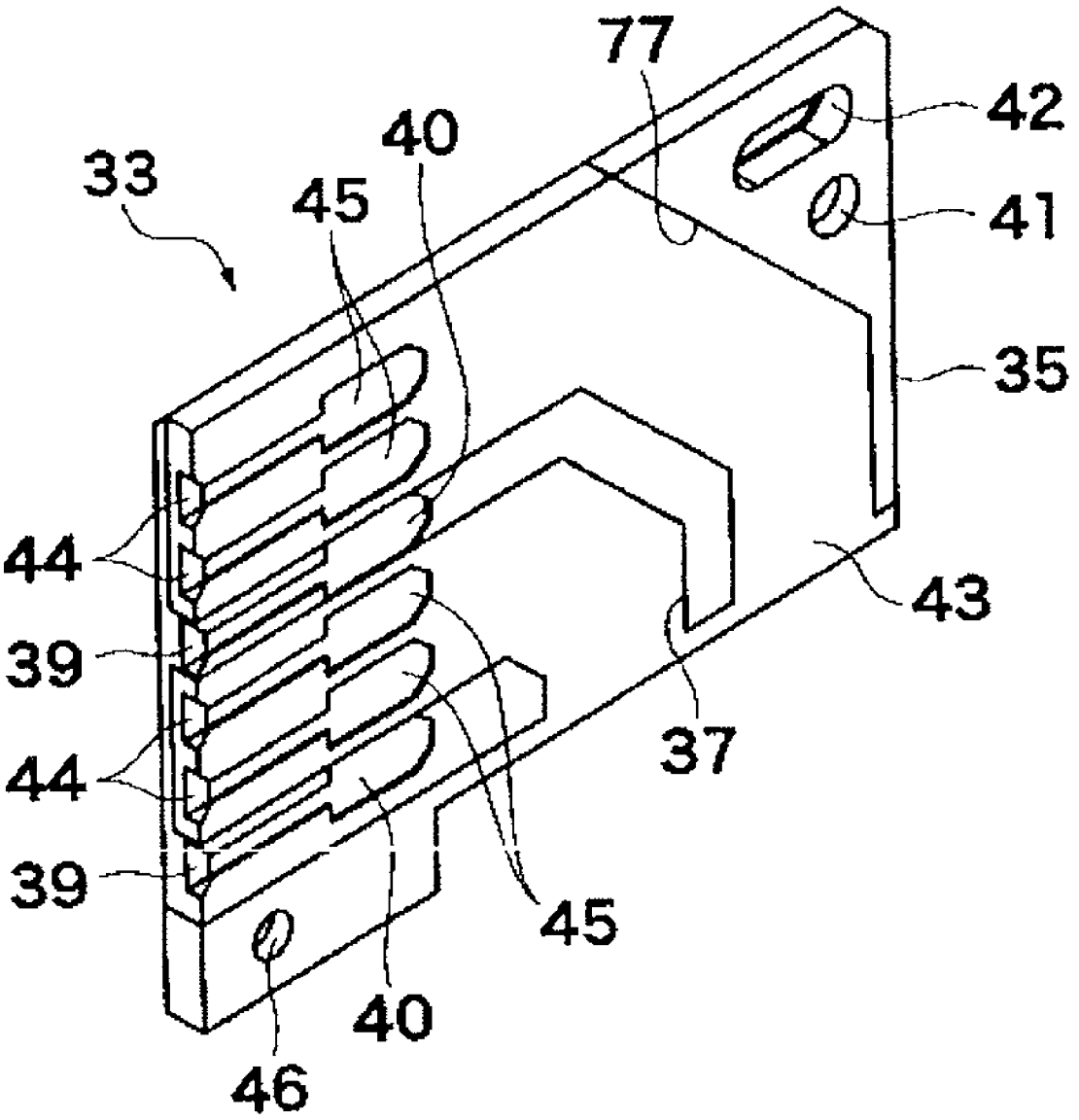

31
35
48
71
71
65
43
55
33
34
65
71
71
65
43
55

Fig. 61



CONNECTOR AND METHOD OF PRODUCING THE SAME

CROSS REFERENCE TO RELATED APPLICATION

[0001] The present invention is related to and claims priority of the following co-pending applications, namely, Japanese Patent Applications Nos. 2007-117407 filed on Apr. 26, 2007 and 2007-323626 filed on Dec. 14, 2007.

BACKGROUND OF THE INVENTION

[0002] 1. Field of the Invention

[0003] The present invention relates to a type of connector including a plurality of contact modules, and further relates to a method of producing this type of connector.

[0004] 2. Description of the Prior Art

[0005] In recent years, information and communication apparatuses, broadcast and video apparatuses, control devices for factory automation systems, medical equipment, semi-conductor manufacturing equipment, semi-conductor testers, etc., have been required to process enormous volumes of data at a high speed with a high degree of precision. Therefore, connectors for these apparatuses or devices are required to have a high shielding capability.

[0006] The connector (the plug connector **3**) disclosed in Japanese unexamined patent publication 2005-197163 is provided with a front housing **5** and a plurality of contact modules **6** which are fixed to the front housing **5** to be arranged in layers in a specific direction.

[0007] Each contact module **6** includes an insulator **28**, a plurality of signal contacts **16** fixed to the insulator **28**, and a plurality of shielding members (the first ground plates **14** and the second ground plates **15**) which are made of metal by insert molding and embedded in the insulator **28**. One end of each signal contact **16** is connected to a board (electrical circuit board), while the other end of each signal contact **16** is connectable with contact pins of another connector (the receptacle connector **4**), respectively.

[0008] Each of the first and second ground plates **14** and **15** includes a plurality of substantially L-shaped portions **18** and a plurality of protrusion-shaped ribs **22**. The substantially L-shaped portions **18** and the protrusion-shaped ribs **22** partly surround the signal contacts **16** in the insulator **28** to shield each signal contact **16** electromagnetically.

[0009] However, in the connector disclosed in the aforementioned patent publication, the connector needs to be provided with shielding members (the first ground plates **14** and the second ground plates **15**) and also needs to be formed in a complicated shape in order to exhibit a shielding effect. Therefore, the number of elements of the connector increases; moreover, it is difficult to increase productivity, and accordingly, the cost of production tends to increase.

[0010] In addition, although the metal-made shielding members are provided for the purpose of surrounding the signal contacts **16**, the internal area and the external surface area of an integrally-molded product **27** (i.e., the portion of the contact module **6** excluding the signal contacts **16**) in which no shielding member exits are large, and accordingly, it is hard to obtain a sufficient shielding effect.

[0011] Additionally, since the plurality of shielding members are embedded in the insulator **28**, it is difficult to miniaturize the integrally-molded product **27** (it is difficult for the integrally-molded product **27** to have a high a space-saving efficiency). Accordingly, each contact module **6** becomes large in size, thus increasing the dimensions of the connector.

[0012] Additionally, since the plurality of shielding members are embedded in the insulator **28**, it is difficult to achieve a higher density in each contact module **6** (i.e., increase the number of the signal contacts **16** in each contact module **6** with no increase in size of each contact module **6**).

SUMMARY OF THE INVENTION

[0013] The present invention provides a simple and easy-to-produce connector (receptacle/plug) having a small number of elements, wherein a high-shielding capability is obtained even if each contact module is miniaturized.

[0014] According to an aspect of the present invention, a receptacle is provided, including a plurality of contact modules, each of which includes a plurality of contacts, one of common ends of the contacts being connected to a corresponding plurality of contact pins of a plug, respectively, when the receptacle and the plug are connected to each other, and the other of the common ends of the contacts being connected to a circuit board. Each of the plurality of contact modules includes a plurality of holding plates arranged in a direction of thickness of the each contact module. At least one conductive layer and at least one insulating portion are formed on each of opposed surfaces of adjacent holding plates of the plurality of holding plates, and at least one of the plurality of contacts is held between the insulating portions that are formed on the opposed surfaces of the adjacent holding plates, respectively.

[0015] In an embodiment, a plug is provided, including a plurality of contact modules, each of which includes a plurality of contact pins, one of common ends of the contact pins being inserted into a receptacle to be connected to a corresponding plurality of contacts included in the receptacle, respectively, when the plug and the receptacle are connected to each other, and the other of the commons ends of the plurality of contact pins being connected to a circuit board. Each of the contact modules includes a plurality of holding plates arranged in a direction of thickness of the each contact module. At least one conductive layer and at least one insulating portion are formed on each of opposed surfaces of adjacent holding plates of the holding plates. At least one of the contact pins is held between the insulating portions that are formed on the opposed surfaces of the adjacent holding plates, respectively. It is desirable for each of the plurality of contact modules to include two adjacent holding plates of the plurality of holding plates.

[0016] It is desirable for each of the plurality of contact modules to include at least three holding plates of the plurality of holding plates.

[0017] Accordingly, the receptacle and the plug achieve a smaller number of elements and are simpler in structure than those of conventional connectors using one or more metal-made shielding members in either case where the contact or contact pins of the receptacle and the plug are constituted by the same type of contacts or contact pins (this case also includes both the case of single-ended signaling and the case of differential signaling, as described above, and where the contact or contact pins of the receptacle and the plug are constituted by two types of contacts or contact pins.

[0018] Moreover, since no metal shielding member becomes no longer necessary, each contact module can be made smaller than before and the contacts or contact pins in each contact module can be further densified in the case

where each contact module is provided therein with the same number of contacts or contact pins as a conventional contact module.

[0019] Furthermore, the shielding effect of the connector (receptacle/plug) can be enhanced because the surface area of each conductive layer can be increased. Accordingly, the connector (receptacle/plug) according to the present invention makes high-speed signal transmission possible.

[0020] It is desirable for the opposed surfaces of the adjacent holding plates to include first opening recesses and second opening recesses, respectively, the first opening recesses and second opening recesses being open at common end surfaces of the adjacent holding plates, respectively. Engaging holes, through which an outside and an inside of the each contact module are communicatively connected to each other, is formed by the first opening recesses and the second opening recesses upon the adjacent holding plates being joined to each other. Electrical continuity is established between the contacts of the each contact module and the contact pins of the plug upon the contact pins of the plug being inserted into the each contact module through the engaging holes, respectively.

[0021] It is desirable for the opposed surfaces of the adjacent holding plates to include first opening recesses and second opening recesses, respectively, the first opening recesses and the second opening recesses being open at common end surfaces of the adjacent holding plates, respectively. Engaging holes through which outside and inside of the each contact module are communicatively connected to each other are formed by the first opening recesses and the second opening recesses upon the adjacent holding plates being joined to each other. The contact pins project to the outside of the each contact module through the engaging holes.

[0022] Accordingly, the connector (receptacle/plug) does not have to be provided with a housing that is an indispensable element of a convention connector, which achieves a further reduction in the number of elements of the connector.

[0023] It is desirable for at least one of the adjacent holding plates to include a plurality of contact holding grooves formed on the insulating portion, the contacts being engaged in the contact holding grooves to be held thereby, respectively.

[0024] It is desirable for some of the contacts to be held between the insulating portions formed on the adjacent holding plates, and for the remainder of the plurality of contacts to be held between the conductive layers formed on the adjacent holding plates.

[0025] It is desirable for a plurality of the insulating portions to be formed on each of the opposed surfaces of the adjacent holding plates with the conductive layer on the each of the opposed surfaces of the adjacent holding plates being provided on opposite sides of each of the plurality of insulating portions. Only one of the contacts is held between each of the insulating portions that are formed on the opposed surfaces of the adjacent holding plates, respectively.

[0026] Accordingly, each contact or contact pin can be securely held by the adjacent holding plates.

[0027] It is desirable for the conductive layer to be formed entirely over each of the opposed surfaces of the adjacent holding plates of the plurality of holding plates, and for the insulating portion to be formed partly on the conductive layer.

[0028] Accordingly, since the range of shielding by the conductive layer with respect to the contacts or contact pins that are held by the associated insulating portions widens, a far superior shielding effect is achieved.

[0029] It is desirable for the conductive layer to cover a pair of side edges of each of the insulating portions positioned on both sides of the plurality of contacts.

[0030] Accordingly, if each contact or contact pin is held between the insulating portions formed on the opposed surfaces of the adjacent holding plates, the perimeter of each contact or contact pin is perfectly shielded since each contact or contact pin is totally surrounded by the conductive layers of a pair of holding plates. Accordingly, an extremely superior shielding effect is obtained.

[0031] It is desirable for a continuous conductive layer to be formed on all surfaces of the adjacent holding plates other than the opposed surfaces of the adjacent holding plates.

[0032] If the conductive layer portion is formed entirely over the surface of each holding plate in such a manner, the surface area of each conductive layer becomes extremely large, so that a far superior shielding effect is achieved.

[0033] It is desirable for each of the plurality of holding plates to include a conductive layer portion including a resin-made substrate on which the conductive layer is plated, and at least one insulation recess formed on a surface which faces the other of the adjacent holding plates; and for the insulating portion to be made of a resin material and be provided in the insulation recesses so as to occupy the insulation recesses.

[0034] Accordingly, the holding plates can be easily produced.

[0035] It is desirable for the receptacle to include a retainer which is attached to a contact module group formed by the plurality of contact modules arranged in layers to combine the plurality of contact modules into one integral module.

[0036] Accordingly, the contact module group can be easily combined into one integral body.

[0037] In an embodiment, a method is provided for making a receptacle with a plurality of contact modules, each of which includes a plurality of contacts, one of common ends of the contacts being connected to a corresponding plurality of contact pins of a plug, respectively, when the receptacle and the plug are connected to each other, and the other of the common ends of the contacts being connected to a circuit board. The method includes forming a plurality of conductive layer portions which each include a resin-made substrate which has been plated; forming a plurality of holding plates by putting a resin-made insulating portion on each of the conductive layer portions so as to occupy a part of a surface thereof; forming the contact modules by arranging the holding plates in a direction of thickness of the each contact module and by joining opposed surfaces of adjacent holding plates thereof, on which the insulating resin-made insulating portion is placed, to each other so that at least one of the contacts is held between the insulating portions that are formed on the opposed surfaces of the adjacent holding plates; and connecting the contact modules into one integral module.

[0038] Accordingly, a receptacle which includes contact modules which are simple in structure with a small number of elements and which can achieve a high shielding capability even if the size of each contact module is reduced, can be easily produced.

[0039] In an embodiment, a method is provided for making a plug with a plurality of contact modules each of which includes a plurality of contact pins, one of common ends of the contact pins being inserted into a receptacle to be con-

nected to a corresponding plurality of contacts included in the receptacle, respectively, when the plug and the receptacle are connected to each other, and the other of the common ends of the plurality of contact pins being connected to a circuit board. The method includes forming a plurality of conductive layer portions which each include a resin-made substrate which has been plated, respectively; forming a plurality of holding plates by putting a resin-made insulating portion on each of the conductive layer portions so as to occupy a part of a surface thereof; forming the contact modules by arranging the holding plates in a direction of thickness of the each contact module and by joining opposed surfaces of adjacent holding plates thereof, on which the insulating resin-made insulating portion is placed, to each other so that at least one of the contact pins is held between the insulating portions that are formed on the opposed surfaces of the adjacent holding plates; and connecting the contact modules into one integral module.

[0040] Similarly, a plug which includes contact modules which are simple in structure with a small number of elements and which can achieve a high shielding capability even if the size of each contact module is reduced, can be easily produced.

[0041] It is desirable for the connecting of the contact modules into one integral module to include arranging the plurality of contact modules in layers to form a contact module group, and attaching a retainer to the contact module group.

[0042] Accordingly, a connector (receptacle/plug) can be easily produced since the contact module group can be easily combined into one integral body.

BRIEF DESCRIPTION OF THE DRAWINGS

[0043] The present invention will be discussed below in detail with reference to the accompanying drawings, in which:

[0044] FIG. **1** is a perspective view of a first embodiment of a connector according to the present invention which includes a receptacle and a plug, showing a state where the receptacle and the plug are connected to each other;

[0045] FIG. **2** is a perspective view of the receptacle and the plug, showing a state where the receptacle and the plug are disengaged from each other;

[0046] FIG. **3** is an exploded perspective view of the receptacle, which is disassembled into three pieces: a contact module group, a retainer and a connecting rod;

[0047] FIG. **4** is a front elevational view of the plug and the receptacle which are connected to each other;

[0048] FIG. **5** is a cross sectional view taken along the V-V line shown in FIG. **4**, viewed in the direction of the appended arrows;

[0049] FIG. **6** is a perspective view of each contact module of the receptacle;

[0050] FIG. **7** is an exploded perspective view of the contact module shown in FIG. **6**;

[0051] FIG. **8** is an exploded perspective view of the contact module shown in FIG. **6**, viewed from a different angle;

[0052] FIG. **9** is a side elevational view of the contact module shown in FIG. **6**;

[0053] FIG. **10** is a cross sectional view taken along the X-X line shown in FIG. **9**, viewed in the direction of the appended arrows;

[0054] FIG. **11** is a cross sectional view taken along the XI-XI line shown in FIG. **9**, viewed in the direction of the appended arrows;

[0055] FIG. **12** is a perspective view of one of the two holding plates of each contact module;

[0056] FIG. **13** is a side elevational view of the holding plate shown in FIG. **12**;

[0057] FIG. **14** is a cross sectional view taken along the XIV-XIV line shown in FIG. **13**, viewed in the direction of the appended arrows;

[0058] FIG. **15** is a perspective view of the holding plate shown in FIG. **12** before an insulating portion is molded integrally with the holding plate;

[0059] FIG. **16** is a side elevational view of the holding plate shown in FIG. **15**;

[0060] FIG. **17** is a cross sectional view taken along the XVII-XVII line shown in FIG. **16**, viewed in the direction of the appended arrows;

[0061] FIG. **18** is a perspective view of the other of the two holding plates of each contact module;

[0062] FIG. **19** is a side elevational view of the holding plate shown in FIG. **18**;

[0063] FIG. **20** is a cross sectional view taken along the XX-XX line shown in FIG. **19**, viewed in the direction of the appended arrows;

[0064] FIG. **21** is a perspective view of the holding plate shown in FIG. **18** before an insulating portion is molded integrally with the holding plate;

[0065] FIG. **22** is a side elevational view of the holding plate shown in FIG. **21**;

[0066] FIG. **23** is a cross sectional view taken along the XXIII-XXIII line shown in FIG. **22**, viewed in the direction of the appended arrows;

[0067] FIG. **24** is a rear perspective view of the plug shown in FIGS. **1** and **2**;

[0068] FIG. **25** is a plan view of the plug;

[0069] FIG. **26** is a cross sectional view taken along the XXVI-XXVI line shown in FIG. **25**, viewed in the direction of the appended arrows;

[0070] FIG. **27** is a perspective view of a second embodiment of the connector according to the present invention which includes a receptacle and a plug, showing a state where the receptacle and the plug are disengaged from each other;

[0071] FIG. **28** is a perspective view of the receptacle and the plug of the second embodiment of the connector, showing a state where the receptacle and the plug are connected to each other;

[0072] FIG. **29** is an exploded front perspective view of the receptacle of the second embodiment of the connector, which is disassembled into three pieces: a contact module group, a retainer and a connecting rod, viewed obliquely from above;

[0073] FIG. **30** is an exploded rear perspective view of the contact module group, the retainer and the connecting rod that are shown in FIG. **29**, viewed obliquely from above;

[0074] FIG. **31** is a front perspective view of the receptacle of the second embodiment of the connector, viewed obliquely from above;

[0075] FIG. **32** is a rear perspective view of the receptacle of the second embodiment of the connector, viewed obliquely from below;

[0076] FIG. **33** is an exploded front perspective view of the receptacle of the second embodiment of the connector, which is disassembled into five pieces: two side contact modules, a center contact module, a retainer and a connecting rod, viewed obliquely from above;

[0077] FIG. **34** is an exploded perspective view of each side contact module shown in FIG. **33**;

[0078] FIG. **35** is an exploded perspective view of each side contact module shown in FIG. **33**;

[0079] FIG. **36** is a perspective view of the conductive layer portion of the center holding plate of the side contact module shown in FIG. **35** in a state before an insulating portion is molded integrally with the conductive layer portion, viewed obliquely from below;

[0080] FIG. **37** is a perspective view of the conductive layer portion of the right-side holding plate of the side contact module shown in FIG. **35** in a state before an insulating portion is molded integrally with the conductive layer portion, viewed obliquely from the upper left side;

[0081] FIG. **38** is a perspective view of the conductive layer portion shown in FIG. **36**, viewed obliquely from the upper right side;

[0082] FIG. **39** is a perspective view of the conductive layer portion shown in FIG. **36**, viewed obliquely from the upper left side;

[0083] FIG. **40** is an enlarged front perspective view of an insulating portion shown in FIG. **35**, viewed obliquely from the upper left side thereof;

[0084] FIG. **41** is an enlarged front perspective view of the insulating portion shown in FIG. **40**, viewed obliquely from the upper right side thereof;

[0085] FIG. **42** is an enlarged perspective view of a contact (signal contact) of the second embodiment of the connector, viewed obliquely from the upper left side;

[0086] FIG. **43** is a front elevational view of the receptacle of the second embodiment of the connector;

[0087] FIG. **44** is a cross sectional view of the receptacle of the second embodiment of the connector taken along the XLIV-XLIV line shown in FIG. **43**, viewed in the direction of the appended arrows;

[0088] FIG. **45** is a bottom view of the receptacle of the second embodiment of the connector;

[0089] FIG. **46** is a side elevational view of the receptacle of the second embodiment of the connector;

[0090] FIG. **47** is a cross sectional view taken along the XLVII-XLVII line shown in FIG. **46**, viewed in the direction of the appended arrows;

[0091] FIG. **48** is a cross sectional view taken along the XLVIII-XLVIII line shown in FIG. **46**, viewed in the direction of the appended arrows;

[0092] FIG. **49** is a cross sectional view taken along the XLIX-XLIX line shown in FIG. **46**, viewed in the direction of the appended arrows;

[0093] FIG. **50** is an exploded perspective view of the plug of the second embodiment of the connector, which is disassembled into three pieces: a contact module group, a retainer and a connecting rod, viewed obliquely from above;

[0094] FIG. **51** is an exploded perspective view of each side contact module shown in FIG. **50**;

[0095] FIG. **52** is a side elevational view of the plug shown in FIG. **51**;

[0096] FIG. **53** is a cross sectional view taken along the LIII-LIII line shown in FIG. **52**, viewed in the direction of the appended arrows;

[0097] FIG. **54** is a cross sectional view taken along the LIV-LIV line shown in FIG. **52**, viewed in the direction of the appended arrows;

[0098] FIG. **55** is a rear elevational view of the plug of the second embodiment of the connector;

[0099] FIG. **56** is a cross sectional view taken along the LVI-LVI line shown in FIG. **55**, viewed in the direction of the appended arrows;

[0100] FIG. **57** is a perspective view of a contact module group in a modified embodiment of the receptacle, viewed obliquely from the upper left side;

[0101] FIG. **58** is an exploded perspective view of the contact module group shown in FIG. **57**, showing a state where the contact module group is partly disassembled;

[0102] FIG. **59** is a view similar to that of FIG. **10**, showing a modified embodiment of each contact module of the receptacle in the first embodiment of the connector;

[0103] FIG. **60** is a view similar to that of FIG. **10**, showing another modified embodiment of each contact module of the receptacle in the first embodiment of the connector; and

[0104] FIG. **61** is a view similar to that of FIG. **12**, showing one of the two holding plates of another modified embodiment of each contact module of the receptacle in the first embodiment of the connector.

DESCRIPTION OF THE PREFERRED EMBODIMENTS

[0105] A first embodiment of a connector according to the present invention will be discussed below with reference to FIGS. **1** through **26**. Note that forward, rearward, leftward and rightward directions of the connector (receptacle/plug) in the following descriptions are determined with reference to the double-headed arrows shown in FIGS. **1**, **2**, **6**, etc.

[0106] As shown in FIGS. **1** and **2**, the first embodiment of the connector **10** is for use in differential signaling and includes ground contacts and signal contacts. For instance, the connector **10** is applicable to information and communication apparatuses, broadcast and video apparatuses, control devices for factory automation systems, medical equipment, semi-conductor manufacturing equipment, semi-conductor testers, etc. The connector **10** is provided with a plug **20** and a receptacle **30** which are engageable with each other. The plug **20** and the receptacle **30** are electrically connected to each other when connected to each other as shown in FIG. **1**.

[0107] As shown in FIGS. **2**, **24** through **26**, etc., the plug **20** is provided with an insulator **21** having a substantially U-shaped cross section, a large number of ground contact pins **25**A and **25**D, and a large number of signal contact pins **25**B, **25**C, **25**E and **25**F. The insulator **21** is made of a heat-resistant insulating synthetic resin by injection molding. The insulator **21** is provided in a bottom plate portion **22** thereof with a large number of through holes into which the ground contact pins **25**A and **25**D and the signal contact pins **25**B, **25**C, **25**E and **25**F are press-fitted. The ground contact pins **25**A and **25**D and the signal contact pins **25**B, **25**C, **25**E and **25**F are all identical in shape and arranged in a 10 by 6 matrix of contact pins, i.e., there are ten columns of contact pins arranged in the left-right direction. The ground contact pins **25**A and **25**D and the signal contact pins **25**B, **25**C, **25**E and **25**F are all stamp molded out of metal. More specifically, in order to manufacture each contact pin **25**A through **25**F of the receptacle **30**, a base material (e.g., phosphor bronze, beryllium copper, titanium copper, stainless steel, or Corson-copper alloy) is first coated with a base plating (e.g., nickel (Ni) plating) and subsequently with a finish plating (e.g., gold(Au) plating, tin(Sn)-copper(Cu) plating, or tin(Sn)-lead(Pb) plating). The rear ends of the ground contact pins **25**A and **25**D and the signal contact pins **25**B, **25**C, **25**E and **25**F are formed as contact ends connectable with the front ends of ground

contacts **65**A and **65**D and signal contacts **65**B, **65**C, **65**E and **65**F of the plug **20**, respectively. The front ends of the ground contact pins **25**A and **25**D and the signal contact pins **25**B, **25**C, **25**E and **25**F are formed as press-fit terminals **27** which are driven (press-fitted) into through holes formed in a circuit board (not shown), respectively. The press-fit terminals **27** of the ground contact pins **25**A and **25**D are electrically connected to a ground pattern on the circuit board, and the press-fit terminals **27** of the signal contact pins **25**B, **25**C, **25**E and **25**F are electrically connected to a circuit pattern on the same circuit board.

[0108] The receptacle **30** will be discussed with reference mainly to FIGS. **5** through **23**. The receptacle **30** is provided with ten contact modules **31** and a retainer **75** as relatively large elements of the receptacle **30**.

[0109] Each contact module **31** is provided with a pair of holding plates **33** and **34**, two of the ground contacts **65**A and **65**D and four of the signal contacts **65**B, **65**C, **65**E and **65**F.

[0110] As discussed below, the holding plate **33** shown in FIGS. **12** through **14** is made of two resin members integrated into one piece.

[0111] A conductive layer portion (conductive layer) **35** serving as a base of the holding plate **33** is made by firstly being molded from an insulating synthetic resin into the shape shown in FIGS. **15** through **17** with the use of molding dies (not shown), and subsequently being entirely plated so as to constitute a continuous conductive layer.

[0112] The method of applying such plating can be a so-called resin plating method or thin-film forming method (evaporation method, spattering, etc.). In the case of the resin plating method, firstly a molded member (molding) as a base of the conductive layer portion **35** is subjected to a grease removing process to remove grease from the outer surface of the molded member, a cleaning process to cleanse the outer surface of the molded member and thereafter a surface activating process to activate the outer surface of the molded member by catalysis. Thereafter, the molded member is given electroless plating, nickel strike plating, electric copper plating, nickel plating, and finish plating in that order. Alternatively, the conductive layer portion **35** can be molded by MID (molded interconnect device).

[0113] As shown in the drawings, the conductive layer portion **35** is provided on the inner surface thereof with two insulation recesses **36** and **37** which are open to both the front end surface and the bottom end surface of the conductive layer portion **35**. The conductive layer portion **35** is further provided, on two ribs formed on the inner surface of the conductive layer portion **35** which are respectively adjacent to the two insulation recesses **36** and **37**, with two opening recesses **39** and two end accommodation grooves (ground-contact holding grooves) **40** positioned immediately behind the two opening recesses **39**, respectively. The two opening recesses **39** are elongated rearward from the front end surface of the conductive layer portion **35**, and the two end accommodation grooves **40** are communicatively connected with the rear ends of the two opening recesses **39** and are greater in width than the two opening recesses **39**, respectively. The conductive layer portion **35** is further provided, on the inner surface thereof in the vicinity of the upper rear corner of the conductive layer portion **35**, with a circular-columnar-shaped engaging recess (bottomed hole) **41** and an elongated insertion hole (through-hole) **42**.

[0114] An insulating portion **43** made of an insulating synthetic resin is molded with the use of molding dies (not shown) to be integral with the inner surface of the conductive layer portion **35**, which is molded in the above described manner, so that the two insulation recesses **36** and **37** are provided (occupied) with the insulating portion **43** as shown in FIGS. **12** through **14**. In addition, at the time of molding the insulating portion **43**, four opening recesses **44** which are identical in shape to the two opening recesses **39**, and associated four end accommodation grooves (contact holding grooves) **45** which are identical in shape to the two end accommodation grooves **40** and are communicatively connected with the rear ends of the four opening recesses **44** are formed in the insulating portion **43** in the two insulation recesses **36** and **37**, and a circular-columnar-shaped engaging recess **46** is formed in the insulating portion **43** in the vicinity of the bottom front corner of the conductive layer portion **35**.

[0115] The two holding plates **33** and **34** of each contact module **31** are substantially bilaterally symmetrical in shape; however, the holding plate **34** is partly different in shape from the holding plate **33**.

[0116] A conductive layer portion (conductive layer) **48** of the holding plate **34**, which is shown in FIGS. **21** through **23**, is an element corresponding to the conductive layer portion **35** of the holding plate **33** (the material of the conductive layer portion **48** (including the plating material) is the same as that of the conductive layer portion **35**). The conductive layer portion **48** is molded with the use of molding dies (not shown) in the same manner as the conductive layer portion **35**, and is provided with two insulation recesses **49** and **50**, two opening recesses **51** and two end accommodation grooves (ground-contact holding grooves) **52** which correspond to the two insulation recesses **36** and **37**, the two opening recesses **39** and the two end accommodation grooves **40** of the conductive layer portion **35** of the holding plate **33**, respectively. The two insulation recesses **49** and **50**, two opening recesses **51** and two end accommodation grooves **52**, and the two insulation recesses **36** and **37**, the two opening recesses **39** and the two end accommodation grooves **40** are bilaterally symmetrical to each other (mirror images to each other), respectively. Unlike the conductive layer portion **35**, the conductive layer portion **48** is further provided, on two ribs formed on the inner surface of the conductive layer portion **48** which are respectively adjacent to the two insulation recesses **49** and **50**, with two communication grooves (ground-contact holding grooves) **53**. One end (front ends) of each of the two communication grooves **53** is communicatively connected to each of the two end accommodation grooves **52**, respectively, and the other end of each of the two communication grooves **53** is open to the bottom end surface of the conductive layer portion **48**. Each communication groove **53** is narrower than each end accommodation groove **52**. Additionally, the conductive layer portion **48** is provided, in the vicinity of the upper rear corner of the conductive layer portion **48**, with an elongated insertion hole (through-hole) **42** which corresponds to the elongated insertion hole **42** of the conductive layer portion **35**, and is further provided, on the inner surface thereof in the vicinity of the upper rear corner of the conductive layer portion **48**, with an engaging projection **54** which is shaped to correspond to the circular-columnar-shaped engaging recess **41** of the conductive layer portion **35** to be engageable therein. An insulating portion **55** which corresponds to the insulating portion **43** of the holding plate **33** is molded with the use of molding dies (not shown) to be integral with the inner surface of the conductive layer portion **48** after the conductive layer portion **48** has been molded (the material of

the insulating portion **55** and the method of molding thereof are the same as those of the insulating portion **43**). Four opening recesses **56** and four end accommodation grooves (contact holding grooves) **57** which correspond to the four opening recesses **44** and the four end accommodation grooves **45**, respectively, are formed on the inner surface of the insulating portion **55**. In addition, the conductive layer portion **48** is further provided on the inner surface of the insulating portion **55** with four communication grooves (contact holding grooves) **58** which respectively extend from the four end accommodation grooves **57** to the bottom end of the insulating portion **55**. Each communication groove **58** is narrower than each end accommodation groove **57**. Additionally, an engaging projection **59** which is shaped to correspond to the engaging recess **46** of the insulating portion **43** of the holding plate **33** to be engageable therein is formed in the insulating portion **55** in the vicinity of the bottom front corner of the conductive layer portion **48**.

[0117] The side edges (upper and lower side edges) of each insulating portion **43** and **55** in each associated insulation recess (**36**, **37**, **49** and **50**) are covered by the associated conductive layer.

[0118] The two ground contacts **65**A and **65**D and the four signal contacts **65**B, **65**C, **65**E and **65**F, which are held between the two holding plates **33** and **34**, are stamp molded out of metal. More specifically, to make each contact **65**A through **65**F, a base material (e.g., phosphor bronze, beryllium copper, titanium copper, stainless steel, or Corson-copper alloy) is coated firstly with a base plating (e.g., nickel (Ni) plating), and subsequently with a finish plating (e.g., gold (Au) plating, tin(Sn)-copper(Cu) plating, or tin(Sn)-lead(Pb) plating). The side shapes of the ground contacts **65**A and **65**D and the signal contacts **65**B, **65**C, **65**E and **65**F are all in the shape of a substantially letter L and mutually different in length. The front ends and the lower ends of all the ground contacts **65**A and **65**D and the signal contacts **65**B, **65**C, **65**E and **65**F are formed as bifurcated resilient (spring) portions **66** and press-fit terminals **67**, respectively.

[0119] The ground contacts **65**A and **65**D, the signal contacts **65**B, **65**C, **65**E and **65**F and the two holding plates **33** and **34** are combined into one integral component in the following manner.

[0120] First of all, the bifurcated resilient portions **66** of the ground contacts **65**A and **65**D are respectively accommodated in the two end accommodation grooves **52**, and middle portions (conductive positions) of the ground contacts **65**A and **65**D between the bifurcated resilient portions **66** and the press-fit terminals **67** thereof are respectively held by the two communication grooves **53** (with projections (not shown) which are formed on the aforementioned conductive portions of the ground contacts **65**A and **65**D pressing against side surfaces of the two communication grooves **53**, respectively) so that the press-fit terminals **67** of the ground contacts **65**A and **65**D project downward from the bottom end of the holding plate **34**. At the same time, the bifurcated resilient portions **66** of the signal contacts **65**B, **65**C, **65**E and **65**F are respectively accommodated in the four end accommodation grooves **57**, and middle portions (conductive positions) of the signal contacts **65**B, **65**C, **65**E and **65**F between the bifurcated resilient portions **66** and the press-fit terminals **67** thereof are respectively held by the four communication grooves **58** (with projections (not shown) which are formed on the aforementioned conductive portions of the signal contacts **65**B, **65**C, **65**E and **65**F pressing against side surfaces of the four communication grooves **58**, respectively) so that the press-fit terminals **67** of the signal contacts **65**B, **65**C, **65**E and **65**F project downward from the bottom end of the holding plate **34**.

[0121] Subsequently, the inner surface of the holding plate **33** is combined with the inner surface of the holding plate **34** to which the ground contacts **65**A and **65**D and the signal contacts **65**B, **65**C, **65**E and **65**F have been installed while the engaging projections **54** and **59** of the holding plate **34** are fitted into the engaging recesses **41** and **46**, respectively. Thereupon, the bifurcated resilient portions **66** of the ground contacts **65**A and **65**D are accommodated in the two end accommodation grooves **40** of the conductive layer portion **35** of the holding plate **33**, respectively, the bifurcated resilient portions **66** of the signal contacts **65**B, **65**C, **65**E and **65**F are accommodated in the four end accommodation grooves **45** of the conductive layer portion **35** of the holding plate **33**, respectively, the inner surfaces of the conductive layer portions **35** and **48** come in intimate contact with each other, and the inner surfaces of the insulating portions **43** and **55** come in intimate contact with each other. In addition, the two opening recesses **39** of the holding plate **33** and the two opening recesses **51** of the holding plate **34**, which face each other, form two engaging holes **69** at the front end of the contact module **31**, and the two opening recesses **44** of the holding plate **33** and the two opening recesses **56** of the holding plate **34**, which face each other, form two engaging holes **70** at the front end of the contact module **31** (see FIGS. **2**, **3** and **6**).

[0122] Ten of the contact modules **31**, each of which is assembled in the above described manner, are arranged in layers in the left-right direction as shown in FIG. **3** to constitute a contact module group **72**. Thereupon, the elongated insertion holes **42** of the ten contact modules **31** are aligned, so that a connecting rod **73** (see FIG. **3**) made of synthetic resin and having the same cross sectional shape as each elongated insertion hole **42** is inserted into each elongated insertion hole **42**. Additionally, the retainer **75** that is shaped as a rectangular frame is fitted on the outer peripheral surface of the front end of the contact module group **72**. Thereupon, the inner peripheral surface of the retainer **75** comes into intimate contact with the outer peripheral surface of the front end of the contact module group **72**, which makes each contact module **31** and the retainer **75** integral with each other.

[0123] After the receptacle **30** is assembled in the above described manner, the press-fit terminals **67** of the ground contacts **65**A and **65**D and the signal contacts **65**B, **65**C, **65**E and **65**F are driven (press-fitted) into the through holes formed in the aforementioned circuit board (not shown), respectively. Thereupon, the press-fit terminals **67** of the ground contacts **65**A and **65**D are connected to a ground pattern on this circuit board, and the press-fit terminals **67** of the signal contacts **65**B, **65**C, **65**E and **65**F are connected to a circuit pattern on this circuit board.

[0124] When the receptacle **30** and the plug **20**, each of which having the above described structure, are connected to each other as shown in FIG. **1** from an disengaged state shown in FIG. **2**, terminal contacts **26** of the ground contact pins **25**A and **25**D are inserted into the associated engaging holes **69**, respectively, that are formed on the front surface of the receptacle **30**, so that the terminal contacts **26** of the ground contact pins **25**A and **25**D enter the spaces formed between the associated end accommodation grooves **52** of the holding plate **34** and the associated end accommodation grooves **40** of the holding plate **33**, respectively, through the engaging holes **69**

as shown in FIG. **5**, while the terminal contacts **26** of the signal contact pins **25**B, **25**C, **25**E and **25**F are inserted into the associated engaging holes **70**, respectively, that are formed on the front surface of the receptacle **30**, so that the terminal contacts **26** of the signal contact pins **25**B, **25**C, **25**E and **25**F enter the spaces formed between the associated end accommodation grooves **57** of the holding plate **34** and the associated end accommodation grooves **45** of the holding plate **33**, respectively, through the engaging holes **70** as shown in FIG. **5**. Thereupon, the terminal contacts **26** of the ground contact pins **25**A and **25**D enter the bifurcated resilient portions **66** of the ground contacts **65**A and **65**D while resiliently deforming the same bifurcated resilient portions **66** to establish connections therewith, respectively, while the terminal contacts **26** of the signal contact pins **25**B, **25**C, **25**E and **25**F enter the bifurcated resilient portions **66** of the signal contacts **65**B, **65**C, **65**E and **65**F while resiliently deforming the same bifurcated resilient portions **66** to establish connections therewith, respectively.

[0125] Therefore, the ground contact pins **25**A and **25**D of the plug **20** are electrically connected to a ground pattern formed on a circuit board on the receptacle **30** side, and the ground contacts **65**A and **65**D of the receptacle **30** are electrically connected to a ground pattern formed on a circuit board on the plug **20** side. Similarly, the signal contact pins **25**B, **25**C, **25**E and **25**F of the plug **20** are electrically connected to a circuit pattern formed on the circuit board on the receptacle **30** side, and the signal contacts **65**B, **65**C, **65**E and **65**F of the receptacle **30** are electrically connected to a circuit pattern formed on the circuit board on the plug **20** side.

[0126] In the above illustrated first embodiment of the connector, the peripheries of the signal contacts **65**B, **65**C, **65**E and **65**F are totally covered by the insulating portions **43** and **55**; moreover, the peripheries of the insulating portions **43** and **55** are totally covered by the insulation recesses **36** and **37** and the insulation recesses **49** and **50** that are formed on the conductive layer portions **35** and **48**, respectively. Due to this structure, the signal contacts **65**B, **65**C, **65**E and **65**F are securely shielded by the inner surfaces of the insulation recesses **36**, **37**, **49** and **50** (which makes it possible to prevent the signal contacts **65**B, **65**C, **65**E and **65**F from both picking up noise from the outside and leaking noise caused by themselves during signal transmission in an extremely effective manner). Accordingly, the connector **10** which has superior shielding characteristics and makes a high-speed signal transmission possible is achieved.

[0127] Moreover, the surface areas of the conductive layer portions **35** and **48** are large because the conductive layer portions **35** and **48** are formed over the entire surface of the holding plates **33** and **34** and because a surface (inner surface) of the conductive layer portion **35** of the holding plate **33** which faces the other holding plate **34** is provided with recesses (the insulation recesses **36** and **37**) and a surface (inner surface) of the conductive layer portion **48** of the holding plate **34** which faces the other holding plate **33** is also provided with recesses (the insulation recesses **49** and **50**).

[0128] Furthermore, the connector can be easily produced with no decrease in productivity even if the holding plates **33** and **34** (conductive layer portions and insulating portions) that are elements of each contact module **31** include complicated shapes such as the insulation recesses and the contact holding grooves because each holding plate **33** and **34** is a molded member made of synthetic resin.

[0129] Furthermore, since no shielding member made of metal is embedded in each contact module **31**, the number of elements of the connector can be reduced as compared with conventional contacts; moreover, each contact module **31** can be miniaturized in the case where the present embodiment of the connector is provided therein with the same number of contacts as a conventional contact.

[0130] Furthermore, since the contact modules **31** are joined together by the retainer **75** to be made as an integral member instead of using a housing that was an indispensable element of a conventional connector, in this respect also it can be said that the present embodiment of the connector is easy to produce (assemble).

[0131] In addition, since the ground contacts **65**A and **65**D and the signal contacts signal contacts **65**B, **65**C, **65**E and **65**F are held between the end accommodation grooves **40** and **45**, which are recessed in the holding plate **33**, and the end accommodation grooves **52**, the communication grooves **53**, the end accommodation grooves **57** and the communication grooves **58**, which are recessed in the holding plate **34**, the ground contacts **65**A and **65**D and the signal contacts signal contacts **65**B, **65**C, **65**E and **65**F can be firmly held and retained by the holding plates **33** and **34** and easily produced with a high degree of productivity.

[0132] A second embodiment of the connector according to the present invention will be discussed below with reference to FIGS. **27** through **56**. Note that forward, rearward, leftward and rightward directions of the connector (receptacle/plug) in the following descriptions are determined with reference to the double-headed arrows shown in FIGS. **27**, **28**, **30**, etc.

[0133] As shown in FIGS. **27** and **28**, the second embodiment of the connector **100** is for use in differential signaling and includes ground contacts and signal contacts. For instance, the connector **100** is applicable to information and communication apparatuses, broadcast and video apparatuses, control devices for factory automation systems, medical equipment, semi-conductor manufacturing equipment, semi-conductor testers, etc., similar to the above-described first embodiment of the connector **10**. The connector **100** is provided with a plug **120** and a receptacle **130** which are engageable with each other. The plug **120** and the receptacle **130** are electrically connected to each other when connected to each other as shown in FIG. **28**.

[0134] Firstly, the receptacle **130** will be discussed with reference mainly to FIGS. **29** through **49**.

[0135] The receptacle **130** is provided with three contact modules (two contact modules **131** and a contact module **132**), a connecting bar **173** and a retainer **175** as relatively large elements of the receptacle **130**.

[0136] First of all, the structures of the two contact modules **131** will be discussed hereinafter.

[0137] Among the three contact modules **131** and **132**, each of the two contact modules **131** that are positioned on the laterally opposite sides of the contact module **132** is provided with two holding plates (side holding plates) **133** and **134**, a holding plate (center holding plate) **138** positioned between the two holding plates **133** and **134**, four ground contacts **165**A and **165**D and eight signal contacts **165**B, **165**C, **165**E and **165**F.

[0138] As shown in FIGS. **34** through **41**, each of the holding plates **133**, **134** and **138** is made of two resin members integrated into one member.

[0139] A conductive layer portion (conductive layer) **135** serving as a base of the holding plate **133** in each contact

module **131** is made by firstly being molded of an insulating synthetic resin into the shape shown in FIG. **37** with the use of molding dies (not shown) and subsequently being entirely plated so as to constitute a continuous conductive layer. The method of applying such plating can be a so-called resin plating method or a thin-film forming method (evaporation method, spattering, etc.). In the case of the resin plating method, firstly a molded member (molding) serving as a substrate of the conductive layer portion **135** is subjected to firstly a grease removing process to remove grease from the outer surface of the molded member, a cleaning process to cleanse the outer surface of the molded member and thereafter a surface activating process to activate the outer surface of the molded member by catalysis. Thereafter, electroless plating, nickel strike plating, electric copper plating, nickel plating, and finish plating are applied to the molded member, in that order. Alternatively, the conductive layer portion **135** can be molded by a MID (molded interconnect device).

[0140] As shown in the drawings, the conductive layer portion **135** is provided on the left side thereof with two insulation recesses **136** and **137** which are open to both the front end surface and the bottom end surface of the conductive layer portion **135**. The conductive layer portion **135** is further provided, on two ribs formed on the left side of the conductive layer portion **135** which are respectively adjacent to the two insulation recesses **136** and **137**, with two opening recesses **139**, two end accommodation grooves (ground-contact holding grooves) **140** and two communication grooves (ground-contact holding grooves) **141**, respectively. The two opening recesses **139** are elongated rearward from the front end surface of the conductive layer portion **135**, the two end accommodation grooves **140** are communicatively connected to the rear ends of the two opening recesses **139** and are greater in width than the two opening recesses **139**, respectively. The two communication grooves **141** extend from the two end accommodation grooves **140** to the rear ends of the aforementioned two ribs, respectively. Additionally, the conductive layer portion **135** is further provided on the left side thereof with four substantially circular-columnar-shaped engaging recesses **135**A and two circular-columnar-shaped engaging pins **135**B. The conductive layer portion **135** is further provided, at the upper front end and the upper rear end of the conductive layer portion **135**, with a front engaging groove **135**C and a rear engaging groove **135**D, respectively. The conductive layer portion **135** is further provided, on the right side thereof in the vicinity of the bottom front corner of the conductive layer portion **135**, with a key groove **135**E having a rectangular shape as viewed from the right side of the conductive layer portion **135**. As shown in FIGS. **47** and **48**, the depth of each key groove **135**E gradually increases in the direction from the bottom upwards. Namely, the bottom surface of the key groove **135**E (a portion of the right side of the conductive layer portion **135** in the key groove **125**E) is formed as a beveled surface. An upper edge **135**F and a lower edge **135**G of the front half of the right side of the conductive layer portion **135** are chamfered as shown in FIGS. **48** and **49**.

[0141] An insulating portion **143** made of an insulating synthetic resin is fitted into the left side of the conductive layer portion **135**, which is molded in the above described manner as shown in FIGS. **34**, etc. The insulating portion **143** is molded with the use of molding dies (not shown) separately from the conductive layer portion **135**. As shown in FIG. **40**, the insulating portion **143** is provided on the left side thereof with four opening recesses **144**, associated four end accommodation grooves (contact holding grooves) **145**, four communication grooves (contact holding grooves) **142** and two communication grooves (contact holding grooves) **146**. The four opening recesses **144** are identical in shape to the two opening recesses **139**. The four end accommodation grooves **145** are identical in shape to the two end accommodation grooves **140** and communicatively connected to the rear ends of the four opening recesses **144**. The four communication grooves **142** extend from the rear ends of the of the four end accommodation grooves **145** to the bottom end of the insulating portion **143**, respectively. The insulating portion **143** is provided, on surfaces of on the right side thereof which face the associated conductive layer portion **135**, with two engaging recesses **143**A (see FIG. **41**) in which the engaging pins **135**B of the associated conductive layer portion **135** can be engaged, respectively. The insulating portion **143** that has the above described structure becomes integral with the conductive layer portion **135** by fitting a substantially upper half portion of the insulating portion **143** into the two insulation recesses **136** and **137** of the conductive layer portion **135** while fitting the two engaging pins **135**B into the two engaging recesses **143**A, respectively.

[0142] The two holding plates **133** and **134** of each contact module **131** are substantially bilaterally symmetrical in shape; however, the holding plate **134** is partly different in shape from the holding plate **133**.

[0143] A conductive layer portion (conductive layer) **148** of the holding plate **134** is an element corresponding to the conductive layer portion **135** of the holding plate **133** (the material of the conductive layer portion **148** (including the material of plating) is the same as that of the conductive layer portion **135**). The conductive layer portion **148** is molded with the use of molding dies (not shown) in the same manner as the conductive layer portion **135**. The conductive layer portion **148** is provided, on the right side thereof at positions thereon which correspond to the positions of the two insulation recesses **136** and **137**, with two insulation recesses **149** and **150**. The two insulation recesses **149** and **150** and the two insulation recesses **136** and **137** are bilaterally symmetrical to each other (are mirror images to each other), respectively. The conductive layer portion **148** is further provided, on the right side thereof at positions thereon which correspond to the positions of the two opening recesses **139**, the two end accommodation grooves **140** and the two communication grooves **141**, with two opening-forming projecting portions **151**, intermediate recessed portions **152** and two pressure ribs **153**, respectively. One of the two pressure ribs **153** projects from the surface of a rib on the right side of the conductive layer portion **148** between the two insulation recesses **149** and **150**, while the other of the two pressure ribs **153** projects from a portion on the right side of the conductive layer portion **148** directly below the insulation recess **150**. Although none of the accompanying drawings shows the right side of the conductive layer portion **148**, the two insulation recesses **149** and **150**, the two opening-forming projecting portions **151**, the intermediate recessed portions **152** and the two pressure ribs **153**, which are formed on the right side of the conductive layer portion **148**, are identical in shape and size to those formed on the right side of a conductive layer portion (conductive layer) **160** serving as a base of the holding plate **138** in each contact module **131**. Accordingly, FIGS. **36** and **38** can be alternatively referred to with regard to the elements formed on the right side of the conductive layer portion **148**, which show the right side of the conductive layer portion **160**.

[0144] The conductive layer portion **148** is provided with a front engaging groove **148**C and a rear engaging groove **148**D which correspond to the engaging groove **135**C and the rear engaging groove **135**D of the conductive layer portion **135**, respectively. The conductive layer portion **148** is provided, on the right side at positions thereon which correspond to the positions of the four engaging recesses **135**A, with four engaging projections **148**A (see FIGS. **34** and **35**), respectively, and is further provided, on the right side of the conductive layer portion **148** at positions thereon which correspond to the positions of the two engaging pins **135**B, with two engaging pins **148**B having the same shapes as the two engaging pins **135**B, respectively (see FIG. **35**). The conductive layer portion **148** is provided, on the left side thereof in the vicinity of the bottom front corner of the conductive layer portion **148**, with a key groove **148**E which is bilaterally symmetrical shaped with respect to the key groove **135**E. An upper edge **148**F and a lower edge **148**G of the front half of the left side of the conductive layer portion **148** are chamfered as shown in FIGS. **33**, **48** and **49**.

[0145] An insulating portion **155** made of an insulating synthetic resin is fitted into the right side of the conductive layer portion **148**. The insulating portion **155** is molded with the use of molding dies (not shown) separately from the conductive layer portion **148** (the material of the insulating portion **155** and the method of molding thereof are the same as those of the insulating portion **143**).

[0146] The insulating portion **155** is provided on the right side thereof with four opening recesses **156** (see FIGS. **34** and **35**) which correspond to the four opening recesses **144**, respectively, that are formed on the insulating portion **143** of the holding plate **133**. The insulating portion **155** is further provided on the right side thereof with associated four end accommodation grooves (not shown) which correspond to the four end accommodation grooves **145**, respectively. On the other hand, although no communication grooves corresponding to the communication grooves **142** of the insulating portion **143** are formed on the insulating portion **155**, the insulating portion **155** is provided, on portions thereof which face the four communication grooves **142**, with four pressure ribs **154** which are substantially identical in side shape to the four communication grooves **142**, respectively (see FIG. **35**). The insulating portion **155** is further provided on the left side thereof with two engaging recesses **155**A which correspond to the two engaging recesses **143**A of the insulating portion **143**, respectively (see FIG. **35**).

[0147] The shape of the conductive layer portion **160** of the holding plate **138**, which is held between the holding plates **133** and **134**, is shown in FIGS. **36**, **38** and **39**. The material of the conductive layer portion **160** (including the material of plating) is the same as those of the conductive layer portions **135** and **148**. The conductive layer portion **160** is molded with the use of molding dies (not shown) in the same manner as the conductive layer portion **135** and **148**.

[0148] As shown in FIG. **38**, the conductive layer portion **160** is provided on the right side thereof with two insulation recesses **149** and **150**, two opening-forming projecting portions **151**, intermediate recessed portions **152** and two pressure ribs **153**, which are identical in shape and size to those formed on the conductive layer portion **148**. One of the two pressure ribs **153** projects from the surface of a rib on the right side of the conductive layer portion **160** between the two insulation recesses **149** and **150**, while the other of the two pressure ribs **153** projects from a portion on the right side of the conductive layer portion **160** directly below the insulation recess **150** (a portion on the right side of the conductive layer portion **160** in the vicinity of one of four engaging projections **160**A**1** that project from the right side of the conductive layer portion **160**). The conductive layer portion **160** is further provided, at positions on the right side thereon which face the positions of the four engaging recesses **135**A, with four engaging projections **160**A**1** engageable in the four engaging recesses **135**A, respectively, and is further provided, at positions on the right side thereon which face the positions of the two engaging pins **135**B, with two engaging pins **160**B having the same shapes as the two engaging pins **135**B, respectively. As shown in FIG. **39**, the conductive layer portion **160** is provided on the left side thereof with two insulation recesses **136** and **137**, two opening recesses **139**, two end accommodation grooves **140** and two communication grooves **141**. Additionally, the conductive layer portion **160** is provided, at positions on the left side thereof which correspond to the positions of the four engaging projections **160**A**1**, with four engaging recesses **160**A**2**, respectively, and is further provided, at positions on the left side of the conductive layer portion **160** which correspond to the positions of the two engaging pins **143**A, with two engaging pins **160**B, respectively. The conductive layer portion **160** is provided, on the left side thereof at the upper front end of the conductive layer portion **160**, with a front engaging groove **160**C, and is provided, at the upper rear end of the conductive layer portion **160**, with a rear engaging groove **160**D. As shown in FIG. **36**, the conductive layer portion **160** is provided on the bottom surface thereof with a locking lug **160**H.

[0149] After the conductive layer portion **160** is molded, the insulating portions **155** and **143**, which are molded separately from the conductive layer portion **160**, are fitted into the right and left sides of the conductive layer portion **160** to become integral therewith, which completes the holding plate **138**.

[0150] Note that the side edges (upper and lower side edges) of each insulating portion **143** and **155** in each associated insulation recess (**136**, **137**, **149** and **150**) are covered by the associated conductive layer.

[0151] A set of six contacts are held between the insulating portion **143** of the holding plate **133** and the insulating portion **155** of the holding plate **138**, and another set of six contacts are held between the insulating portion **155** of the holding plate **134** and the insulating portion **143** of the holding plate **138**. Each of these two sets of contacts is composed of two ground contacts **165**A and **165**D and four signal contacts **165**B, **165**C, **165**E and **165**F. The two ground contacts **165**A and **165**D and the four signal contacts **165**B, **165**C, **165**E and **165**F are stamp molded out of metal. More specifically, to make each contact **165**A through **165**F, a base material (e.g., phosphor bronze, beryllium copper, titanium copper, stainless steel, or Corson-copper alloy) is coated firstly with a base plating (e.g., nickel (Ni) plating) and subsequently with a finish plating (e.g., gold(Au) plating, tin(Sn)-copper(Cu) plating, or tin(Sn)-lead(Pb) plating). The side shapes of the ground contacts **165**A and **165**D and the signal contacts **165**B, **165**C, **165**E and **165**F are all in the shape of a substantially letter L and mutually different in length. The front ends and the lower ends of all the ground contacts **165**A and **165**D and the signal contacts **165**B, **165**C, **165**E and **165**F are formed as bifurcated resilient (spring) portions **166** and press-fit terminals **167**, respectively.

[0152] One set of six contacts (the ground contacts **165**A and **165**D, and the signal contacts **165**B, **165**C, **165**E and **165**F) (hereinafter referred to as a first set of contacts), another set of six contacts (the ground contacts **165**A and **165**D, and the signal contacts **165**B, **165**C, **165**E and **165**F) (hereinafter referred to as a second set of contacts) and the two of the holding plates **133**, **134** and **138** are combined into one with these two sets of six contacts being held between the two holding plates **133** and **138** and between the two holding plates **134** and **138**, respectively, in the following manner.

[0153] Firstly, the bifurcated resilient portions **166** of the ground contacts **165**A and **165**D of the first set of contacts are accommodated in the two end accommodation grooves **140** of the conductive layer portion **135** of the holding plate **133**, respectively, and middle portions (conductive positions) of the ground contacts **165**A and **165**D of the first set of contacts between the bifurcated resilient portions **166** and the press-fit terminals **167** thereof are respectively held by the two communication grooves **141** of the conductive layer portion **135** of the holding plate **133** and the communication grooves **146** of the insulating portion **143** so that the press-fit terminals **167** of the ground contacts **165**A and **165**D of the first set of contacts project downward from the bottom end of the holding plate **133**. On the other hand, the bifurcated resilient portions **166** of the ground contacts **165**A and **165**D of the second set of contacts are accommodated in the two end accommodation grooves **140** of the conductive layer portion **160** of the holding plate **138**, respectively, and middle portions (conductive positions) of the ground contacts **165**A and **165**D of the second set of contacts between the bifurcated resilient portions **166** and the press-fit terminals **167** thereof are respectively held by the two communication grooves **141** of the conductive layer portion **160** of the holding plate **138** so that the press-fit terminals **167** of the ground contacts **165**A and **165**D of the second set of contacts project downward from the bottom end of the holding plate **138**. At the same time, the bifurcated resilient portions **166** of the signal contacts **165**B, **165**C, **165**E and **165**F of the first set of contacts are accommodated in the four end accommodation grooves **145** of the insulating portion **143** of the holding plate **133**, respectively, and middle portions (conductive positions) of the signal contacts **165**B, **165**C, **165**E and **165**F of the first set of contacts between the bifurcated resilient portions **166** and the press-fit terminals **167** thereof are respectively held by the two communication grooves **142** of the insulating portion **143** of the holding plate **133** so that the press-fit terminals **167** of the signal contacts **165**B, **165**C, **165**E and **165**F of the first set of contacts project downward from the bottom end of the holding plate **133**. On the other hand, the bifurcated resilient portions **166** of the signal contacts **165**B, **165**C, **165**E and **165**F of the second set of contacts are accommodated in the four end accommodation grooves **145** of the insulating portion **143** of the holding plate **138**, respectively, and middle portions (conductive positions) of the signal contacts **165**B, **165**C, **165**E and **165**F of the second set of contacts between the bifurcated resilient portions **166** and the press-fit terminals **167** thereof are respectively held by the two communication grooves **142** of the insulating portion **143** of the holding plate **138** so that the press-fit terminals **167** of the signal contacts **165**B, **165**C, **165**E and **165**F of the second set of contacts project downward from the bottom end of the holding plate **138**.

[0154] Furthermore, the right side of the holding plate **138** (which includes the conductive layer portion **160** and the insulating portion **155**) is combined with the left side of the holding plate **133** (which includes the conductive layer portion **135** and the insulating portion **143**) to which the ground contacts **165**A and **165**D and the signal contacts **165**B, **165**C, **165**E and **165**F have been installed, and the right side of the holding plate **134** (which includes the conductive layer portion **148** and the insulating portion **155**) is combined with the left side of the holding plate **138** (which includes the conductive layer portion **160** and the insulating portion **143**). At this time, the four engaging projections **160**A**1** of the conductive layer portion **160** are fitted into the four engaging recesses **135**A of the conductive layer portion **135**, respectively, and the four engaging projections **148**A of the conductive layer portion **148** are fitted into the four engaging recesses **160**A**2** of the conductive layer portion **160**, respectively. Thereupon, the right side of the insulating portion **155** of the holding plate **134** comes into intimate contact with the left side of the insulating portion **143** of the holding plate **138**, the right side of the insulating portion **155** of the holding plate **138** comes into intimate contact with the left side of the insulating portion **143** of the holding plate **133**, the right side of the conductive layer portion **148** comes into intimate contact with the left side of the conductive layer portion **160**, and the right side of the conductive layer portion **160** comes into intimate contact with the left side of the conductive layer portion **135**. Additionally, the four opening recesses **144** of each insulating portion **143** and the four opening recesses **156** of the associated insulating portion **155**, which face each other, form four engaging holes **169** at the front ends of the insulating portions **143** and **155** (see FIGS. **29** and **33**). Likewise, the two opening recesses **139** of the conductive layer portion **135** and the two opening-forming projecting portions **151** of the conductive layer portion **160** (with the two opening-forming projecting portions **151** blocking the left-side openings of the two opening recesses **139**) form two engaging holes **170** at the front end of the contact module **131** (specifically at the front ends of the conductive layer portions **135** and **160**), and the two opening recesses **139** of the conductive layer portion **160** and the two opening-forming projecting portions **151** of the conductive layer portion **148** form two engaging holes **170** at the front end of the contact module **131** (specifically at the front ends of the conductive layer portions **148** and **160**) (see FIGS. **29** and **33**). Additionally, as shown in FIG. **44**, the bifurcated resilient portions **166** of the signal contacts **165**B, **165**C, **165**E and **165**F of the first set of contacts are respectively accommodated in the spaces formed between the four end accommodation grooves **145** on the insulating portion **143** of the holding plate **133** and the aforementioned four end accommodation grooves (not shown) on the insulating portion **155** of the holding plate **138**, respectively. Likewise, the bifurcated resilient portions **166** of the signal contacts **165**B, **165**C, **165**E and **165**F of the second set of contacts are respectively accommodated in the spaces formed between the four end accommodation grooves **145** on the insulating portion **143** of the holding plate **138** and the aforementioned four end accommodation grooves (not shown) on the insulating portion **155** of the holding plate **134**, respectively. Additionally, the upper pressure rib **153** (narrower in width than the grand contact **165**D) on the right side of the conductive layer portion **160** of each contact module **131** is in press contact with the left side of the ground contact **165**D of the first set of contacts while the right side of this ground contact **165**D is in press contact with the bottom surface (left side) of the associated communication recess (contact holding recess) **141** of the

conductive layer portion **135**. Likewise, the lower pressure rib **153** on the right side of the conductive layer portion **160** of each contact module **131** is in press contact with the left side of the ground contact **165**A of the first set of contacts while the right side of the same ground contact **165**A is in press contact with the bottom surface of the associated communication recess **141** of the conductive layer portion **135**. Similarly, the upper pressure rib **153** on the right side of the conductive layer portion **148** of each contact module **131** is in press contact with the left side of the ground contact **165**D of the second set of contacts while the right side of the same ground contact **165**D is in press contact with the bottom surface of the associated communication recess (contact holding recess) **141** of the conductive layer portion **160**. Likewise, the lower pressure rib **153** on the right side of the conductive layer portion **148** of each contact module **131** is in press contact with the left side of the ground contact **165**A of the second set of contacts while the right side of the same ground contact **165**A is in press contact with the bottom surface of the associated communication recess **141** of the conductive layer portion **160**. Accordingly, electrical continuity is securely established between the ground contacts **165**A and **165**D of the first set of contacts and the conductive layer portions **135** and **160** while electrical continuity is securely established between the ground contacts **165**A and **165**D of the second set of contacts and the conductive layer portions **148** and **160**, respectively. Moreover, the signal contacts **165**B, **165**C, **165**E and **165**F of the first set of contacts are held between the bottom surfaces (left sides) of the communication grooves (contact holding grooves) **142** of the insulating portion **143** of the holding plate **133** and the four pressure ribs **154** on the right side of the insulating portion **155** of the holding plate **138**, respectively, to be in contact with both the bottom surfaces (left sides) of the same communication grooves (contact holding grooves) **142** and the same four pressure ribs **154**, and the signal contacts **165**B, **165**C, **165**E and **165**F of the second set of contacts are held between the bottom surfaces (left sides) of the communication grooves (contact holding grooves) **142** of the insulating portion **143** of the holding plate **138** and the four pressure ribs **154** on the right side of the insulating portion **155** of the holding plate **134**, respectively, to be in contact with both the bottom surfaces (left sides) of the same communication grooves (contact holding grooves) **142** and the same four pressure ribs **154**.

[0155] Hence, each of the two contact modules **131** (the right contact module **131** and the left contact module **131**) are assembled in the above described manner.

[0156] The structures of the contact module **132**, which is held between the two contact modules **131**, will be discussed hereinafter.

[0157] The contact module **132** is assembled by joining the left side of the holding plate **133** (which includes the conductive layer portion **135** and the insulating portion **143**) and the right side of the holding plate **134** (which includes the conductive layer portion **148** and the insulating portion **155**) to each other with a set of six contacts (the two grand contacts **165**A and **165**D and the four signal contacts **165**B, **165**C, **165**E and **165**F) being held between the holding plates **133** and **134**. Upon the contact module **132** being assembled in this manner, the four engaging holes **169** and the two engaging holes **170** are formed at the front end of the contact module **132** (see FIGS. **29** and **33**).

[0158] The manner of assembling the contact module **132** is similar to the manner of assembling each contact module **131**. Namely, in the first place, the bifurcated resilient portions **166** of the ground contacts **165**A and **165**D are accommodated in the two end accommodation grooves **140** of the conductive layer portion **135** of the holding plate **133**, respectively, and middle portions (conductive positions) of the ground contacts **165**A and **165**D between the bifurcated resilient portions **166** and the press-fit terminals **167** thereof are respectively held by the two communication grooves **141** of the conductive layer portion **135** of the holding plate **133** and the communication grooves **146** of the insulating portion **143** so that the press-fit terminals **167** of the ground contacts **165**A and **165**D project downward from the bottom end of the conductive layer portion **135** of the holding plate **133**. Additionally, the bifurcated resilient portions **166** of the signal contacts **165**B, **165**C, **165**E and **165**F are accommodated in the four end accommodation grooves **145** of the insulating portion **143** of the holding plate **133**, respectively, and middle portions (conductive positions) of the signal contacts **165**B, **165**C, **165**E and **165**F between the bifurcated resilient portions **166** and the press-fit terminals **167** thereof are respectively held by the two communication grooves **142** of the insulating portion **143** of the holding plate **133** so that the press-fit terminals **167** of the signal contacts **165**B, **165**C, **165**E and **165**F project downward from the bottom end of the conductive layer portion **135** of the holding plate **133**. Furthermore, the right side of the holding plate **134** (which includes the conductive layer portion **148** and the insulating portion **155**) is combined with the left side of the holding plate **133** (which includes the conductive layer portion **135** and the insulating portion **143**) to which the ground contacts **165**A and **165**D and the signal contacts **165**B, **165**C, **165**E and **165**F have been installed, and the four engaging projections **148**A of the conductive layer portion **148** are fitted into the four engaging recesses **135**A of the conductive layer portion **135**, respectively. Thereupon, the upper pressure rib **153** on the right side of the conductive layer portion **148** of the contact module **132** is in press contact with the left side of the ground contact **165**D while the right side of the same ground contact **165**D is in press contact with the bottom surface of the associated communication recess (contact holding recess) **141** of the conductive layer portion **135**. Likewise, the lower pressure rib **153** on the right side of the conductive layer portion **148** of the contact module **132** is in press contact with the left side of the ground contact **165**A while the right side of the same ground contact **165**A is in press contact with the bottom surface of the associated communication recess **141** of the conductive layer portion **135**. Moreover, the signal contacts **165**B, **165**C, **165**E and **165**F are held between the bottom surfaces (left sides) of the communication grooves (contact holding grooves) **142** of the insulating portion **143** of the holding plate **133** and the four pressure ribs **154** on the right side of the insulating portion **155** of the holding plate **134**, respectively.

[0159] Two contact modules **131** and one contact module **132**, each of which is assembled in the above described manner, are arranged in layers in the left-right direction as shown in FIGS. **29** and **30** to constitute a contact module group **172**. The connecting bar **173** and the retainer **175** are the elements which prevent the two contact modules **131** and the contact module **132** from separating from each other.

[0160] The connecting bar **173** is an element with a substantially L-shaped cross section which is substantially iden-

tical in length (in the left-right direction) to the contact module group **172**, and is provided with an insertion jutting portion **174**A and a contacting portion **174**B.

[0161] The retainer **175** is an element having a substantially U-shaped cross section. The retainer **175** is provided with a vertical side **176**, an upper side **177** and a lower side **178**. The upper side **177** and the lower side **178** extend rearward from the upper and lower ends of the vertical side **176**, respectively.

[0162] The vertical side **176** is provided with five columns of through holes **179** arranged in the left-right direction, wherein each column includes six through holes **179**. Namely, a total of thirty through holes **179** are formed in the vertical side **176**.

[0163] The lower side **178** is provided, in a central part on the top surface thereof, with a pair of guide keys (right and left guide keys) **180** which extend in the forward-rearward direction. The lower side **178** is provided, on the top surface thereof at the right and left ends thereof with a pair of guide keys **182** which extend in the forward-rearward direction. As shown in FIG. **30**, the lower side **178** is provided at the front ends of the pair of guide keys **180** with two engaging keys **183** which project upward. As shown in FIGS. **47** and **48**, each of the two engaging keys **183** increases in width (dimensions in the left-right direction) in the direction from down to up and also increases in width in the direction from rear to front. In other words, the right and left sides of each engaging key **183** are formed as tapered surfaces. The lower side **178** is provided at the front ends of the pair of guide keys **180** with two engaging keys **184** which project upward. The inner surfaces of the engaging keys **184** are formed as beveled surfaces which approach each other in the direction from rear to front and approach each other in the bottom thereof in upward direction (toward the right on the left engaging key **184** and toward the left on the right engaging key **184**). In addition, the lower side **178** is provided on the top surface thereof with a pair of lock holes (right and left lock holes) **185** in which the locking lugs **160**H of the conductive layer portions **160** of the two contact modules **131** engage upon the retainer **175** being attached to the contact module group **172**, which is composed of the two contact modules **131** and the contact module **132**.

[0164] The upper side **177** is provided at the rear end thereof with a pair of engaging projections (right and left engaging projections) **186**. The upper side **177** is provided, at the rear end thereof between the pair of engaging projections **186**, with an engaging projection **187** which is greater in width than each engaging projection **186**. As shown in FIG. **48**, the upper side **177** is provided in a central part on the lower surface thereof with a pair of guide keys **188** which extend from the front end to the rear end of the lower surface of the upper side **177**, and is further provided at the right and left ends of the lower surface of the upper side **177** with a pair of guide keys (right and left guide keys) **189** which extend from the front end to the rear end of the lower surface of the upper side **177**.

[0165] The manner of combining the contact module group **172**, the connecting bar **173** and the retainer **175** into one will be discussed hereinafter.

[0166] Firstly, the manner of combining the contact module group **172** and the retainer **175** will be discussed hereinafter.

[0167] In this case, firstly the retainer **175** is brought to approach the contact module group **172** as shown in FIG. **29** and **30**. Subsequently, as shown in FIG. **49**, the pair of guide keys **180** of the lower side **178** are brought to be engaged in two grooves each having a substantially V-shaped cross section, respectively, wherein one of the two grooves (left groove) is formed between a lower-left chamfered edge **148**G of the conductive layer portion **148** of the contact module **132** and a lower-right chamfered edge **135**G of the conductive layer portion **135** of the left contact module **131**, and the other groove (right groove) is formed between a lower-right chamfered edge **135**G of the conductive layer portion **135** of the contact module **132** and a lower-left chamfered edge **148**G of the conductive layer portion **148** of the right contact module **131**. At the same time, the right and left guide keys **182** of the lower side **178** are brought to be engaged with a lower-left chamfered edge **148**G of the conductive layer portion **148** of the left contact module **131** and a lower-right chamfered edge **135**G of the conductive layer portion **135** of the right contact module **131**, respectively. In addition, as shown in FIG. **49**, the pair of guide keys **188** of the upper side **177** are brought to be engaged in two grooves each having a substantially V-shaped cross section, respectively, wherein one of the two grooves (left groove) is formed between an upper-left chamfered edge **148**F of the conductive layer portion **148** of the contact module **132** and an upper-right chamfered edge **135**F of the conductive layer portion **135** of the left contact module **131**, and further wherein the other groove (right groove) is formed between an upper-right chamfered edge **135**F of the conductive layer portion **135** of the contact module **132** and an upper-left chamfered edge **148**F of the conductive layer portion **148** of the right contact module **131**. At the same time, the right and left guide keys **189** of the upper side **177** are brought to be engaged with an upper-left chamfered edge **148**F of the conductive layer portion **148** of the left contact module **131** and an upper-right chamfered edge **135**F of the conductive layer portion **135** of the right contact module **131**, respectively. Thereafter, the retainer **175** is slidingly moved rearward on the contact module group **172** along the guide keys **180**, **182**, **188** and **189**. Upon the retainer **175** being fully moved rearward relative to the contact module group **189**, the rear surface (inner surface) of the vertical side **176** comes in contact with the front surface of the contact module group **172**, and thereupon, the upper side **177** covers a front half of the top surface of the contact module group **172** while the lower side **178** covers a front half of the bottom surface of the contact module group **172**. Moreover, the left engaging projection **186** engages in both the front engaging groove **148**C and the front engaging groove **160**C of the left contact module **131**, the right engaging projection **186** engages in the front engaging groove **135**C of the right contact module **131**, the engaging projection **187** engages a laterally-elongated groove which is formed on top of the contact module group **172** by the front engaging groove **135**C of the left contact module **131**, the front engaging groove **148**C and the front engaging groove **135**C of the contact module **132**, and the front engaging groove **148**C and the front engaging groove **160**C of the right contact module **131**. Furthermore, as shown in FIG. **48**, the pair of engaging keys **183** of the lower side **178** are engaged in a groove formed between the key groove **148**E of the contact module **132** and the key groove **135**E of the left contact module **131** and a groove formed between the key groove **135**E of the contact module **132** and the key groove **148**E of the right contact module **131**, respectively. Furthermore, as shown in FIG. **48**, the pair of engaging keys **184** are engaged in the key groove **148**E of the left contact module **131** and the key groove **135**E of the right contact module **131**, respectively. Accordingly, each contact module **131** and **132** is held between the adjacent engaging keys **183** and **184**.

Furthermore, the locking lugs **160**H of the conductive layer portions **160** of the two contact modules **131** engage in the pair of lock holes **185** of the lower side **178**, respectively (this state of engagement between the locking lugs **160**H and the pair of lock holes **185** is not shown in the drawings).

[0168] The contact module group **172** and the retainer **175** are combined into one integral module in the above described manner.

[0169] Next the manner of combining the contact module group **172** and the connecting bar **173** will be discussed hereinafter.

[0170] Upon completion of the contact module group **172**, the rear engaging groove **135**D of each conductive layer portion **135**, the rear engaging groove **148**D of each conductive layer portion **148**D and the rear engaging groove **160**D of each conductive layer portion **160** are aligned in the left-right direction to form a laterally-elongated engaging groove (see FIGS. **30**, etc.). The connecting bar **173** is fixed to the contact module **172** to be integral therewith by fitting the insertion jutting portion **174**A into this laterally-elongated engaging groove while making the front surface of the contacting portion **174**B contact with the rear end surface of the top end of the contact module group **172** (see FIG. **44**).

[0171] After the completion of the receptacle **130** by combining the contact module group **172**, the connecting bar **173** and the retainer **175** into one integral module in the above described manner, the press-fit terminals **167** of the ground contacts **165**A and **165**D and the signal contacts **165**B, **165**C, **165**E and **165**F, which project downward from a bottom surface of the receptacle **130**, are driven (press-fitted) into through holes (not shown) formed in a circuit board CB**1**, respectively (see FIGS. **27** and **28**). Thereupon, the press-fit terminals **167** of the ground contacts **165**A and **165**D are electrically connected to a ground pattern on the circuit board CB**1** while the press-fit terminals **167** of the signal contacts **165**B, **165**C, **165**E and **165**F are electrically connected to a circuit pattern on the circuit board CB**1**.

[0172] Next, the plug **120** will be discussed with reference mainly to FIGS. **50** through **56**.

[0173] The plug **120** is provided with two contact modules **121**, a contact module **122**, a connecting bar **173** and a retainer **110** as relatively large elements of the plug **120**.

[0174] Each contact module **121** is identical in structure to each contact module **131** except that each contact module **121** is provided with four ground contact pins **125**A and **125**D and eight signal contact pins **125**B, **125**C, **125**E and **125**F, whereas each contact module **131** is provided with the four ground contacts **165**A and **165**D and the eight signal contacts **165**B, **165**C, **165**E and **165**F.

[0175] As shown in FIGS. **51**, etc., the ground contact pins **125**A and **125**D and the signal contact pins **125**B, **125**C, **125**E and **125**F of each contact module **121** are each provided with a terminal contact **126** and a press-fit terminal **127** and greater in length in the forward-rearward direction than the ground contacts **165**A and **165**D and the signal contacts **165**B, **165**C, **165**E and **165**F, respectively. The terminal contacts **126** of the ground contact pins **125**A and **125**D and the signal contact pins **125**B, **125**C, **125**E and **125**F of each contact module **121** are connected with the bifurcated resilient portions **166** of the ground contacts **165**A and **165**D and the signal contacts **165**B, **165**C, **165**E and **165**F of the associated contact module **131**, respectively, when the plug **120** and the receptacle **130** are connected to each other. The ground contact pins **125**A and **125**D and the signal contact pins **125**B, **125**C, **125**E and **125**F are stamp molded out of metal. More specifically, to make each contact **125**A through **125**F, a base material (e.g., phosphor bronze, beryllium copper, titanium copper, stainless steel, or Corson-copper alloy) is coated firstly with base plating (e.g., nickel (Ni) plating) and subsequently with finish plating (e.g., gold(Au) plating, tin(Sn)-copper(Cu) plating, or tin(Sn)-lead(Pb) plating).

[0176] The manner of assembling each contact module **121** is the same as the manner of assembling each contact module **131**.

[0177] The contact module **122** is identical in structure to the contact module **132** except that the contact module **122** is provided with four ground contact pins **125**A and **125**D and eight signal contact pins **125**B, **125**C, **125**E and **125**F, whereas the contact module **132** is provided with four ground contacts **165**A and **165**D and eight signal contacts **165**B, **165**C, **165**E and **165**F.

[0178] The contact module **122** is assembled in the same manner as the contact module **132**.

[0179] The retainer **110** is an element having a substantially H-shaped cross section. The retainer **110** is provided with a vertical side **111**, an upper side **112** and a lower side **113**. The upper side **112** extends both forward and rearward from the upper end of the vertical side **111**. Likewise, the lower side **113** extends both forward and rearward from the lower end of the vertical side **111**. The upper side **112** is provided with a contact-module retaining portion **112**A and a receptacle retaining portion **112**B which extend forward and rearward, respectively. Likewise, the lower side **113** is provided with a contact-module retaining portion **113**A and a receptacle retaining portion **113**B which extend forward and rearward, respectively.

[0180] The vertical side **111** is provided with five columns of through holes **114** arranged in the left-right direction, wherein each column includes six through holes **114**. Namely, a total of thirty through holes **114** are formed in the vertical side **111**. The contact-module retaining portion **113**A is provided with a pair of guide keys **180**, a pair of guide keys **182**, two engaging keys **183**, two engaging keys **184** and a pair of lock holes **185** which are all formed in the same manner as those of the retainer **175** (see FIG. **50**).

[0181] The plug **120** that has the above described structure is completed by mounting the retainer **110** and the connecting bar **173** to the contact module group **116** in the same manner as the receptacle **131** after the completion of the contact module group **116** by combining the two contact module **121** and the contact module **122** into one. Upon the vertical side **111** being mounted to the contact module group **116**, the terminal contacts **126** of the ground contact pins **125**A and **125**D and the signal contact pins **125**B, **125**C, **125**E and **125**F project rearward from the vertical side **111** through the corresponding through holes **114** of the vertical side **111**, respectively, as shown in FIG. **56**.

[0182] Upon the press-fit terminals **127** of the ground contact pins **125**A and **125**D being driven (press-fitted) into through holes (not shown) formed in a circuit board CB**2** (see FIGS. **27** and **28**), the press-fit terminals **127** of the ground contact pins **125**A and **125**D are electrically connected to a ground pattern on the circuit board CB**2** while the press-fit terminals **127** of the signal contact pins **125**B, **125**C, **125**E and **125**F are electrically connected to a circuit pattern on the circuit board CB**2**.

[0183] When the receptacle **130** and the plug **120** that have the above described structures are connected to each other so

that the receptacle retaining portion **112**B of the retainer **110** covers the upper surface of the upper side **177** of the retainer **175** and so that the receptacle retaining portion **113**B of the retainer **110** covers the bottom surface of the lower side **178** of the retainer **175** as shown in FIG. **28**, the terminal contacts **126** of the ground contact pins **125**A and **125**D and the signal contact pins **125**B, **125**C, **125**E and **125**F of each contact module **121** firstly pass through the corresponding through holes **179** and subsequently engage in the corresponding engaging holes **169** and **170**, respectively, thus entering inside of the receptacle **130** (specifically, entering the inside of the associated contact module **131** or **132**). Thereupon, each terminal contact **126** enters the bifurcated resilient portion **166** of the associated ground or signal contact **165**A, **165**B, **165**C, **165**D, **165**E or **165**F while resiliently deforming the same bifurcated resilient portion **166** to establish connection therewith, respectively.

[0184] Therefore, the ground contact pins **125**A and **125**D of the plug **120** are electrically connected to a ground pattern formed on the circuit board CB**1** on the receptacle **130** side and the ground contacts **165**A and **165**D of the receptacle **130** are electrically connected to a ground pattern formed on the circuit board CB**2** on the plug **120** side, while the signal contact pins **125**B, **125**C, **125**E and **125**F of the plug **120** are electrically connected to a circuit pattern formed on the circuit board CB**1** on the receptacle **130** side and the signal contacts **165**B, **165**C, **165**E and **165**F of the receptacle **130** are electrically connected to a circuit pattern formed on the circuit board CB**2** on the plug **120** side.

[0185] The above illustrated second embodiment of the connector **100** can obtain effects similar to those obtained in the first embodiment of the connector **10** because the basic structure of the second embodiment of the connector **100** is the same as the basic structure of the first embodiment of the connector **10**.

[0186] In addition, since two sets of contacts **165**A through **165**F are sandwiched between three holding plates (**133**, **134** and **138**) while two sets of contact pins **125**A through **125**F are sandwiched between three holding plates (**133**, **134** and **138**) in each of the contact modules **121** and **131** of the second embodiment of the connector **100**, each of the contact modules **121** and **131** of the second embodiment of the connector **100** have the following advantages with respect to each contact module **31** of the first embodiment of the connector **10**, in which a set of contacts (**65**A through **65**F) are sandwiched between two holding plates (**33** and **34**).

[0187] First of all, for instance, a total of four holding plates are required to sandwich two sets of contacts in the first embodiment of the connector, whereas a total of three holding plates can do the same in the second embodiment of the connector. Namely, according to the second embodiment of the connector, since the number of components, the number of assembly procedures, and the time required for the plating process performed on each component can be reduced, it is possible to achieve an improvement in productivity and a reduction in production cost.

[0188] Furthermore, since each of the contact modules **121** and **131** is composed of the two holding plates **133** and **134** and the holding plate **138** that is mechanically stronger and greater in thickness than either of the two holding plates **133** and **134**, the mechanical strength of each contact module and the contact module group itself in the second embodiment of the connector can be made higher than that in the first embodiment of the contact module **31**.

[0189] Moreover, more than one plug connector **120** or more than one receptacle **130** can be arranged in the left-right direction with all the contacts (**125**A through **125**F and **165**A through **165**F) being positioned at regular intervals in the left-right direction because neither of the retainers **110** and **175** has side walls (either a left side wall or a right side wall) and because, among the three holding plates **133**, **134** and **138** of the two contact modules **121** of the plug **120** that respectively include the left side portion and the right side portion of the plug **120**, the two conductive layer portions **135** and **148** of each contact module **121** that respectively include the left side portion and the right side portion of each contact module **121** are each designed to be smaller in wall thickness than a half the wall thickness of the conductive layer portion **160**, and further because, among the three holding plates **133**, **134** and **138** of the two contact modules **131** of the receptacle **130** that respectively include the left side portion and the right side portion of the receptacle **130**, the two conductive layer portions **135** and **148** of each contact module **131** that respectively comprise the left side portion and the right side portion of each contact module **131** are each designed to be smaller in wall thickness than a half the wall thickness of the conductive layer portion **160**.

[0190] Furthermore, each contact pin (**125**A through **125**F) of the plug **120** can be easily held at a predetermined position (i.e., all the contact pins **125**A through **125**F of the plug **120** can be placed in proper alignment) since the through holes **114** are formed in the vertical plate portion **111** of the retainer **110**. Likewise, since the through holes **179** are formed in the vertical side **176** of the retainer **175**, each contact pin (**165**A through **165**F) of the receptacle **130** can be easily lead into the associated contact module **131** or **132** of the receptacle **130** (i.e., the ground contact pins **165**A and **165**D and the signal contact pins **165**B, **165**C, **15**E and **165**F of the receptacle **130** can be easily made contact with the ground contacts **125**A and **125**D and the signal contacts **125**B, **125**C, **125**E and **125**F of the plug **120**, respectively).

[0191] Although the present invention has been described based on the above illustrated first and second embodiments of the connectors, the present invention is not limited solely to these embodiments; making various modifications to these embodiments is possible.

[0192] For instance, although each contact module **31** includes the two holding plates (a pair of holding plates) **33** and **34** in the first embodiment of the connector and each of the contact modules **121** and **131** includes the three holding plates **133**, **134** and **138** in the second embodiment of the connector, it is possible that each contact module include more than three holding plates so that contacts or contact pins are held between adjacent holding plates. FIGS. **57** and **58** show an example of this modified embodiment of the receptacle. A contact module group **191** of this modified embodiment of a receptacle **190** is composed of six holding plates (four holding plates **138**, a left holding plate **133** and a right holding plate **134**) and five sets of contacts **165**A through **165**F, and each set of contacts **165**A through **165**F is held between the adjacent holding plates.

[0193] Additionally, all the contacts (or contact pins) of each of the receptacle **30**, the plug **120** and the receptacle **130** can consist of only signal contacts (or signal contact pins) as shown in FIGS. **59** and **60** though the contacts of each of the receptacle **30**, the plug **120** and the receptacle **130** consist of two types of contacts (the ground contacts **65**A and **65** and the signal contacts **65**B, **65**C, **65**E and **65**F, or the ground contact

pins **125**A and **125**D and the signal contact pins **125**B, **125**C, **125**E and **125**F, or the ground contacts **165**A and **165**D and the signal contacts **165**B, **165**C, **165**E and **165**F).

[0194] FIG. **59** shows a modified embodiment of each contact module **31** of the receptacle **30** of the first embodiment of the connector, wherein each contact module **31** is modified for use in single-ended signaling. In this modified embodiment, the conductive layer portions **35** and **48** are provided on the laterally-opposed surfaces thereof with a total of six insulation recesses **68** and corresponding six insulation recesses **68**, respectively. In addition, the conductive layer portion **35** is provided in the six insulation recesses **68** thereof with six insulating portions **43** which are fitted into the six insulation recesses **68** so as to occupy the six insulation recesses **68**, respectively, and the conductive layer portion **48** is provided in the six insulation recesses **68** thereof with six insulating portions **55** which are fitted into the six insulation recesses **68** so as to occupy the six insulation recesses **68**, respectively. A signal contact **65** is held between each insulating portion **43** and the associated insulating portion **55**.

[0195] FIG. **60** shows another modified embodiment of each contact module **31** of the receptacle **30** of the first embodiment of the connector, wherein each contact module **31** is modified for use in differential signaling. In this modified embodiment, the conductive layer portions **35** and **48** are provided on the laterally-opposed surfaces thereof with a total of three insulation recesses **71** and corresponding three insulation recesses **71**, respectively. In addition, the conductive layer portion **35** is provided in the three insulation recesses **71** thereof with three insulating portions **43** which are fitted into the three insulation recesses **71** so as to occupy the three insulation recesses **71**, respectively, and the conductive layer portion **48** is provided in the three insulation recesses **71** thereof with three insulating portions **55** which are fitted into the three insulation recesses **71** so as to occupy the three insulation recesses **71**, respectively. Two signal contacts **65** are held between each insulating portion **43** and the associated insulating portion **55**.

[0196] Although not shown in the drawings, the number of contacts or contact pins held between the conductive layer portion and the conductive layer portion of the adjacent holding plates **33** and **34** can be any number so long as the number is at least one. In addition, it is possible that contact holding grooves and corresponding contact holding grooves be formed on two conductive layer portions which face each other, respectively. Additionally, it is also possible that contact holding grooves and no contact holding grooves be formed on two conductive layer portions which face each other, respectively.

[0197] In addition, in the first embodiment of the connector, it is possible to combine all the ten contact modules **31** into one integral module by a retainer similar to the retainer **175** of the second embodiment of the connector instead of combining all the ten contact modules **31** into one integral by the retainer **75**.

[0198] In addition, although the side edges (upper and lower side edges in the illustrated first embodiment of the connector) of each insulation recess (**36**, **37**, **49** and **50**) in either of the two holding plates **33** and **34**, which extend parallel to the associated signal contact **65**B, **65**C, **65**E or **65**F, are covered by the associated conductive layer portion **35** or **48** and also the side edges (upper and lower side edges in the illustrated second embodiment of the connector) of each insulation recess (**136**, **137**, **149** and **150**) in each of the three holding plates **133**, **134** and **138**, which extend parallel to the associated signal contact **165**B, **165**C, **165**E or **165**F, are covered by the associated conductive layer portion **135**, **148** or **160**, the side edges of each insulation recess (**36**, **37**, **49** and **50**) in either of the two holding plates **33** and **34** can be shaped so as only to be partly covered by the associated conductive layer portion **35** or **48**, and also the side edges of each insulation recess (**136**, **137**, **149** and **150**) in each of the three holding plates **133**, **134** and **138** can be shaped so as only to be partly covered by the associated conductive layer portion **135**, **148** or **160**. FIG. **61** shows an example of this modified embodiment (one of the two holding plates of a modified embodiment of each contact module of the receptacle in the first embodiment of the connector). In this embodiment, the conductive layer portion **35** of the holding plate **33** is provided on the inner surface thereof with two insulation recesses **77** and **37** which correspond to the two insulation recesses **36** and **37** of the holding plate **33** shown in FIGS. **12** and **13**, respectively, and the insulation recess **77** (the upper portion thereof) is not partly covered by the conductive layer portion **35**.

[0199] In addition, in the first embodiment of the connector, it is possible that the holding plate **33** be made by forming the conductive layer portion **35** on a synthetic-resin-made member, subsequently making the insulating portion **43** as a member separated from the conductive layer portion **35** (as a member independent of the conductive layer portion **35**), and subsequently fitting the insulating portion **43** into the conductive layer portion **35**, and that the holding plate **34** be made by forming the conductive layer portion **48** on a synthetic-resin-made member, subsequently making the insulating portion **55** as a member separated from the conductive layer portion **48** (as a member independent of the conductive layer portion **48**), and subsequently fitting the insulating portion **55** into the conductive layer portion **48**. Additionally, in the second embodiment of the connector, it is possible that each conductive layer portion (**135**, **148** and **160**) be formed on a synthetic-resin-made member, and then the associated insulating portion (**143** or **155**) be molded integrally with this conductive layer portion with the use of molding dies (by so-called two-color forming).

[0200] In addition, it is possible that firstly the conductive layer portion (**35**, **48**, **135**, **148** or **160**) be formed over the surface of a synthetic-resin-made member, subsequently a portion of this conductive layer portion (plating) on which the insulating portion (**43**, **55**, **143** or **155**) is to be formed be removed, and subsequently the insulating portion (**43**, **55**, **143** or **155**) be formed on this removed portion.

[0201] Obvious changes may be made in the specific embodiments of the present invention described herein, such modifications being within the spirit and scope of the invention claimed. It is indicated that all matter contained herein is illustrative and does not limit the scope of the present invention.

What is claimed is:

1. A receptacle comprising a plurality of contact modules, each of which includes a plurality of contacts, one of common ends of said contacts being connected to a corresponding plurality of contact pins of a plug, respectively, when said receptacle and said plug are connected to each other, and the other of said common ends of said contacts being connected to a circuit board,

wherein each of said plurality of contact modules includes a plurality of holding plates arranged in a direction of thickness of said each contact module,

wherein at least one conductive layer and at least one insulating portion are formed on each of opposed surfaces of adjacent holding plates of said plurality of holding plates, and

wherein at least one of said plurality of contacts is held between said insulating portions that are formed on said opposed surfaces of said adjacent holding plates, respectively.

2. The receptacle according to claim **1**, wherein said opposed surfaces of said adjacent holding plates comprise first opening recesses and second opening recesses, respectively, said first opening recesses and second opening recesses being open at common end surfaces of said adjacent holding plates, respectively,

wherein engaging holes, through which an outside and an inside of said each contact module are communicatively connected to each other, is formed by said first opening recesses and said second opening recesses upon said adjacent holding plates being joined to each other, and

wherein electrical continuity is established between said contacts of said each contact module and said contact pins of said plug upon said contact pins of said plug being inserted into said each contact module through said engaging holes, respectively.

3. The receptacle according to claim **1**, wherein at least one of said adjacent holding plates comprises a plurality of contact holding grooves formed on said insulating portion, said contacts being engaged in said contact holding grooves to be held thereby, respectively.

4. The receptacle according to claim **1**, wherein some of said contacts are held between said insulating portions formed on said adjacent holding plates, and

wherein the remainder of said plurality of contacts are held between said conductive layers formed on said adjacent holding plates.

5. The receptacle according to claim **1**, wherein a plurality of said insulating portions are formed on each of said opposed surfaces of said adjacent holding plates with said conductive layer on said each of said opposed surfaces of said adjacent holding plates being provided on opposite sides of each of said plurality of insulating portions; and

wherein only one of said contacts is held between each of said insulating portions that are formed on said opposed surfaces of said adjacent holding plates, respectively.

6. The receptacle according to claim **1**, wherein each of said plurality of contact modules comprises two adjacent holding plates of said plurality of holding plates.

7. The receptacle according to claim **1**, wherein each of said plurality of contact modules comprises at least three holding plates of said plurality of holding plates.

8. The receptacle according to claim **1**, wherein said conductive layer is formed entirely over each of said opposed surfaces of said adjacent holding plates of said plurality of holding plates, and

wherein said insulating portion is formed partly on said conductive layer.

9. The receptacle according to claim **8**, wherein said conductive layer covers a pair of side edges of each of said insulating portions positioned on both sides of said plurality of contacts.

10. The receptacle according to claim **1**, wherein a continuous conductive layer is formed on all surfaces of said adjacent holding plates other than said opposed surfaces of said adjacent holding plates.

11. The receptacle according to claim **1**, wherein each of said plurality of holding plates comprises:

a conductive layer portion including a resin-made substrate on which said conductive layer is plated, and at least one insulation recess formed on a surface which faces the other of said adjacent holding plates; and

said insulating portion made of a resin material and is provided in said insulation recesses so as to occupy said insulation recesses.

12. The receptacle according to claim **1**, further comprising a retainer which is attached to a contact module group formed by said plurality of contact modules arranged in layers to combine said plurality of contact modules into one integral module.

13. A plug including a plurality of contact modules each of which includes a plurality of contact pins, one of common ends of said contact pins being inserted into a receptacle to be connected to a corresponding plurality of contacts included in said receptacle, respectively, when said plug and said receptacle are connected to each other, and the other of said commons ends of said plurality of contact pins being connected to a circuit board,

wherein each of said contact modules includes a plurality of holding plates arranged in a direction of thickness of said each contact module,

wherein at least one conductive layer and at least one insulating portion are formed on each of opposed surfaces of adjacent holding plates of said holding plates, and

wherein at least one of said contact pins is held between said insulating portions that are formed on said opposed surfaces of said adjacent holding plates, respectively.

14. The plug according to claim **13**, wherein said opposed surfaces of said adjacent holding plates comprise first opening recesses and second opening recesses, respectively, said first opening recesses and said second opening recesses being open at common end surfaces of said adjacent holding plates, respectively,

wherein engaging holes through which outside and inside of said each contact module are communicatively connected to each other are formed by said first opening recesses and said second opening recesses upon said adjacent holding plates being joined to each other, and

wherein said contact pins project to the outside of said each contact module through said engaging holes.

15. The plug according to claim **13**, wherein each of said plurality of contact modules comprises two adjacent holding plates of said plurality of holding plates.

16. The plug according to claim **13**, wherein each of said plurality of contact modules comprises at least three holding plates of said plurality of holding plates.

17. The plug according to claim **13**, wherein said conductive layer is formed entirely over each of said opposed surfaces of said adjacent holding plates of said plurality of holding plates, and

wherein said insulating portion is formed partly on said conductive layer.

18. The plug according to claim **17**, wherein said conductive layer covers a pair of side edges of each of said insulating portions positioned on both sides of said plurality of contacts.

19. The plug according to claim **13**, wherein a continuous conductive layer is formed on all surfaces of said adjacent holding plates other than said opposed surfaces of said adjacent holding plates.

20. The plug according to claim **13**, wherein each of said plurality of holding plates comprises:

a conductive layer portion including a resin-made substrate on which said conductive layer is plated, and at least one insulation recess formed on a surface which faces the other of said adjacent holding plates; and

said insulating portion made of a resin material and is provided in said insulation recesses so as to occupy said insulation recesses.

21. The plug according to claim **13**, further comprising a retainer which is attached to a contact module group formed by said plurality of contact modules arranged in layers to combine said plurality of contact modules into one integral module.

22. A method of making a receptacle with a plurality of contact modules, each of which includes a plurality of contacts, one of common ends of said contacts being connected to a corresponding plurality of contact pins of a plug, respectively, when said receptacle and said plug are connected to each other, and the other of said common ends of said contacts being connected to a circuit board, said method comprising:

forming a plurality of conductive layer portions which each include a resin-made substrate which has been plated;

forming a plurality of holding plates by putting a resin-made insulating portion on each of said conductive layer portions so as to occupy a part of a surface thereof;

forming said contact modules by arranging said holding plates in a direction of thickness of said each contact module and by joining opposed surfaces of adjacent holding plates thereof, on which said insulating resin-made insulating portion is placed, to each other so that at least one of said contacts is held between said insulating portions that are formed on said opposed surfaces of said adjacent holding plates; and

connecting said contact modules into one integral module.

23. The method of making a receptacle according to claim **22**, wherein said connecting of said contact modules into one integral module comprises:

arranging said plurality of contact modules in layers to form a contact module group; and

attaching a retainer to said contact module group.

24. A method of making a plug with a plurality of contact modules each of which includes a plurality of contact pins, one of common ends of said contact pins being inserted into a receptacle to be connected to a corresponding plurality of contacts included in said receptacle, respectively, when said plug and said receptacle are connected to each other, and the other of said common ends of said plurality of contact pins being connected to a circuit board, said method comprising:

forming a plurality of conductive layer portions which each include a resin-made substrate which has been plated, respectively;

forming a plurality of holding plates by putting a resin-made insulating portion on each of said conductive layer portions so as to occupy a part of a surface thereof;

forming said contact modules by arranging said holding plates in a direction of thickness of said each contact module and by joining opposed surfaces of adjacent holding plates thereof, on which said insulating resin-made insulating portion is placed, to each other so that at least one of said contact pins is held between said insulating portions that are formed on said opposed surfaces of said adjacent holding plates; and

connecting said contact modules into one integral module.

25. The method of making a plug according to claim **24**, wherein said connecting of said contact modules into one integral module comprises:

arranging said plurality of contact modules in layers to form a contact module group; and

attaching a retainer to said contact module group.

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